

SELEK_N17P Schematic

CoffeLake-H

2019/04/03

REV : SD

DY : None Installed
UMA: UMA only installed
OPS: DISCRTE OPTIMUS installed

Selek CFLH N17P



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
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Title

Cover Page

Size
A4

Document Number

SELEK_N17P

Rev
SD

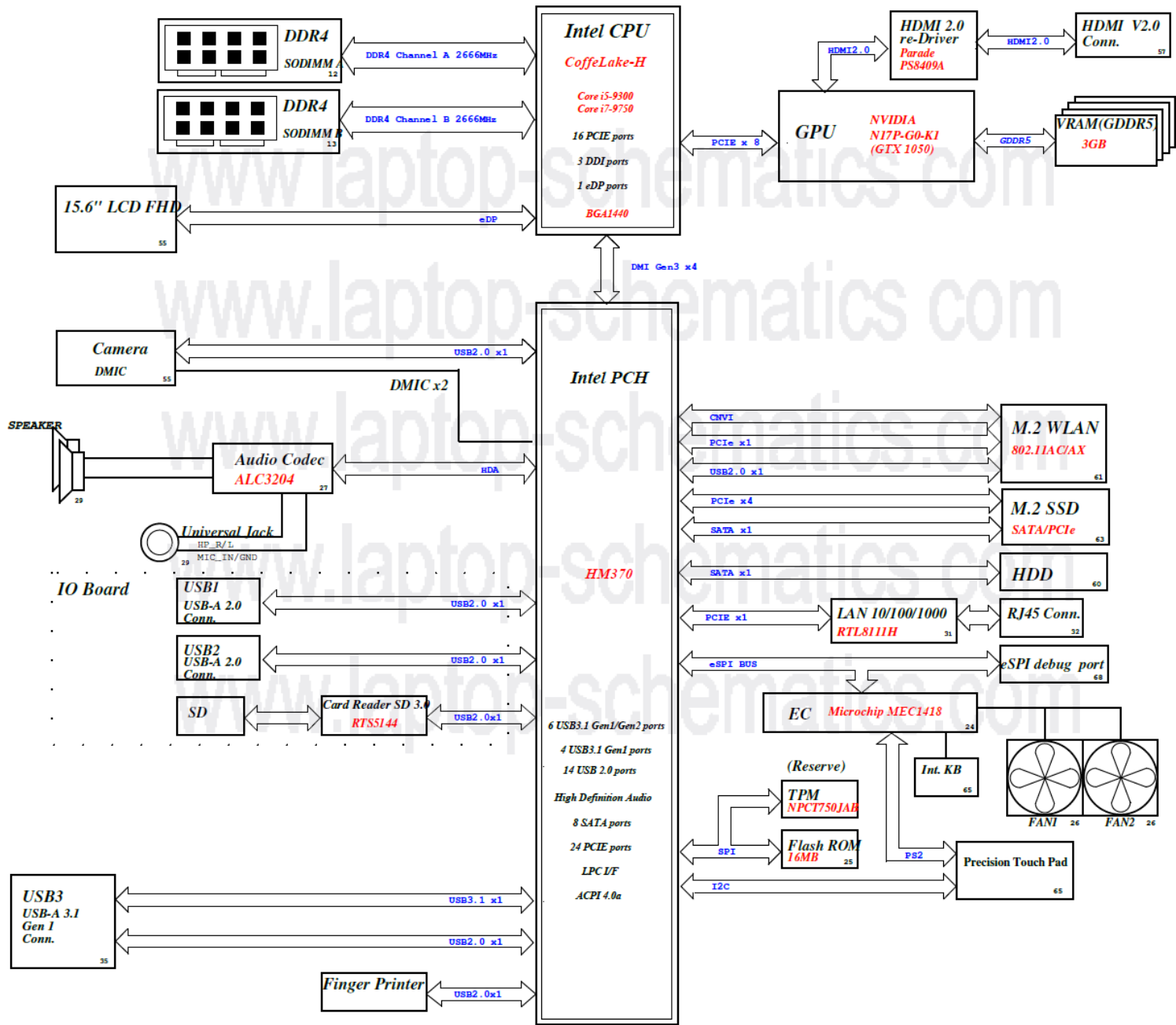
Date: Wednesday, April 03, 2019

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Project Code : 448.0H701.000SD
PCB P/N : 18839-SD
Revision -SD

SELEK N17P

Block Diagram



CHARGER		ISL88739	44
INPUTS		OUTPUTS	
AD+		DCBATOUT	
BT+			
SYSTEM DC/DC		TP651225RUKR-GP	45
INPUTS		OUTPUTS	
		3D3V_PWR	
		3D3V_SS	
DCBATOUT		5V_PWR	
		5V_SS	
CPU Core Power			
NCP81208MNTXG		46-50	
NCP81382MNTXG x 2			
NCP81382MNTXG (23e)			
NCP81253MNTBG			
INPUTS		OUTPUTS	
DCBATOUT		VCC_CORE	
DCBATOUT		+VCCGT	
DCBATOUT		+VCCGT (23e)	
DCBATOUT+VCCSA			
DDR4 SUS			
RT8231AGCW-GP			51
APL5930KAI-TRG			
INPUTS		OUTPUTS	
DCBATOUT		1D2V_S3	
3D3V_SS		0D6V_S0	
		2D5V_S3	
CPU VCCPRIM_CORE			
1V		11	
INPUTS		OUTPUTS	
1D0V_S5		+VCCPRIM_CORE	
CPU DCDC-V1D00A			
AO22262QI-10-GP-U		53	
INPUTS		OUTPUTS	
DCBATOUT		1D0V_S5	
LDO-V1D8V			
APL5930KAI-TRG		54	
INPUTS		OUTPUTS	
3D3V_S5		1D8V_S5	
5V/3V_S0			
TPS22966DPUR-GP		40	
INPUTS		OUTPUTS	
5V_S5		5V_S0	
3D3V_S5		3D3V_S0	
EOP10/EDRAM (23e)			
TPS22961DNTT		40	
INPUTS		OUTPUTS	
1D0V_S5		+V_VCCPRIM_VR	
1D0V_S5		+V_VCCPRIM_VR	
3D3V_VGA			
AO3419L		86	
INPUTS		OUTPUTS	
3D3V_S0		3D3V_VGA_S0	
VGA_CORE			
ISL62771HRTZ-GP-U		85	
INPUTS		OUTPUTS	
DCBATOUT		VGA_CORE	
1D5V_VGA_S0			
Y8288RAC-GP		86	
INPUTS		OUTPUTS	
DCBATOUT		1D5V_VGA_S0	

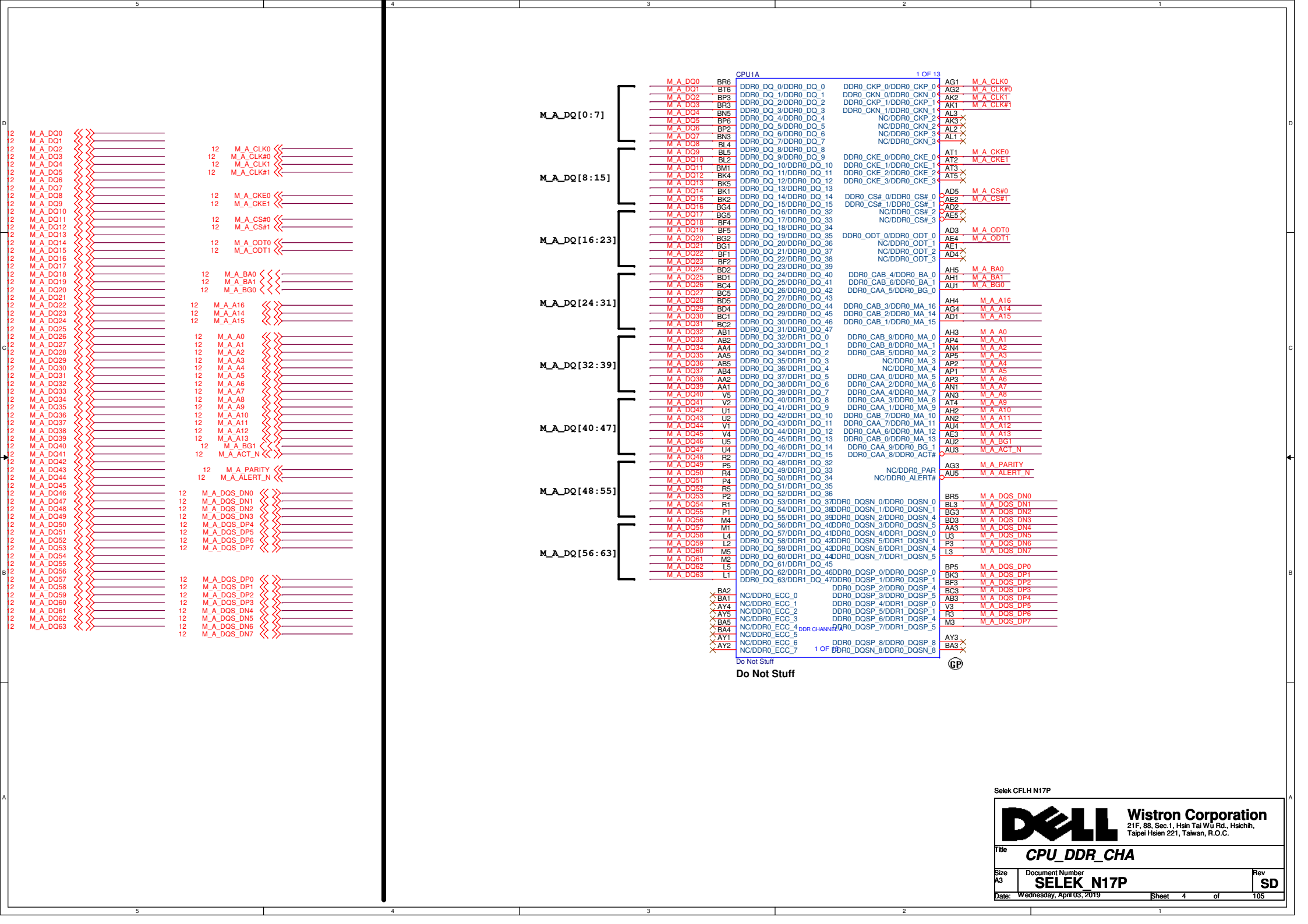


Do Not Stuff

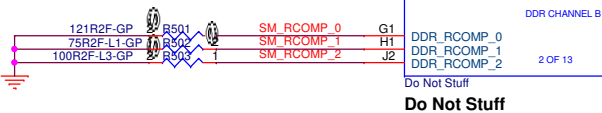
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SSID = CPU



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AROUND_CPU

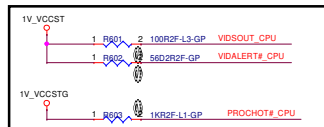
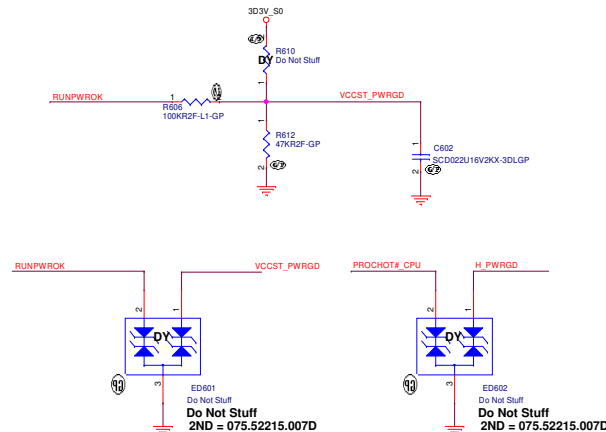


Table 13-14. SVID Bus Routing Guidelines

Signal	W1 [inches]	W2 [inches]	W3/4/5 [inches]	W2+W3+W4+W5 [inches]	W51 [inches]	W52 [inches]	R _{PULL} [Ω]	R _{IN} [Ω]	R _L [Ω]	R _S [Ω]	V _{CC} [V]
VIDSOUT							100	100	0	10	
VIDSCK	0.5-3	1-15	0.5-4	3-17	<0.1	<0.1	Empty	45	0	50	1.0
VIDALERT#							56	Empty	220	0	

Note: For additional information regarding SVID and power management refer to "Power Architecture Guide".



GPD11 pull high by Intel PDG1.3 request

PEG Static Lane Reversal	
CFG2	1: Normal Operation; Lane # definition matches socket pin map definition 0: Lane Reversed

eDP Enable	
CFG4	1: Disable 0: Enable

PEG Training	
CFG7	1: (default) PEG Train immediately following RESET# de assertion 0 = PEG Wait for BIOS for training.

Physical_Debug_Enabled (DFX privacy)	
CFG4	1: Disable 0: Enable (Set DFX enables bit in debug)

PCIe Port Bifurcation Straps	
CFG[6:5]	11: x16 - Device 1 functions 1 and 2 disabled 10: x8, x8 - Device 1 function 1 enabled, function 2 disabled 01: Reserved - (Device 1 function 1 disabled, function 2 enabled) 00: x8, x4, x4 - Device 1 functions 1 and 2 enabled



Processor Internal Pull-Up / Pull-Down Terminations

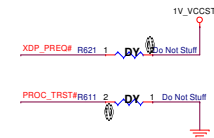
Processor Internal Pull-Up / Pull-Down Terminations

Signal Name	Pull Up/Pull Down	Rail	Value
BPM[3:0]	Pull Up	VCC _{IO}	16-60 Ω
PREQ#	Pull Up	VCC _{ST}	3 kΩ
PROC_TDI	Pull Up	VCC _{STG} ¹	3 kΩ
PROC_TMS	Pull Up	VCC _{STG} ¹	3 kΩ
CFG[19:0]	Pull Up	VCC _{IO}	3 kΩ

Note:
1. For SKL-S it should be VCC_{ST}

Table 6-8. Reset and Miscellaneous Signals

Signal Name	Description	Dir.	Buffer Type	Link Type	Availability
CFG[19:0]	<p>Configuration Signals: The CFG signals have a default value of '1' if not terminated on the board. Refer to the appropriate platform design guide for pull-down recommendations when a logic low is desired.</p> <p>Intel recommends placing test points on the board for CFG pins.</p> <ul style="list-style-type: none"> CFG[0]: Shall reset sequence after PCU PLL lock until de-asserted. <ul style="list-style-type: none"> 1 = (Default) Normal Operation; No stall. 0 = Stall. CFG[1]: Reserved configuration lane. CFG[2]: PCI Express* Static x16 Lane Numbering Reversal. <ul style="list-style-type: none"> 1 = Normal operation 0 = Lane numbers reversed. CFG[3]: Reserved configuration lane. CFG[4]: eDP enable. <ul style="list-style-type: none"> 1 = Disabled. 0 = Enabled. CFG[6:5]: PCI Express* Bifurcation <ul style="list-style-type: none"> 00 = 1 x8, 2 x4 PCI Express* 01 = reserved 10 = 2 x8 PCI Express* 11 = 1 x16 PCI Express* CFG[7]: PEG Training. <ul style="list-style-type: none"> 1 = (default) PEG Train immediately following RESET# de assertion. 0 = PEG Wait for BIOS for training. CFG[19:8]: Reserved configuration lanes. 	I/O	GTL	SE	All processor lines. CFG[2], CFG[6:5] and CFG[7] are relevant for H and S-processor line only and test point may be placed on the board for them.

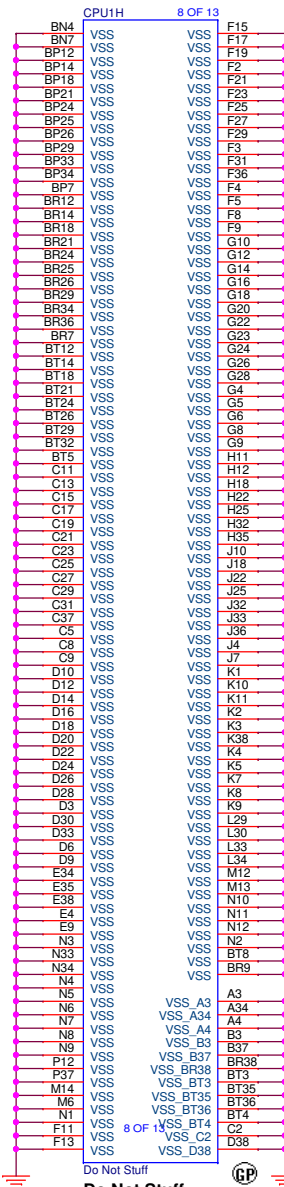
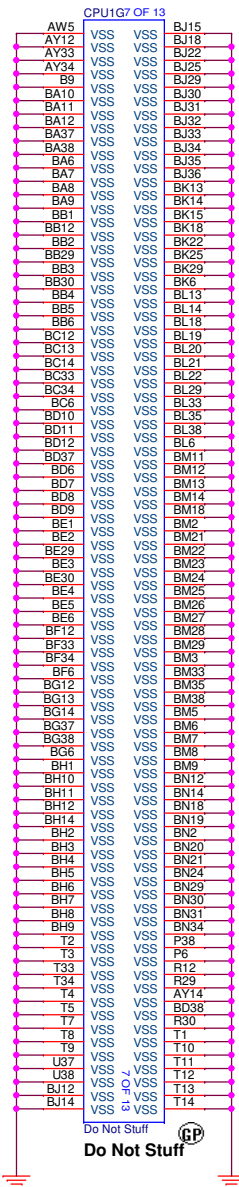
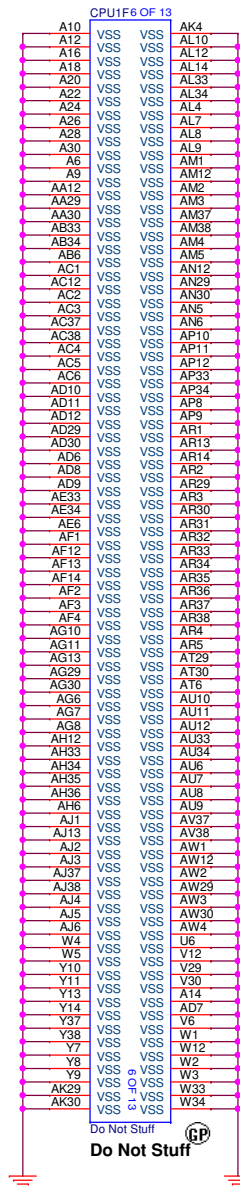


Selek CPLH N17P


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Title **CPU_CFG_CFG STRAP**

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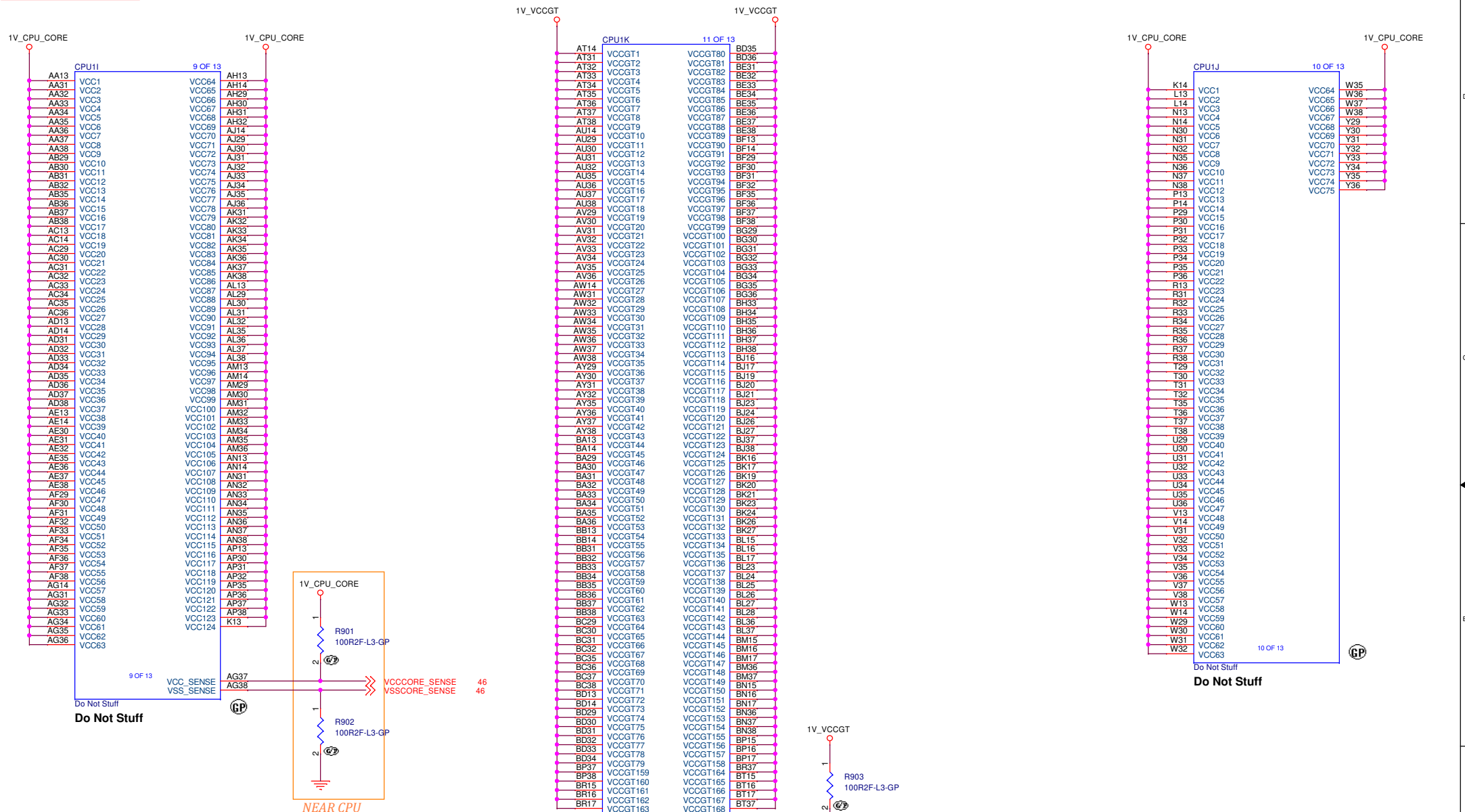
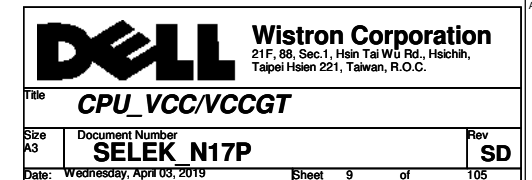


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S

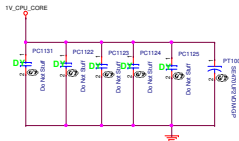
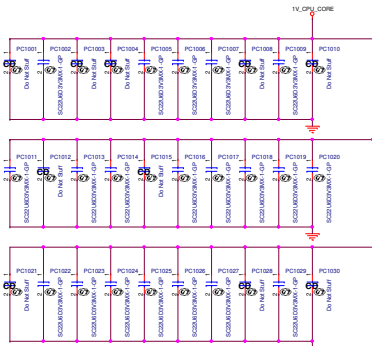
SSID = CPU

**Selek CFLH N17P**

VCCORE

CFL-H_45W

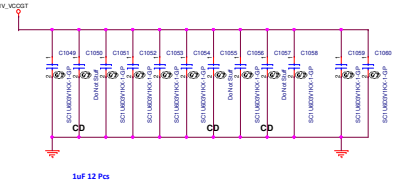
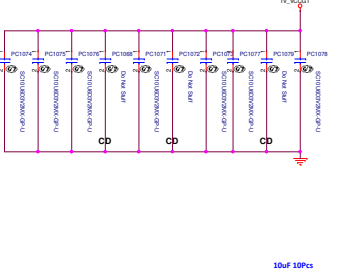
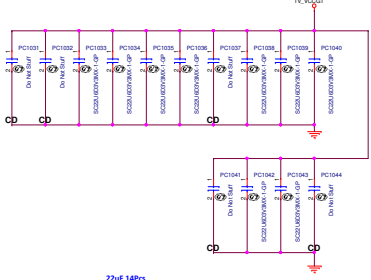
10-line 45W
Ic0Max current=10ma max = 128A



VCCGT

CFL-H_45W

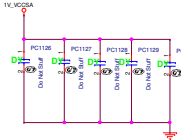
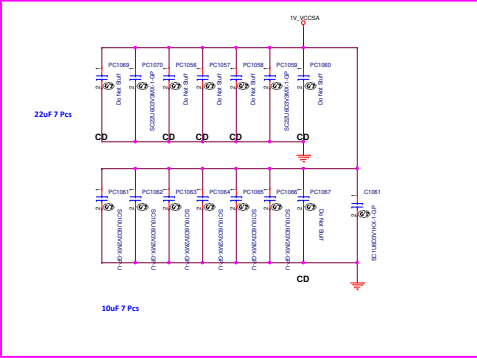
Ic0Max current=10ma max(A) = 32 A



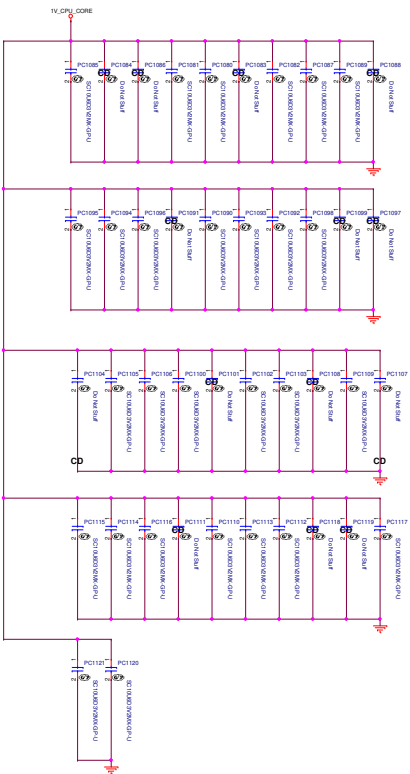
VCCSA

H-Line

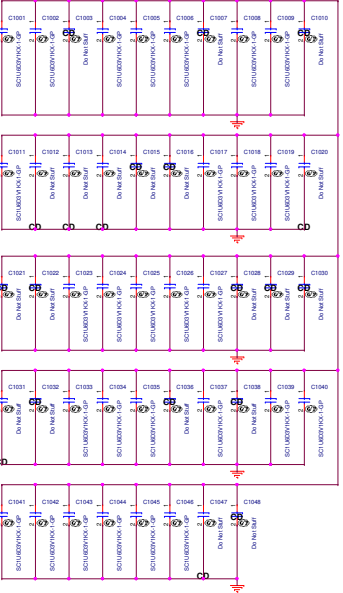
Ic0Max current=10ma max(A) = 11.1 A



10uF 42Pcs



1uF 48 Pcs



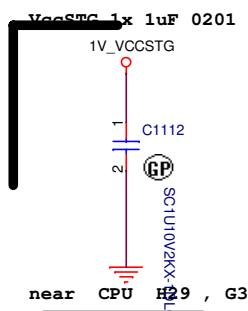
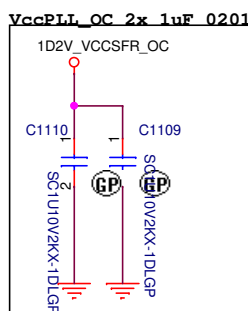
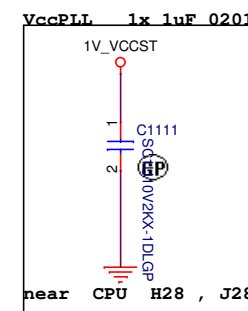
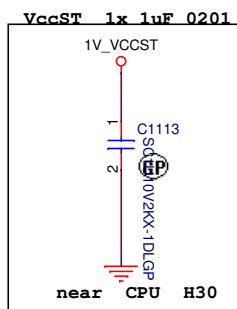
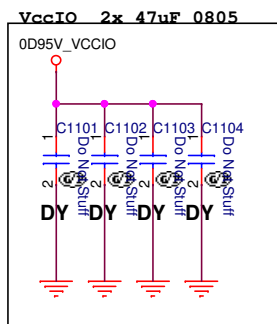
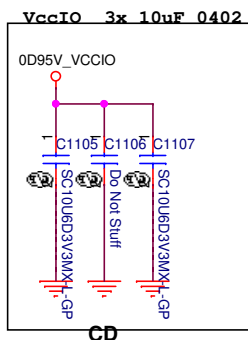
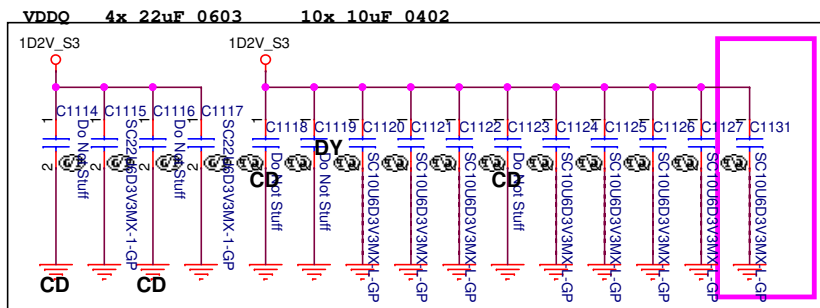


Table 50-5. Decoupling Requirements for CFL H 8+2 Processor (Sheet 1 of 2)

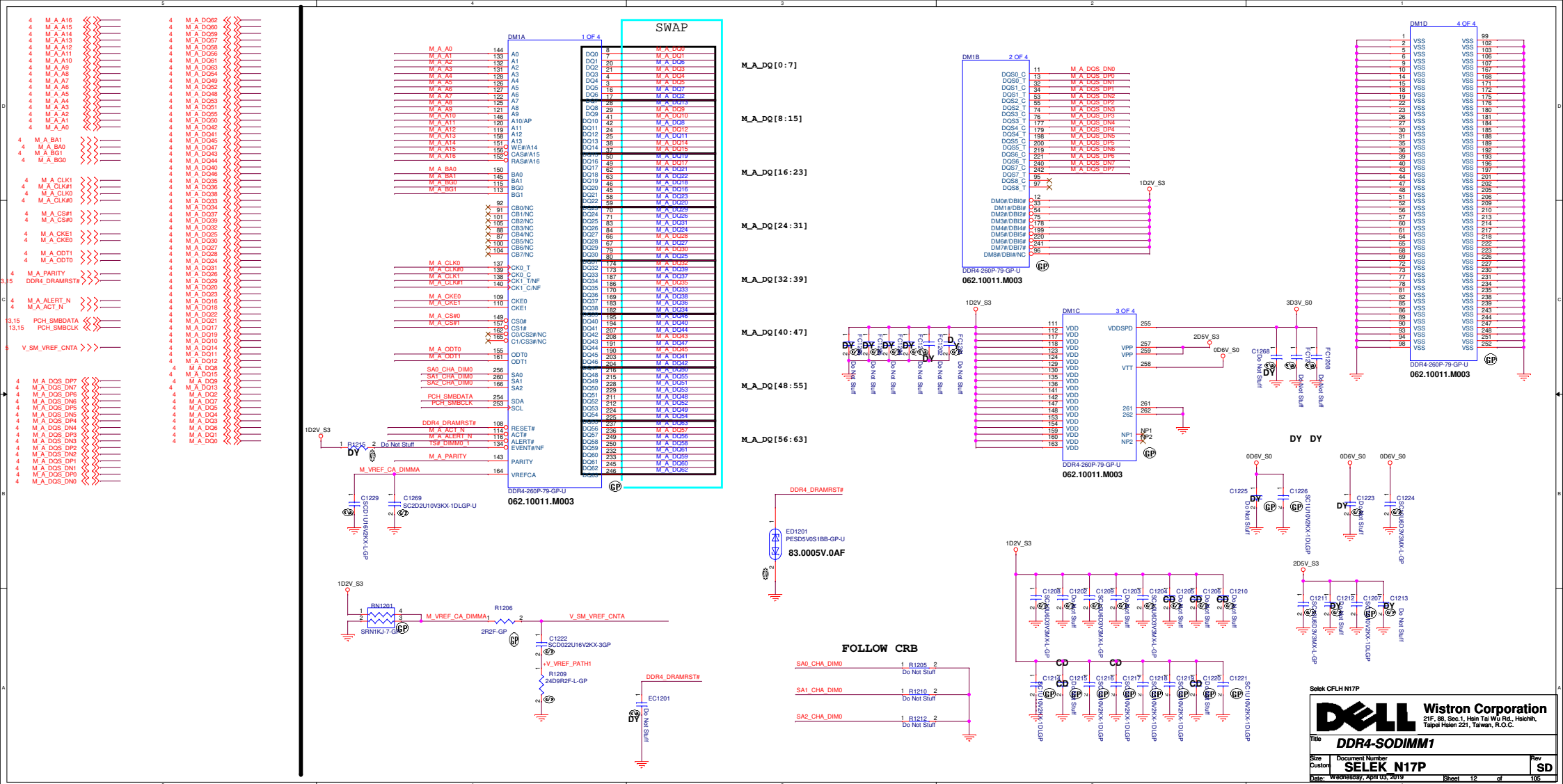
Domain	Board Edge cap	Backside cap	Notes
Vcc	2x 22uF 0603		
	8x 47uF 0805		
		48x 1uF 0201	
		42x 10uF 0402	
		10x 22uF 0603	
VccGT	3x 47uF 0805		Place as close to the BGA as possible
	7x 22uF 0603		
		10x 10uF 0402	
		12x 1uF 0201	
VccSA	2x 47uF 0805		
	2x 22uF 0603		
		7x 10uF 0402	
VDDQ		1x 1uF 0201	
		4x 22uF 0603	
		11x 10uF 0402	
VccIO		3x 10uF 0402	
VccST		1x 1uF 0201	Additional capacitors might be needed if the connectivity from BGAs to capacitors is not adequate.
VccSTG		1x 1uF 0201	Must be Ground referenced. Share with 1.0V PCH rail.
VccPLL		1x 1uF 0201	Must be Ground referenced. Share with 1.0V PCH rail. Board resistance from BGA to Power gate should be less than 130mOhm.
		1x 22uF/47uF 0805 (placeholder)	*Placeholder not stuffed. To be placed as close as possible to BGA (H28, J28) and be placed either at board edge or backside.
Domain	Board Edge cap	Backside cap	Notes
VccPLL_OC		2x 1uF 0201	Must be Ground referenced. Share with VDDQ. Board resistance from BGA to Power gate should be less than 86mOhm.

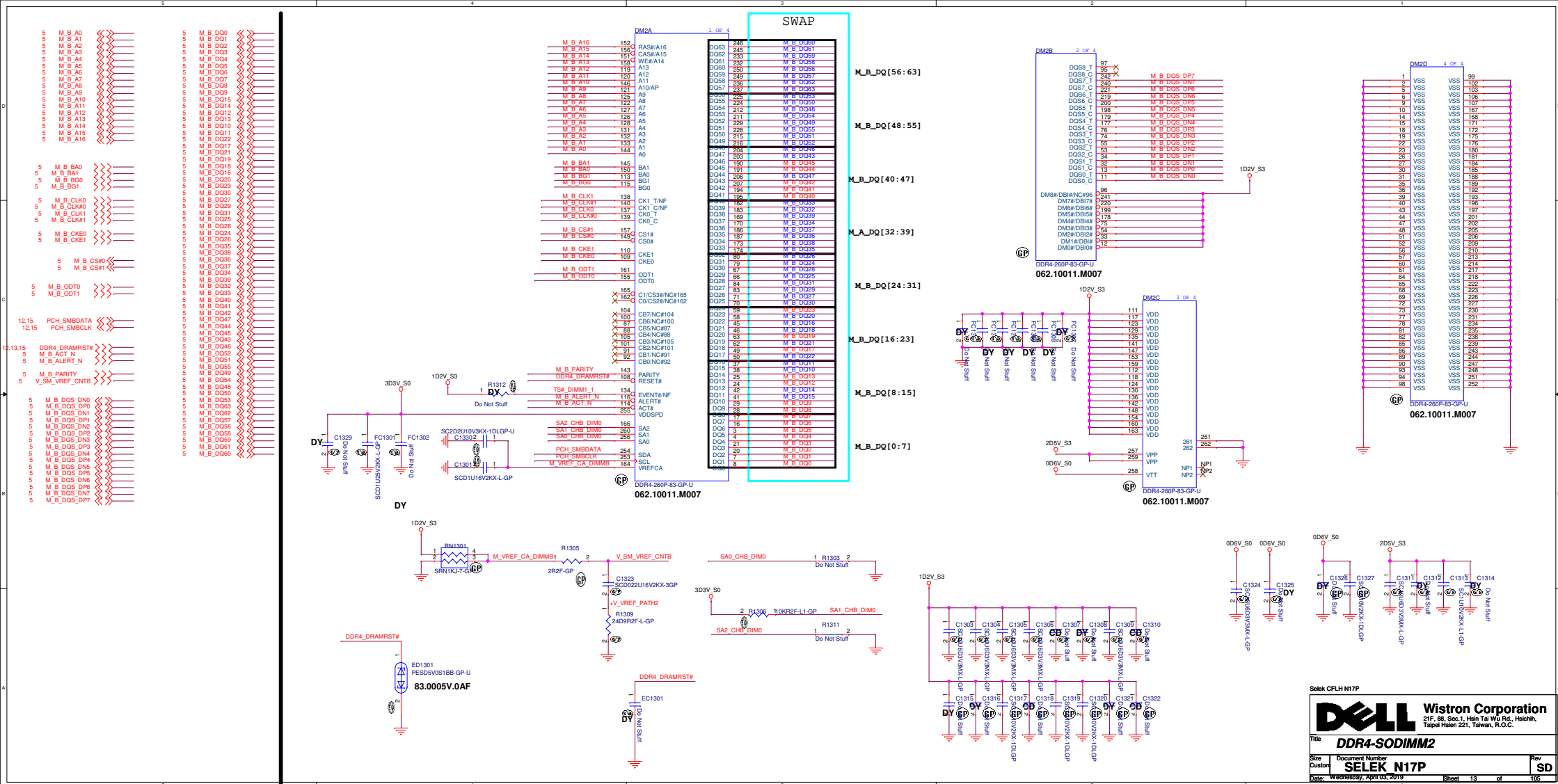
Note: High Current Rail assuming 600KHz for VR bandwidth. Higher VR bandwidth assumptions results in lower quantity of MLCC (0805/0603) to meet the same AC loadline.

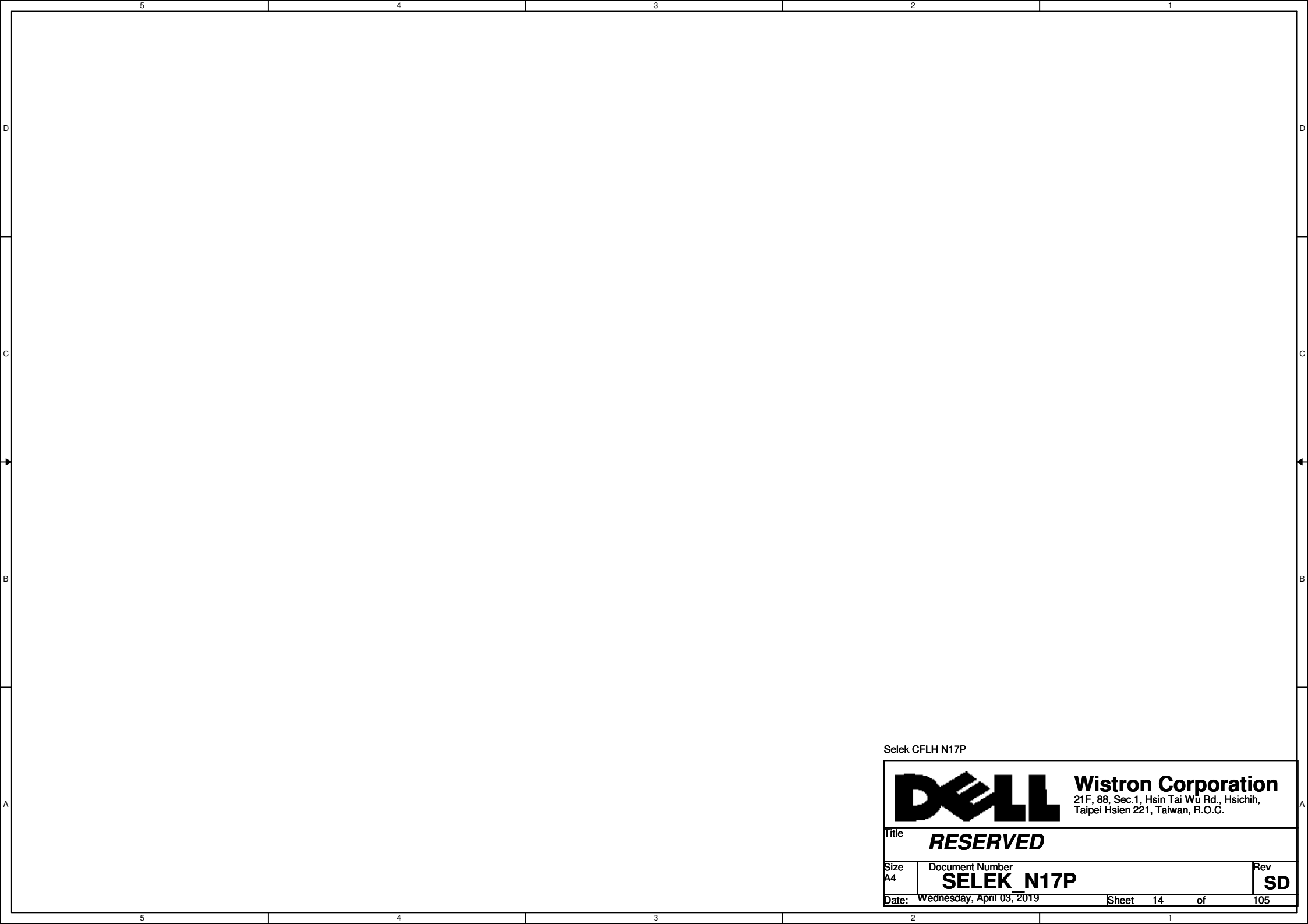
Note: It is important to make sure that the noise on VCCPLL rail must be limited to the +/-5% VR specification below 150KHz - as this will potentially impact the PLL failing to phase lock. Where necessary, the 0805 placeholder can be stuffed with a 22uF or 47uF to assist noise reduction. While stuffing the 0805 cap may reduce noise coupling, one should still route the PLL rail carefully (i.e. to avoid noisy and high current rail) to mitigate any potential issue.

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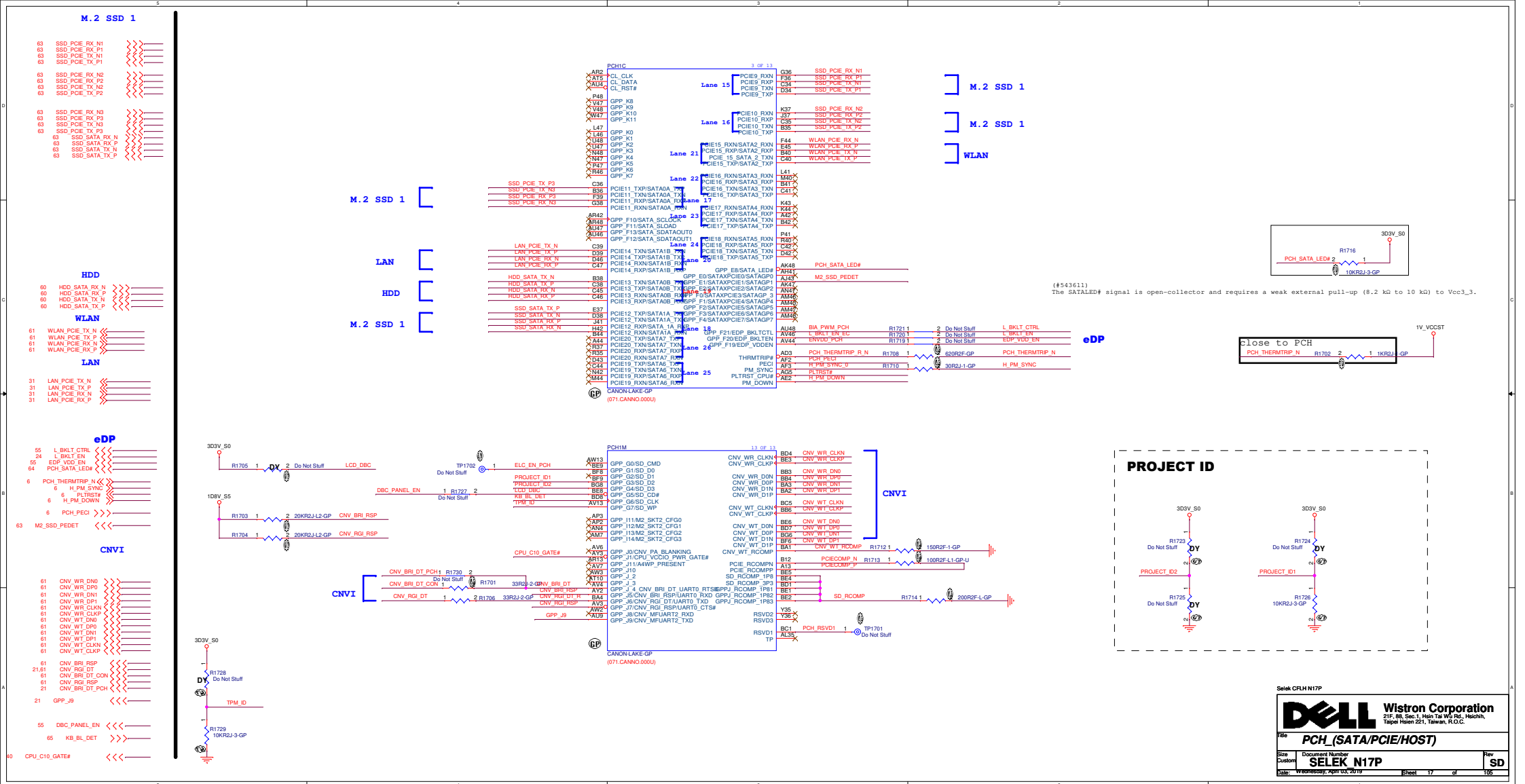
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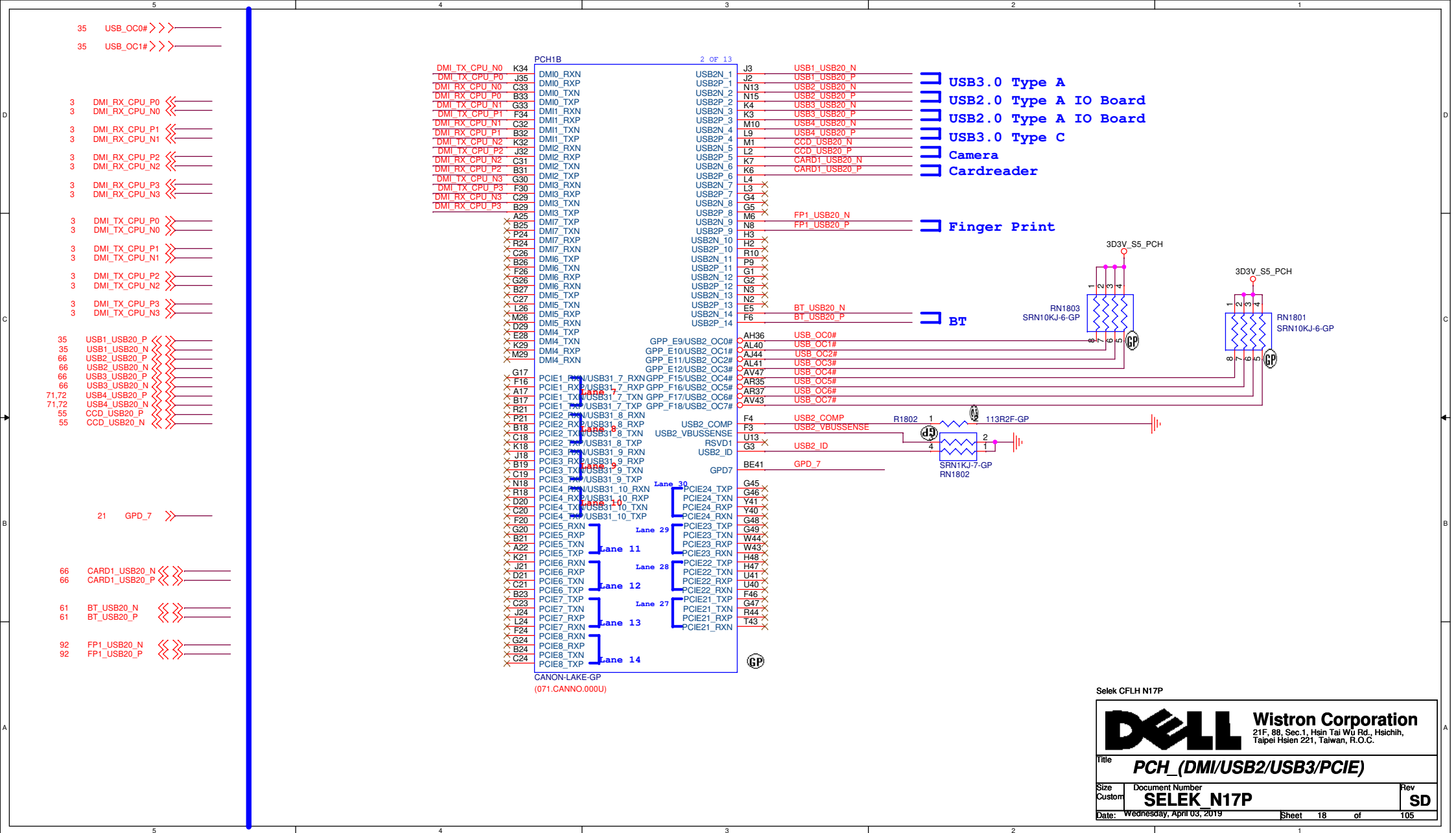
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40.64.51.92    PUL_SLP_35M    >>>>
24    PCH_WAVE_N    >>>>
12.26.75    CPU_SAM_SEC    >>>>
24.76.86    DSPU_PWROK    >>>>
24    SYS_PWROK    >>>>
24.05    TP_WAVE_KBCW    >>>>
21.27    SPIR    >>>>
24.26    RESET_OUTF    >>>>
12.13    PCH_SMBDATA    >>>>
12.13    PCH_SMBIOX    >>>>
6    PCH_I2TAGX    <<<<
25.40.43    IV_SLP_PCH    >>>>
24    PCH_RSMRST    >>>>
43.44    ACK_IN_RJ    >>>>
84    PM_RSMRSTF    >>>>

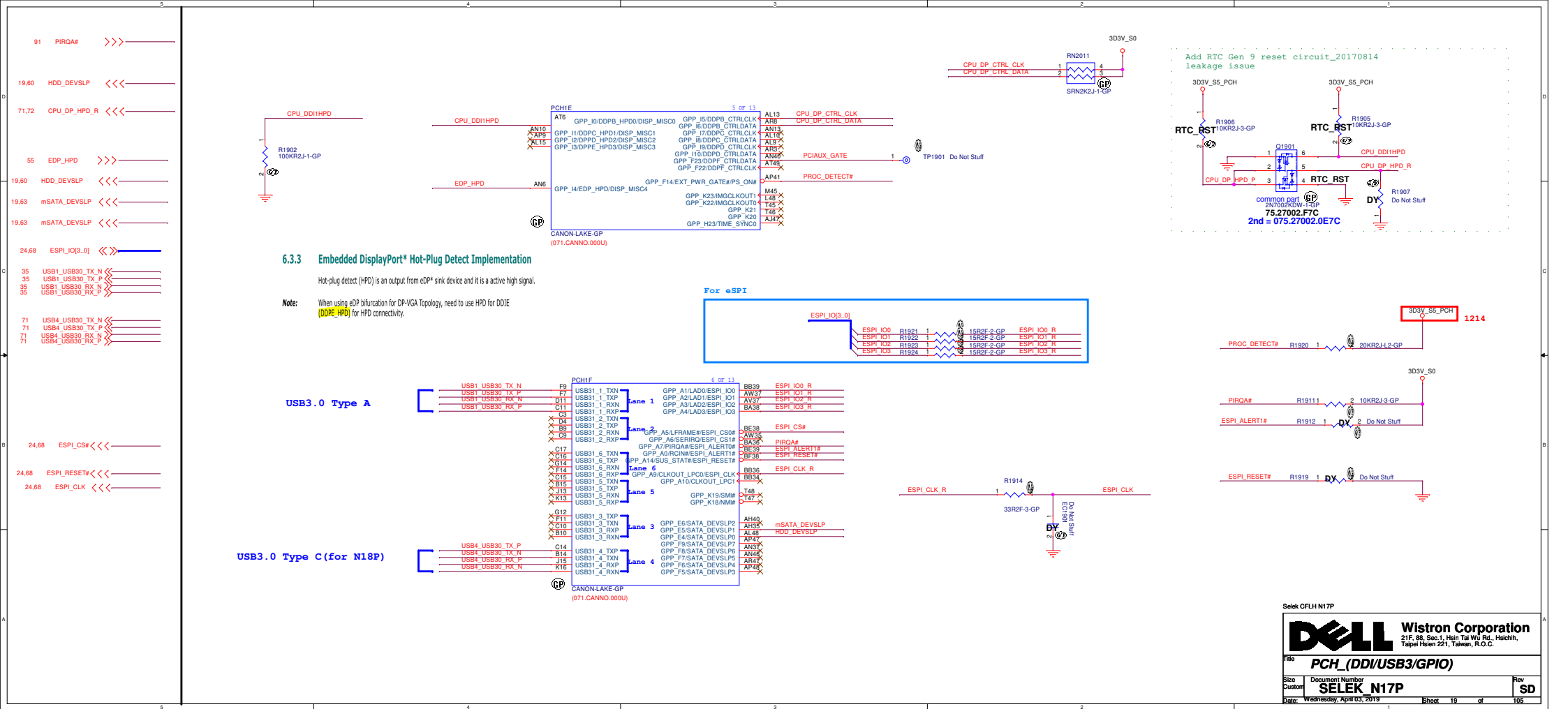
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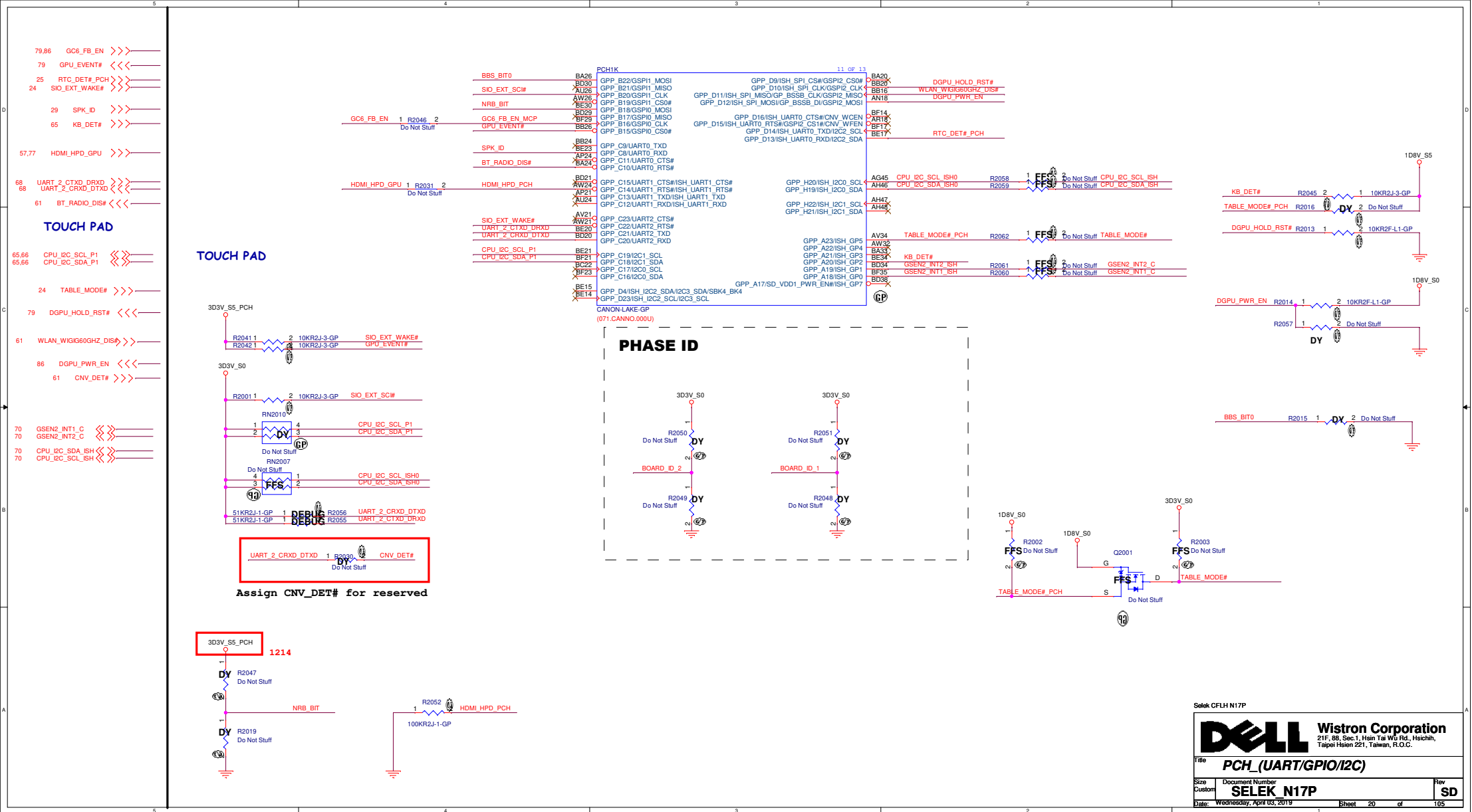


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Title PCH (CLK)			
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GPIO	GPP_B14 SPKR	GPP_B18 GSPIO_MOSI	GPP_C2 SMBALERT#	GPP_B22 GSPII_MOSI	GPP_C5 SMBALERT#	SPIO_MOSI SPIO_MISO	GPP_H15 SML3ALERT#
Schematic		default is internal pull down add TP at PCH side		default is internal pull down add TP at PCH side			

GPIO	GPP_B23 SML1ALERT# PCHHOT#	SPIO_IO2	SPIO_IO3	HDA_SDO/ I2S0_TXD	GPP_H12 SML2ALERT#	GPP_I6 DDPB_CTRLDATA	GPP_I8 DDPC_CTRLDATA
Schematic					internal pull down	Pull high at page 19	internal pull down

need check the latest CRB,PDG

GPIO	GPP_I10	GPP_F23/ DPPF_CTRLDATA	GPP_J4 CNV_BRI_DT UART0_RTS#	GPP_J6 CNV_RGI_DT UART0_TXD	GPP_J9	GPDI7	
Schematic		internal pull down					

Table 9-1. Pin Straps (Sheet 1 of 4)

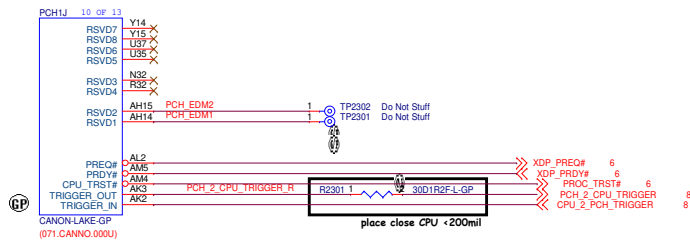
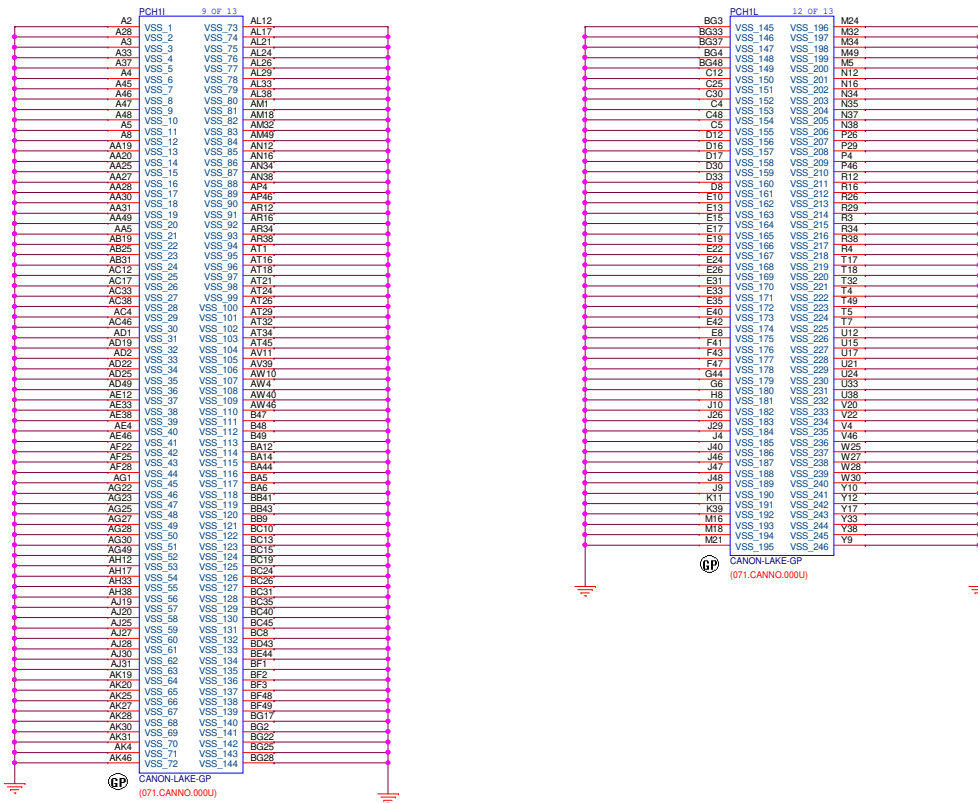
Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top Drive Overhaul	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_B18 / GSPIO_MOSI	No Sensor	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_C2 / SMBALERT#	TL3 Core Activity	Rising edge of SSM1#	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.

Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top Drive Overhaul	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_B18 / GSPIO_MOSI	No Sensor	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_C2 / SMBALERT#	TL3 Core Activity	Rising edge of SSM1#	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.

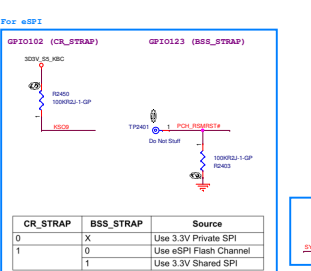
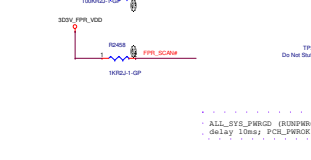
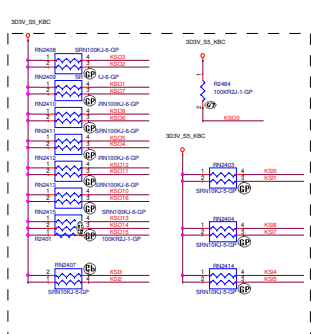
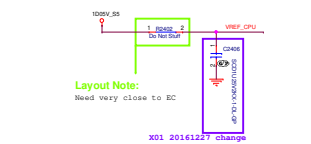
Signal	Usage	When Sampled	Comment
GPP_B14 / SPCR	Top Drive Overhaul	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_B18 / GSPIO_MOSI	No Sensor	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_C2 / SMBALERT#	TL3 Core Activity	Rising edge of SSM1#	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.

Signal	Usage	When Sampled	Comment
GPP_F23 / DPPF_CTRLDATA	Display Port 7 Detected	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_J4 / CNV_BRI_DT / UART0_RTS#	XTAL Frequency Select	Rising edge of SSM1#	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_J6 / CNV_RGI_DT / UART0_TXD	PL2 CNV Mode Select	Rising edge of SSM1#	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPP_J9	1.8V VCCPSI	Rising edge of SSM1#	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.
GPDI7	Reserved	Rising edge of PCH_PWDOK	<p>The signal has a weak internal pull-down.</p> <p>1 = Disable "No Sensor" mode. (Default)</p> <p>0 = "No Sensor" mode. This enables an address on the sensor (I2C) and allows the PCH to read the sensor data. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor. The sensor data is then used to determine the status of the sensor.</p> <p>Notes:</p> <ol style="list-style-type: none"> The internal pull-down is disabled after PCH_PWDOK is high. This signal is in the primary well.

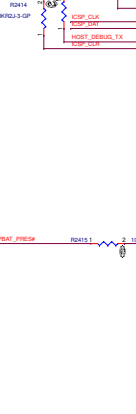
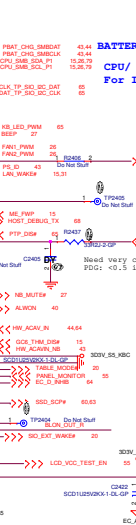
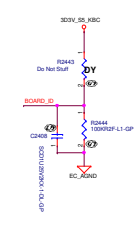
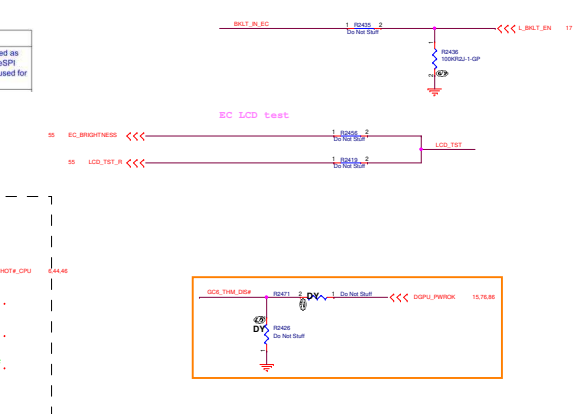
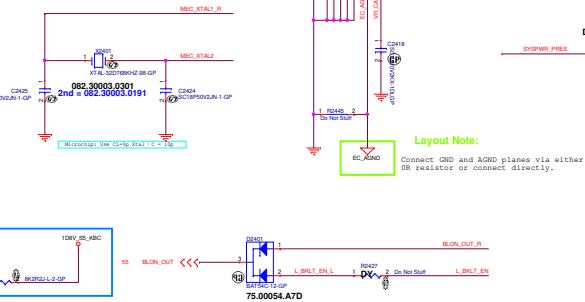
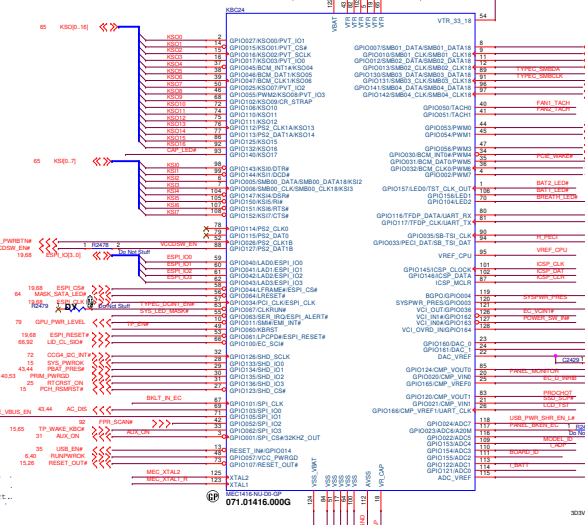
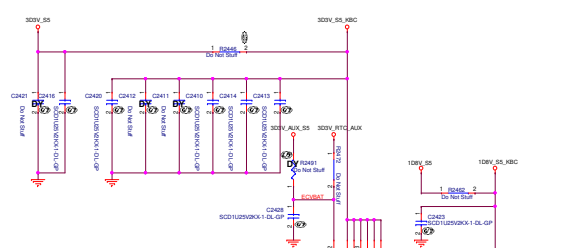
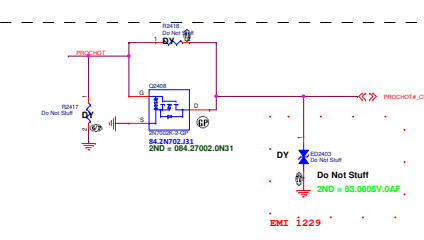
SMBALERT#



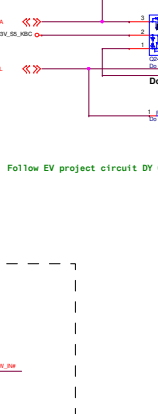
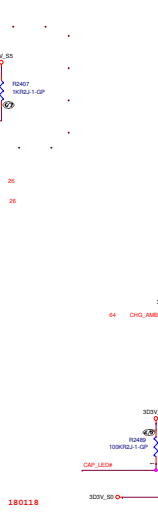
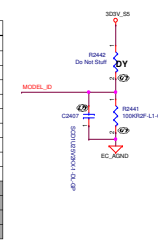
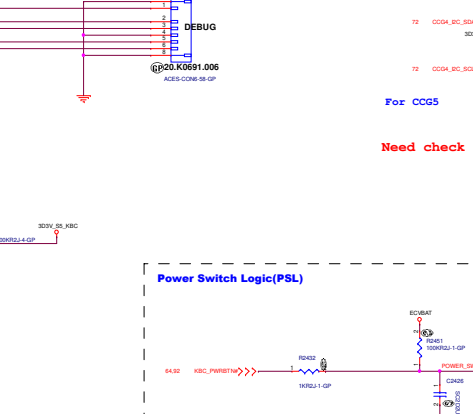
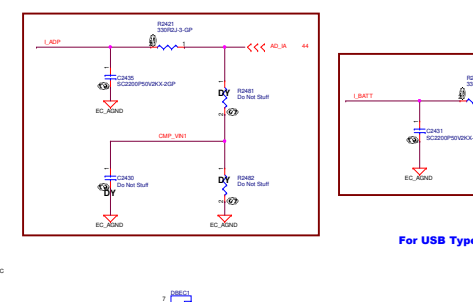
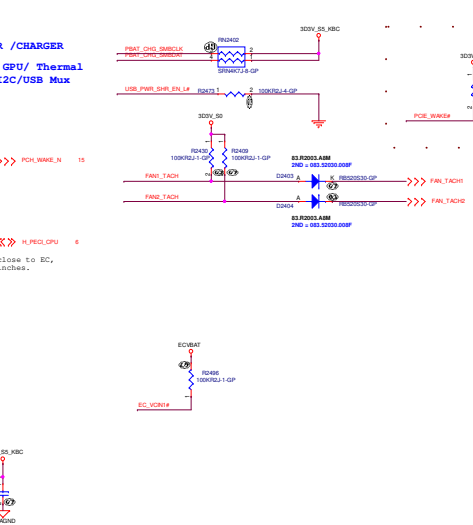
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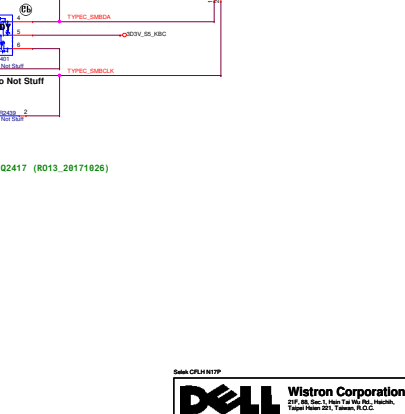
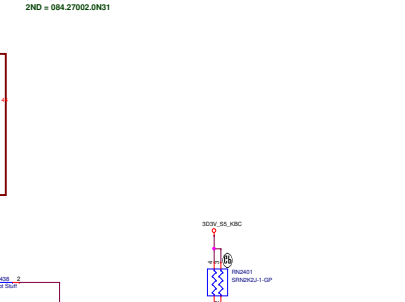
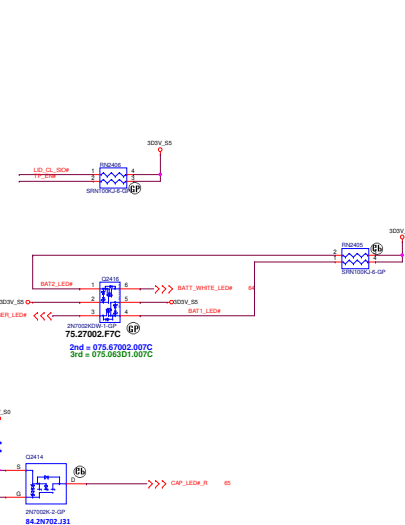
Note	Description
Note 16	If the eSPI Flash Channel is used for booting, the GPIO123/SHD_C58 pin must be used as RSMRST#. This pin will be driven high by the boot ROM code in order to activate the eSPI flash channel. If the SHD_SPI port is used for booting, then any unused GPIO may be used for RSMRST#.



#	Board_ID(GPIO155)	PULL-LOW RESISTOR	PULL-HIGH RESISTOR	VOLTAOE
1	X00	100.0K	10.0K	3
2	X01	100.0K	17.8K	2.801
3	X02	100.0K	27.0K	2.598
4	X03(Reserved)	100.0K	37.4K	2.402
5	A00	100.0K	49.9K	2.201
6	A01	100.0K	64.9K	2.001
7	A02	100.0K	82.5K	1.808
8	A03	100.0K	107K	1.594
9	Reserved	100.0K	154K	1.299
10	Reserved	100.0K	200K	1.1
11	Reserved	100.0K	TBD	0.9
12	Reserved	100.0K	TBD	0.7
13	Reserved	100.0K	TBD	0.5
14	Reserved	100.0K	TBD	0.3



#	MODEL_ID(GPIO153)	PULL-LOW RESISTOR	PULL-HIGH RESISTOR	VOLTAOE
1	Nvidia-N17P-G0-K1	100.0K	10.0K	3
2	Nvidia-N18P-G0	100.0K	17.8K	2.801
3	Nvidia-N19P-G0	100.0K	27.0K	2.598
4	Nvidia-N18E-G0	100.0K	37.4K	2.402
5	Nvidia-N19E-G0	100.0K	49.9K	2.201
6	Nvidia-N18E-G1	100.0K	64.9K	2.001
7	Nvidia-N19E-G1	100.0K	82.5K	1.808
8	Nvidia-N18E-G1	100.0K	107K	1.594
9	Nvidia-N19E-G1	100.0K	154K	1.299
10	Reserved	100.0K	TBD	0.9
11	Reserved	100.0K	TBD	0.7
12	Reserved	100.0K	TBD	0.5
13	Reserved	100.0K	TBD	0.3

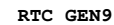
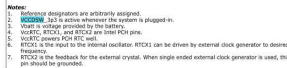


SSID = Flash.ROM

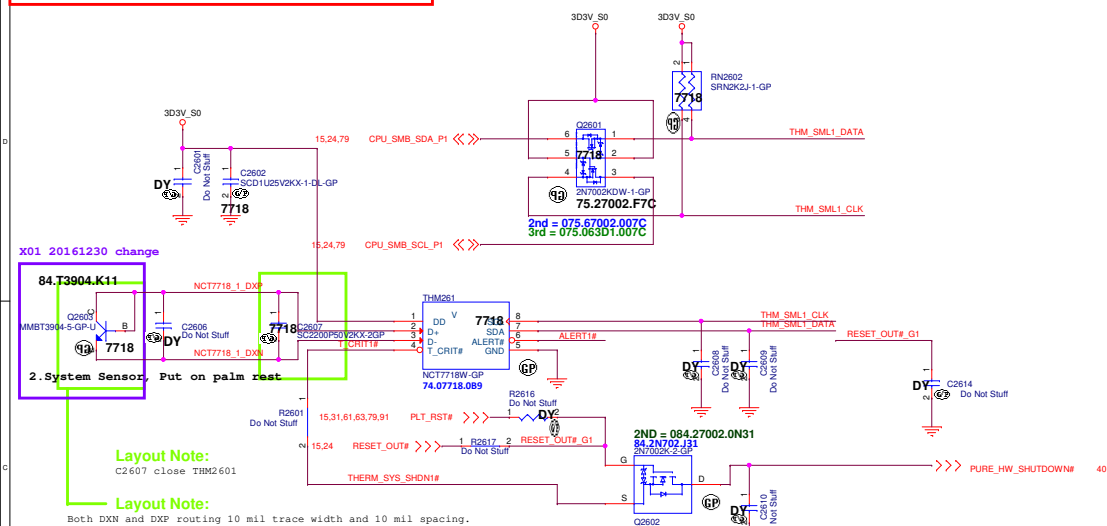


BTY RTC CR2016_30MM KTS 2PIN

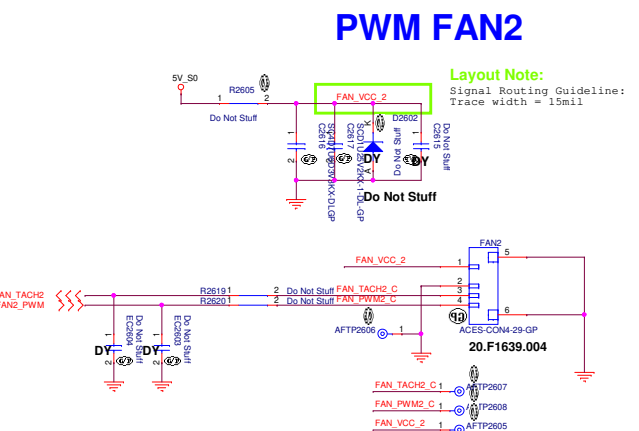
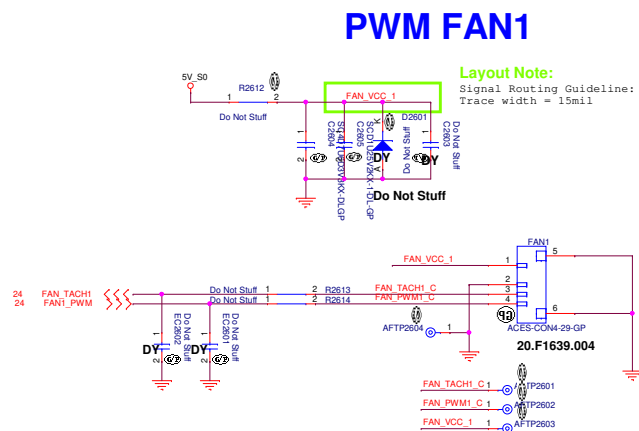
-1 20161118



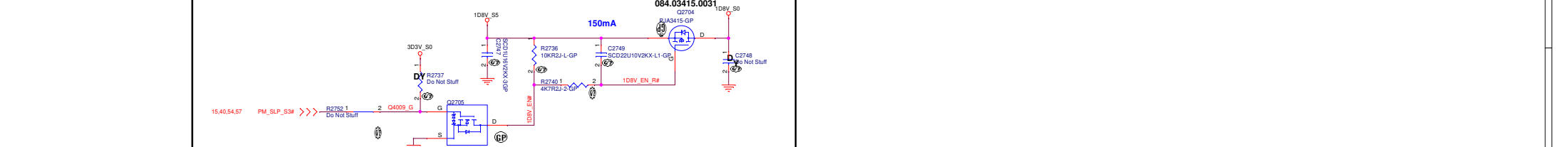
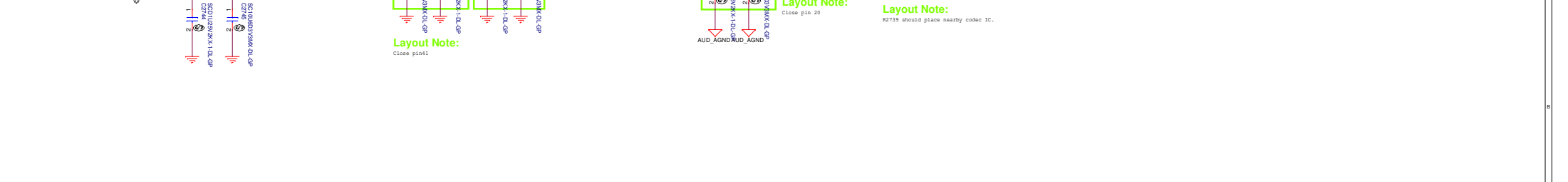
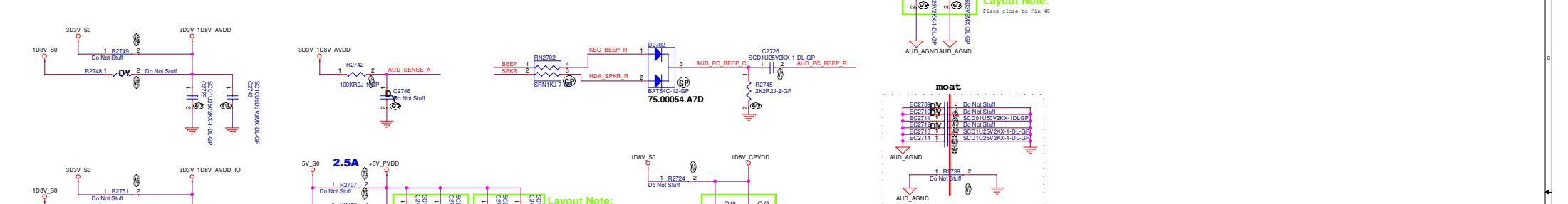
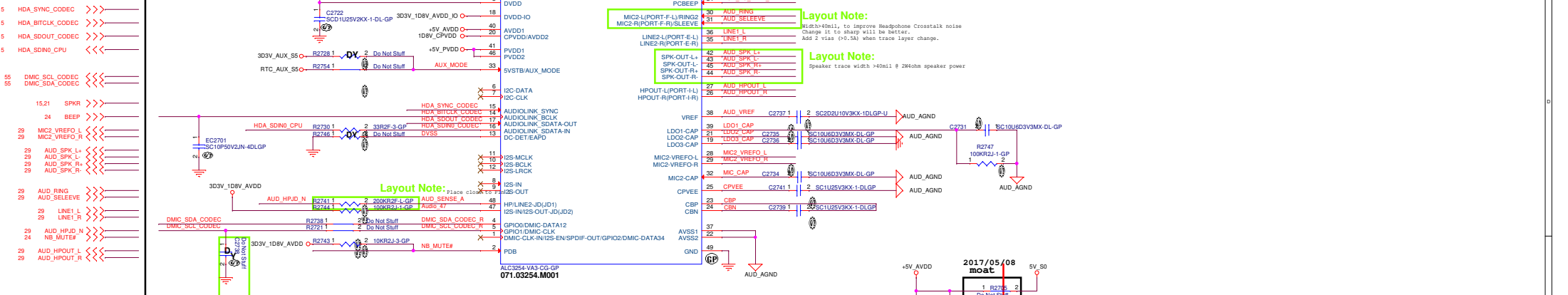
5
Main Func = Thermal Sensor

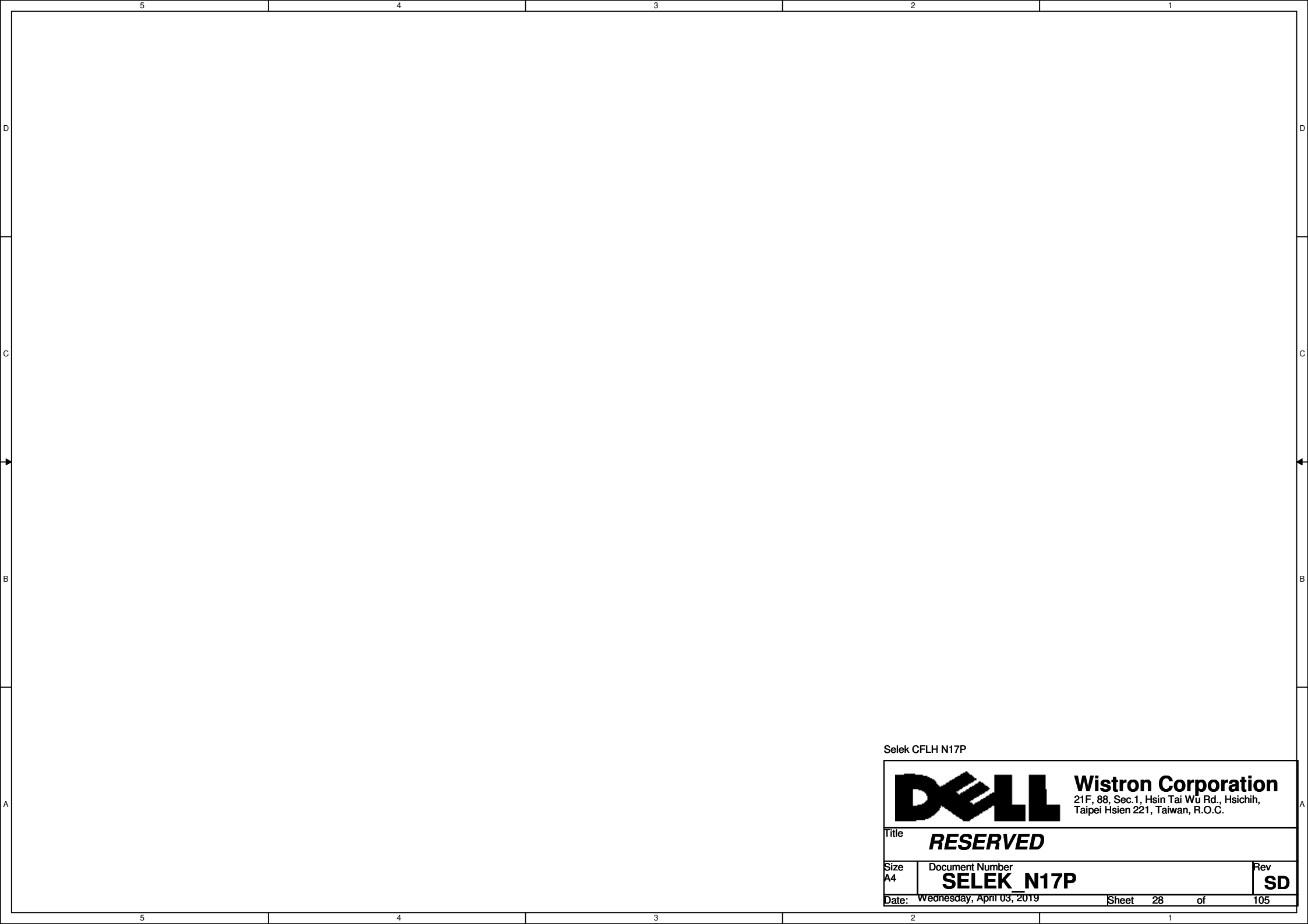


TEMPERATURE (°C)		T_CRIT#				
		2KΩ	7.5KΩ	10.5KΩ	14KΩ	18.7KΩ
ALERT#	2KΩ	77	87	97	107	117
	7.5KΩ	79	89	99	109	119
	10.5KΩ	81	91	101	111	121
	14KΩ	83	93	103	113	123
	18.7KΩ	85	95	105	115	125




SSID = Audio





Selek CFLH N17P

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Title RESERVED			
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D

C |

B

A

Selek CFLH N17P



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title

(Reserved)

Size

A

Document Number

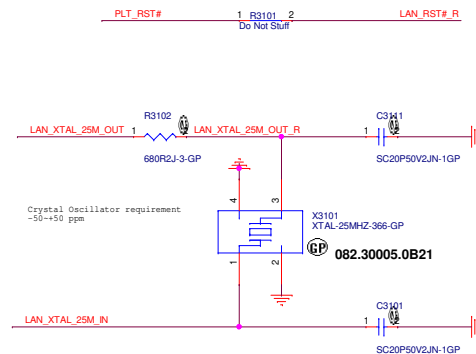
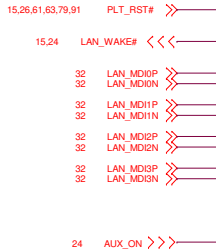
SELEK N17P

Rev

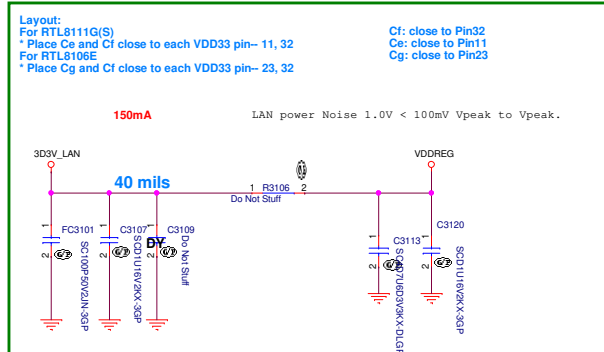
SD

Date: Wednesday, April 03, 2019

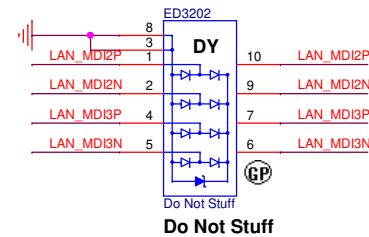
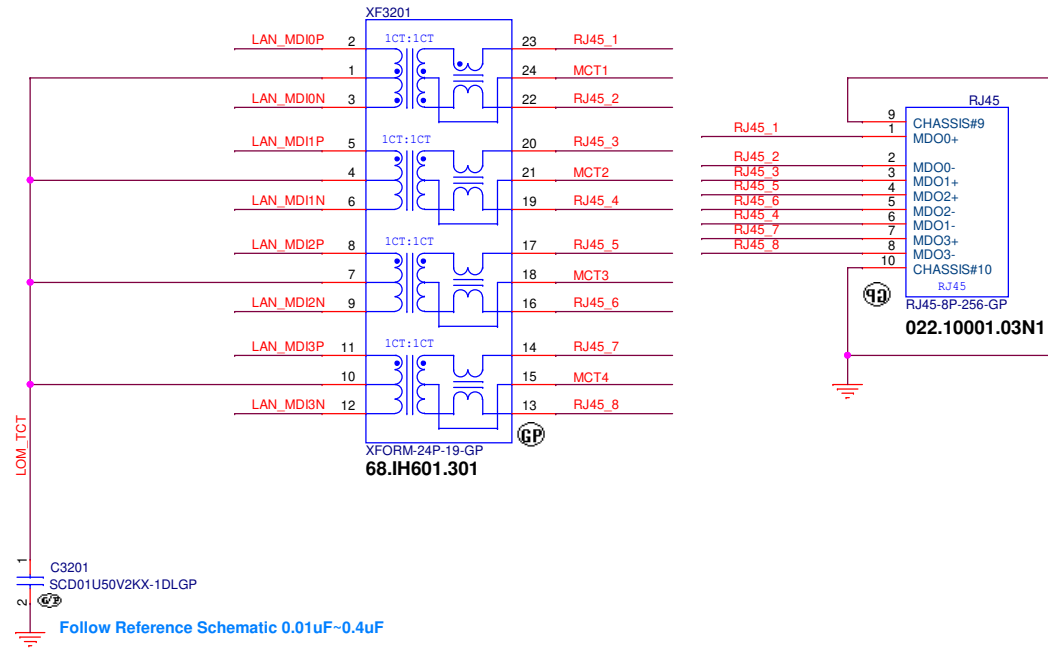
Sheet 30 of 105



RTL8111HSD-CGT
071.8111H.M001
SWR mode
10/100/1000M



SSID = LAN



Title	<i>RJ45+Transformer</i>
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SSID = Card Reader

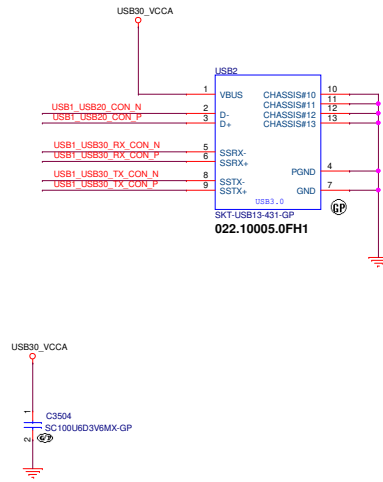
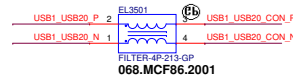
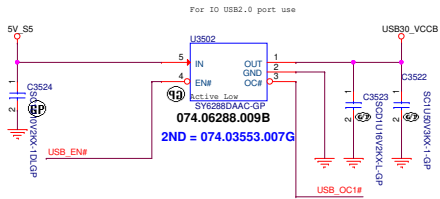
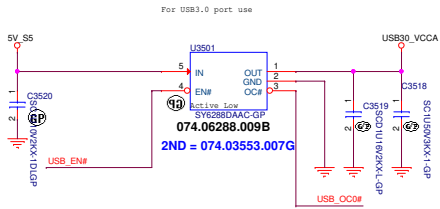
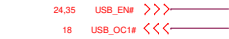
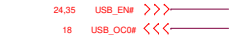
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Title (Reserved)			
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5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

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USB 3.0 Connector Pin definition	
1	POWER
2	USB 2.0 D-
3	USB 2.0 D+
4	GND
5	StdA_SSRX- SuperSpeed RX
6	StdA_SSRX+
7	GND
8	StdA_SSTX- SuperSpeed TX
9	StdA_SSTX+

D

C |

B

A

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Title	Author	Year	Journal	Volume	Issue	Page
1. The Effect of the 1997 Asian Financial Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	581-594
2. The Impact of the Asian Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	595-608
3. The Effect of the 1997 Asian Financial Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	609-622
4. The Impact of the Asian Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	623-636
5. The Effect of the 1997 Asian Financial Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	637-650
6. The Impact of the Asian Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	651-664
7. The Effect of the 1997 Asian Financial Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	665-678
8. The Impact of the Asian Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	679-692
9. The Effect of the 1997 Asian Financial Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	693-706
10. The Impact of the Asian Crisis on the U.S. Economy	John H. Coatsworth	1998	Journal of International Money and Finance	17	4	707-720

(Reserved)

Size

A

Document Number

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Rev

SD

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SSID = USB3.0 Redrivere

USB 3.0 Re-driver Pull High / Low

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

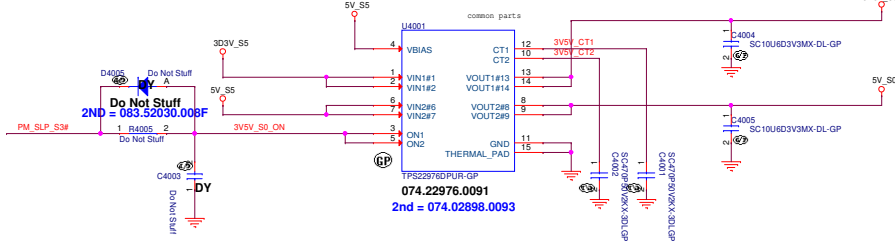
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Title (Reserved)			
Size A	Document Number SELEK N17P		Rev SD
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Power Sequence

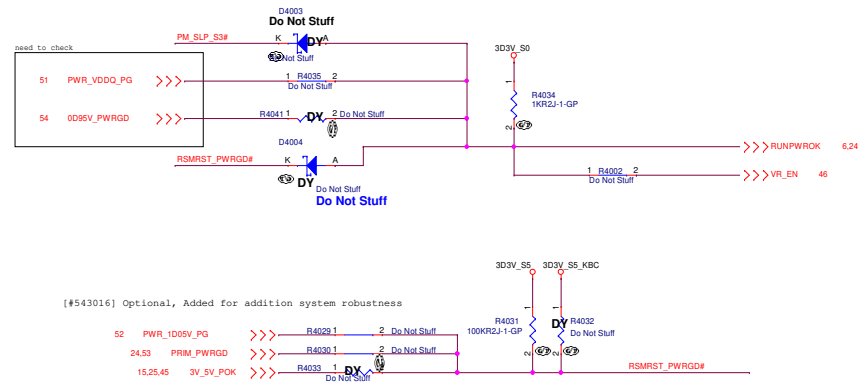
5V_S0 3D3V_S0

5V_S0 Consumption Peak current 5A
3D3V_S0 Consumption Peak current 2.5A

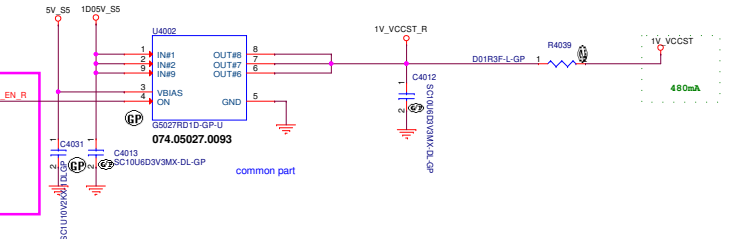
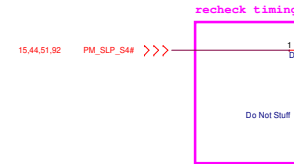
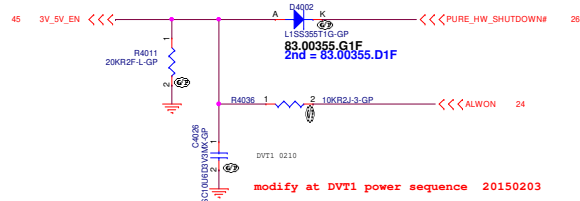
ROSA Run Power



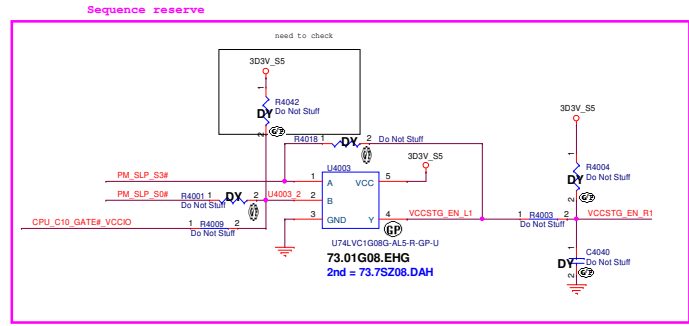
Power Good



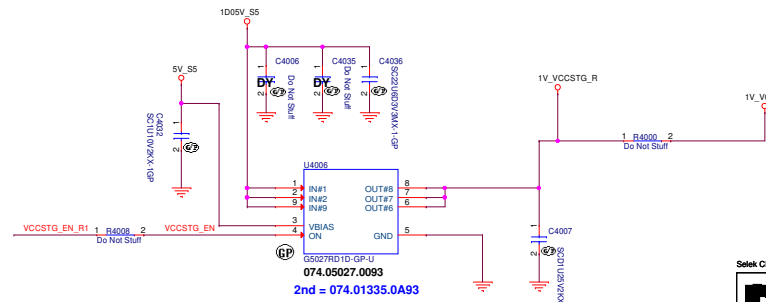
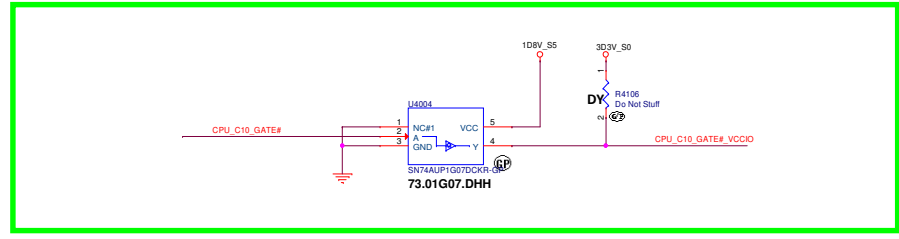
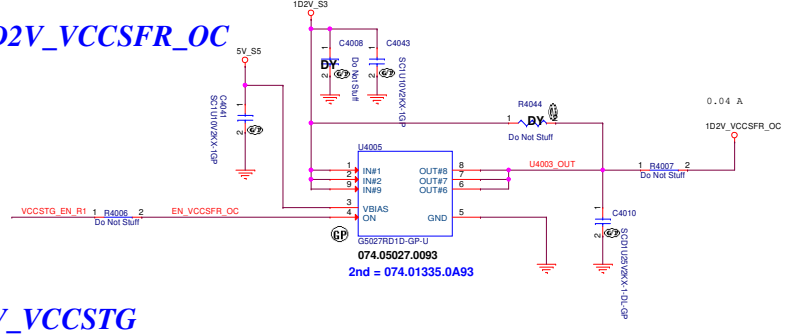
IV_VCCST



ID2V_VCCSFR_OC




IV_VCCSTG




Main Func = Power & Sequence

Selek CFLH N17P

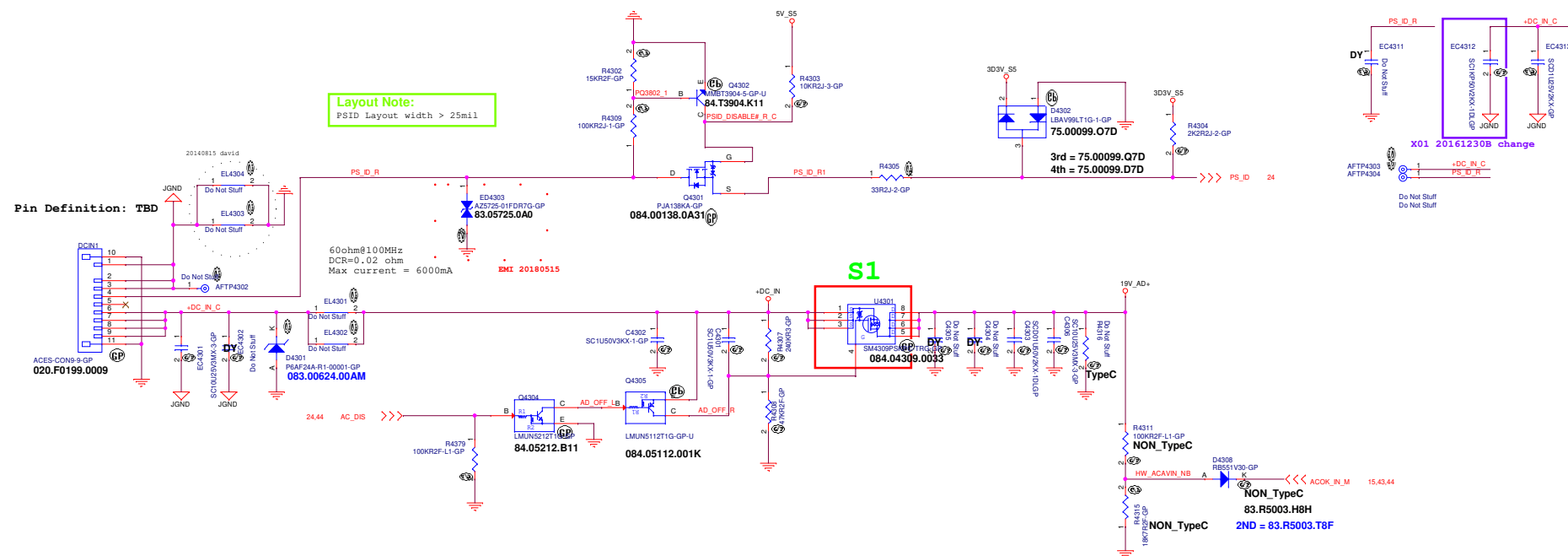
		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title		Connected_Standby(1/2)+DS3	
Size A3	Document Number SELEK N17P		Rev SD
Date: Wednesday, April 03, 2019	Sheet	41	of 105

5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

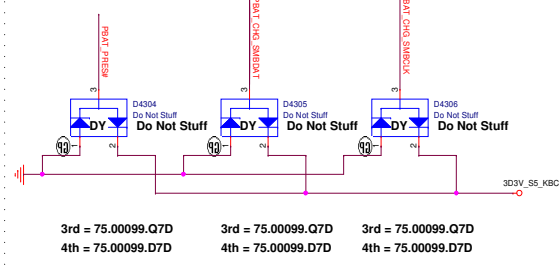
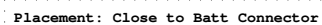
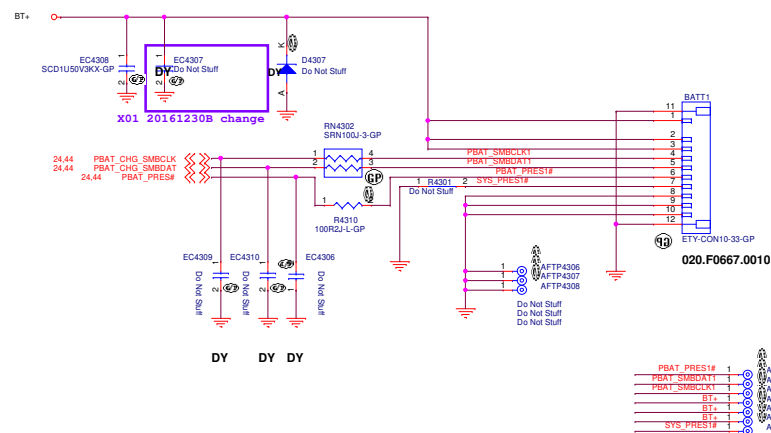
Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title (Reserved)			
Size A	Document Number SELEK N17P		Rev SD
Date:	Wednesday, April 03, 2019	Sheet 42 of	105

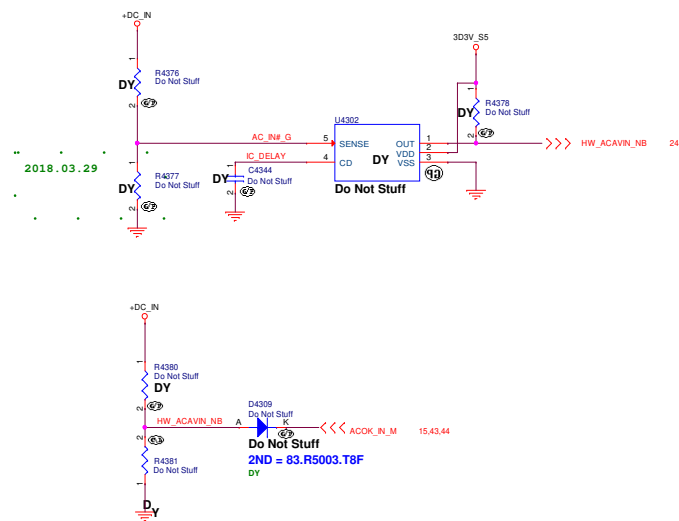
Main Func = ADT Input



Main Func = M-BAT Input



Barrel Adapter Piug-in Detect



ISL95522 Hybrid Charger

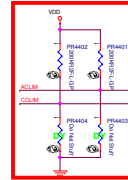
OFF PAGE

24.44	HW_ACR_IN	<<<<	1	PR4453	2	HW_ACR_IN_M	>>>>
							Do Not Stuff
	24.43	AC_DIS	>>>>				
	15.43.51.50	PWR_SLP_SAW	<<<<				
	15.43	ACOK_NL_M	<<<<				
	24.43	PRAT_CHG_SMBCLK	<<<<				
	24.43	PRAT_CHG_SMBCLK	<<<<				
	24.43	PRAT_PRESH	>>>>				
	6.24.46	PROCHOT#_CPU	<<<<				
	24	ADJ_A	<<<<				
	46	CHGR_PSYS_BAMP	<<<<				
	24	batm_hm	<<<<				

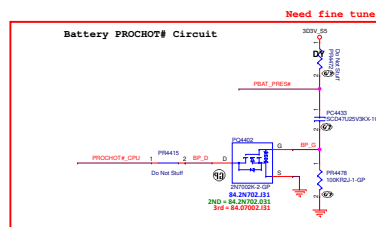
E3

$$I_{ACLIMHW} = \frac{V_{ACLIMHW}}{32 \times PR4433}$$

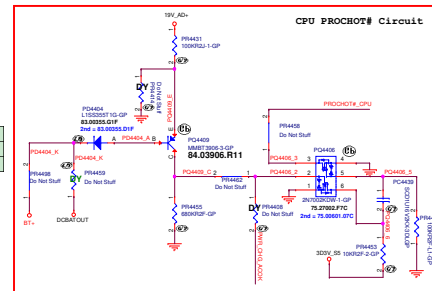
$$I_{CCLIMHW} = \frac{V_{CCLIMHW}}{32 \times PR4436}$$



Change the load in the Bat_Saw to batm_hm by power team release 1/10



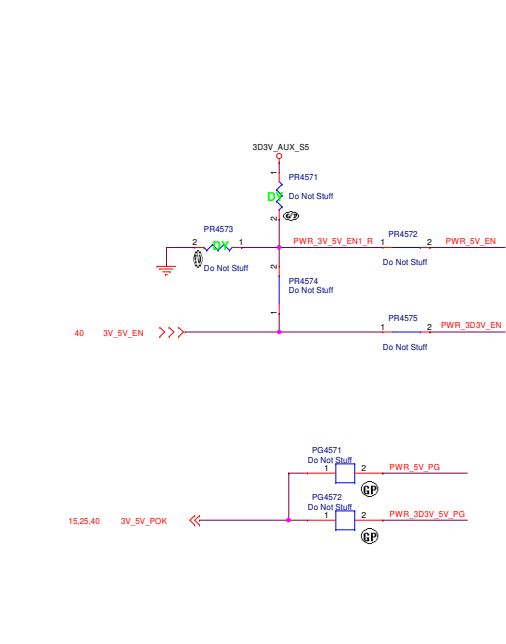
PR4405	2 cell	3 cell	4 cell
NVDC	100k	66.5k	82.5k
HYBRID	165k	182k	147k



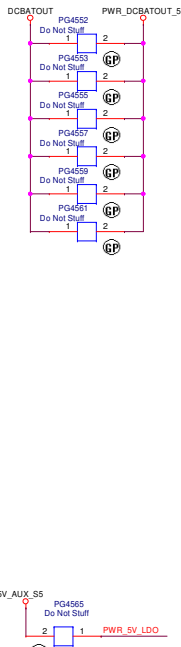
Sata CPU#N1P

SSID = PWR.Plane.Regulator_5V

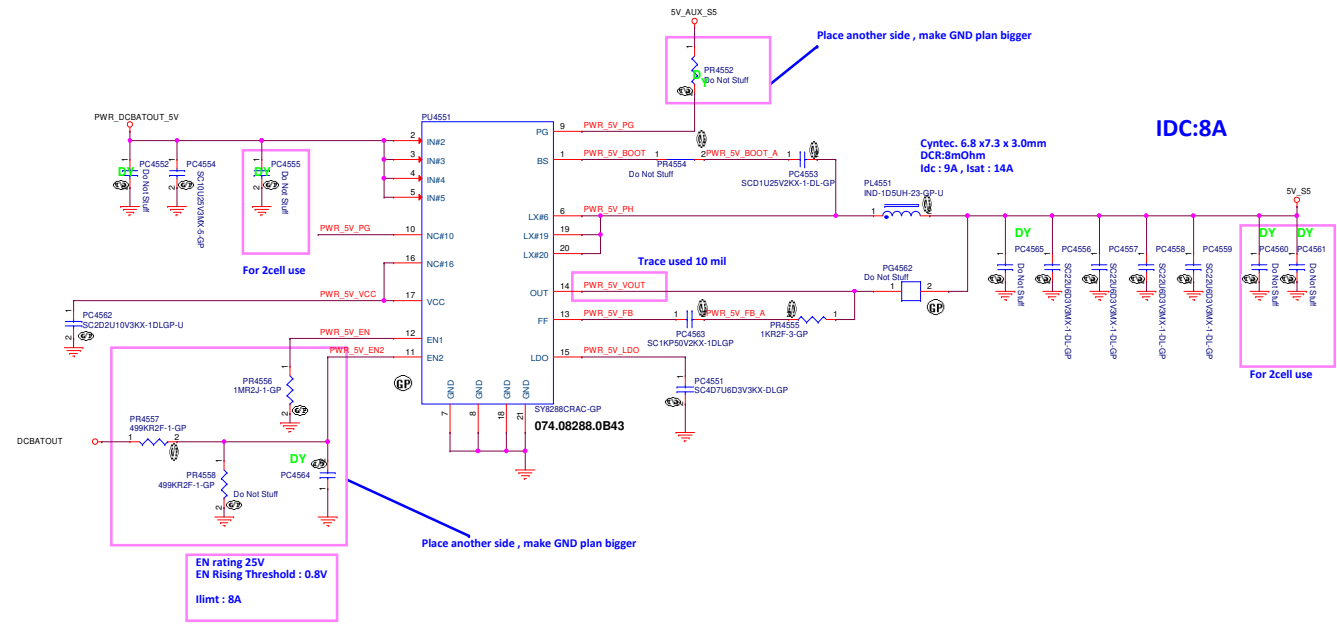
OFFPAGE-Signal



OFFPAGE-GAP



SY8288C For 5V



SSID = PWR.Plane.Regulator_3D3V

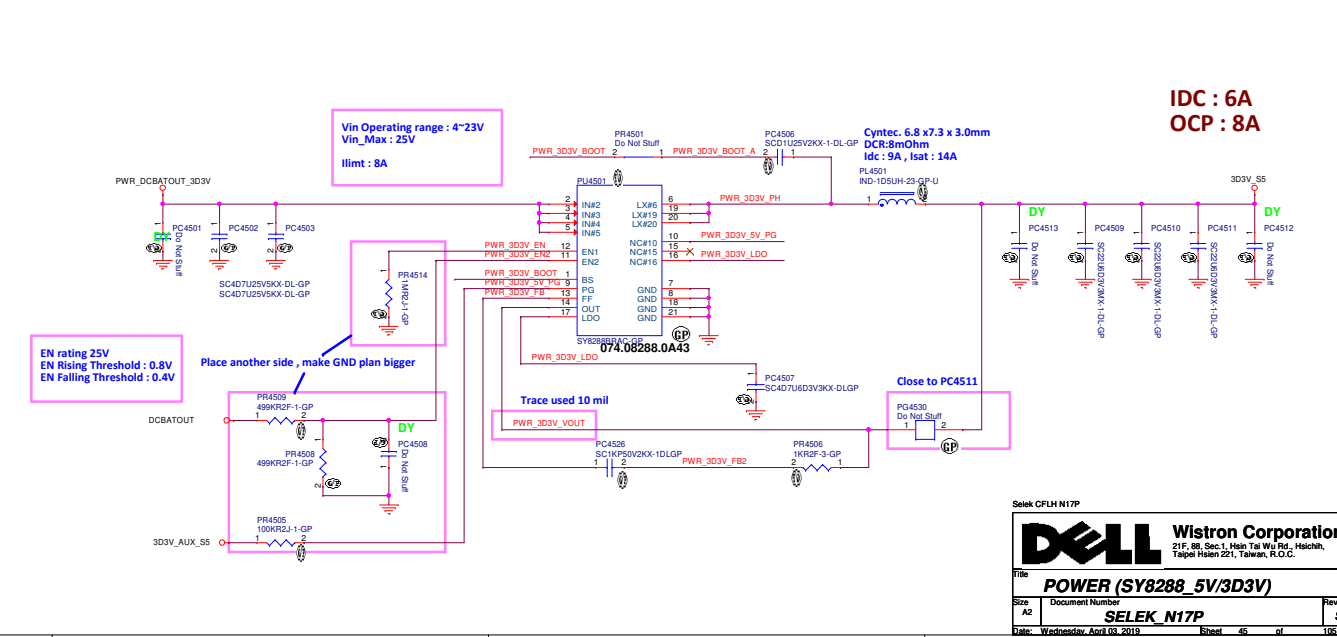
OFFPAGE-Signal

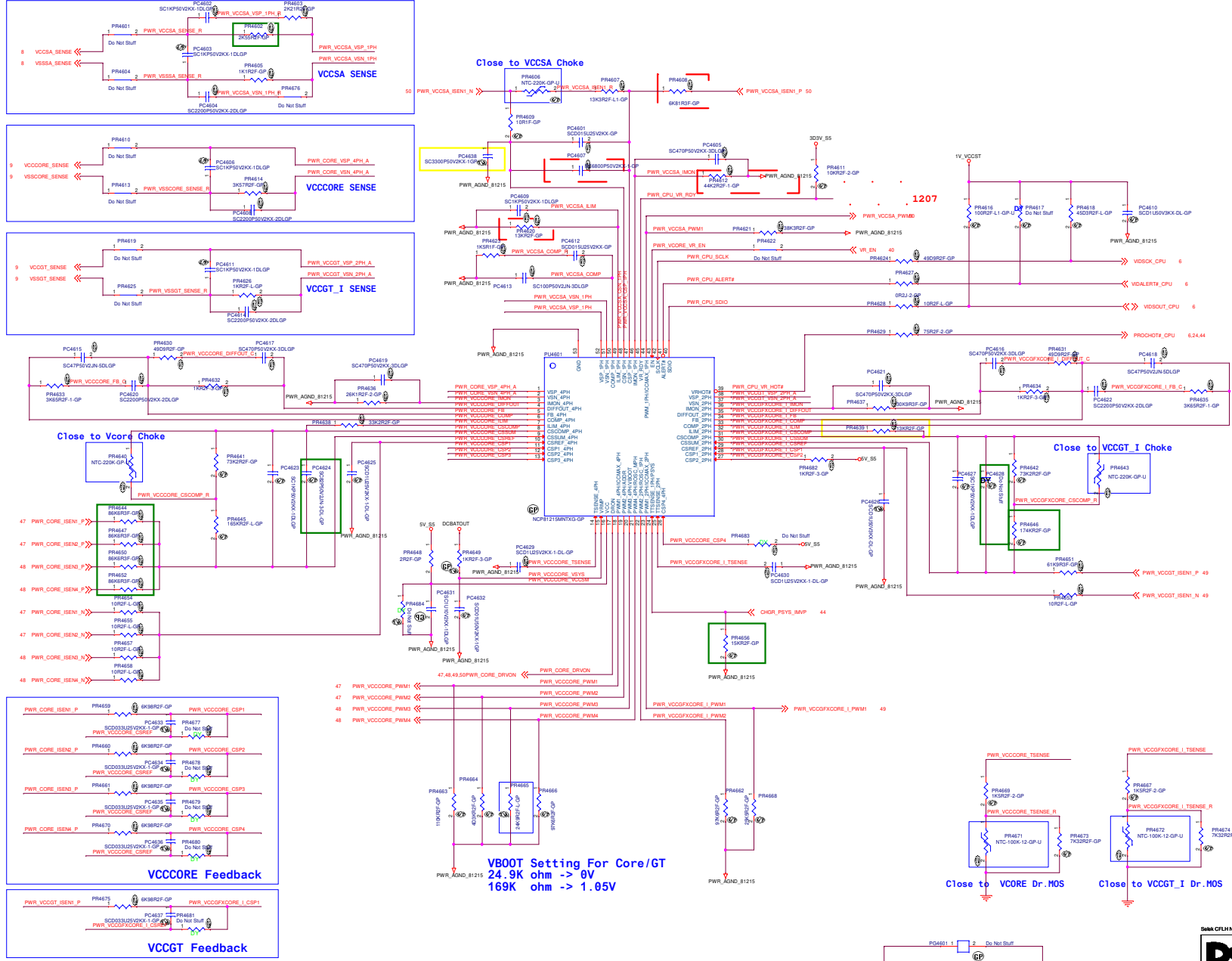


OFFPAGE-GAP



SY8286B For 3D3V





VB00T Setting For Core/GT
24.9K ohm -> 0V
169K ohm -> 1.05V

Add: PWR GAP
change GND symbol on this page ALL GND

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

- CFL_H-45W
IMAX 96 A / TDC 75 A / OCP 120 A

330uF 4 Pcs

EE 0401

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.

Max Current = 3.50(A)

PWR_DCBATOUT_VCCCORE

MLCCs must be placed
symmetrically on Top and Bottom.

This circuit is for Hexa core.
Please refer to the table in next page.

Selek CFLH N17P

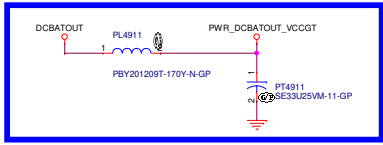
DELL Wistron Corporation
21F, 88, Sec 1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title
DC/DC VCCCPUCORE (2/2)

Size
C Document Number
SELEK N17P

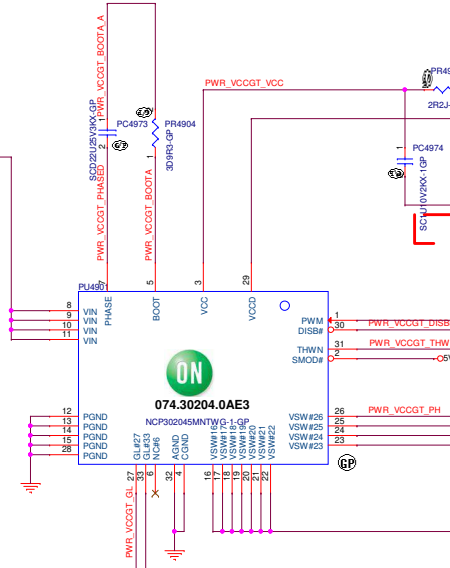
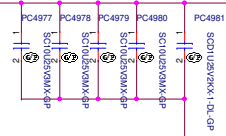
Rev
SD

Date: Wednesday, April 03, 2019 Sheet 48 of 105



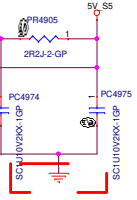
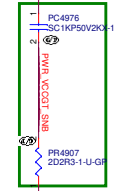
For acousaic noise 1228

PWR_DCBATOUT_VCCGT



074.30204.0AE3

NCP30204SMNTW1G-1-GP



Add comment :
MLCCs (Input capacitors at charger)
must placed symmetrically on TOP and BOTTOM side

CFL_H-45W
IMAX 32 A / TDC 25 A / OCP 60 A

1V_VCCGT

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

PWR_VCCGT_VCC

CFL_H-45W
IMAX 32 A / TDC 25 A / OCP 60 A

1V_VCCGT

PT4901

PT4902

SE330VDM4-GP

SE330VDM4-GP

SE330VDM4-GP

SE330VDM4-GP

SE330VDM4-GP

SE330VDM4-GP

SE330VDM4-GP

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SE330VDM4-GP

SE330VDM4-GP

SE330VDM4-GP

SE330VDM4-GP

SE330VDM4-GP

Selek CFLH N17P

DELL		Wistron Corporation	
		21F, 88, Sec-1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title		DC/DC VCCGFXCORE_I(NCP302045)	
Size		Document Number	Rev
Custom		SELEK N17P	SD
Date:		Wednesday, April 03, 2019	Sheet 49 of 105

MLCCs must be placed
symmetrically on Top and Bottom.

Max Current = 0.49(A)

EE 0401

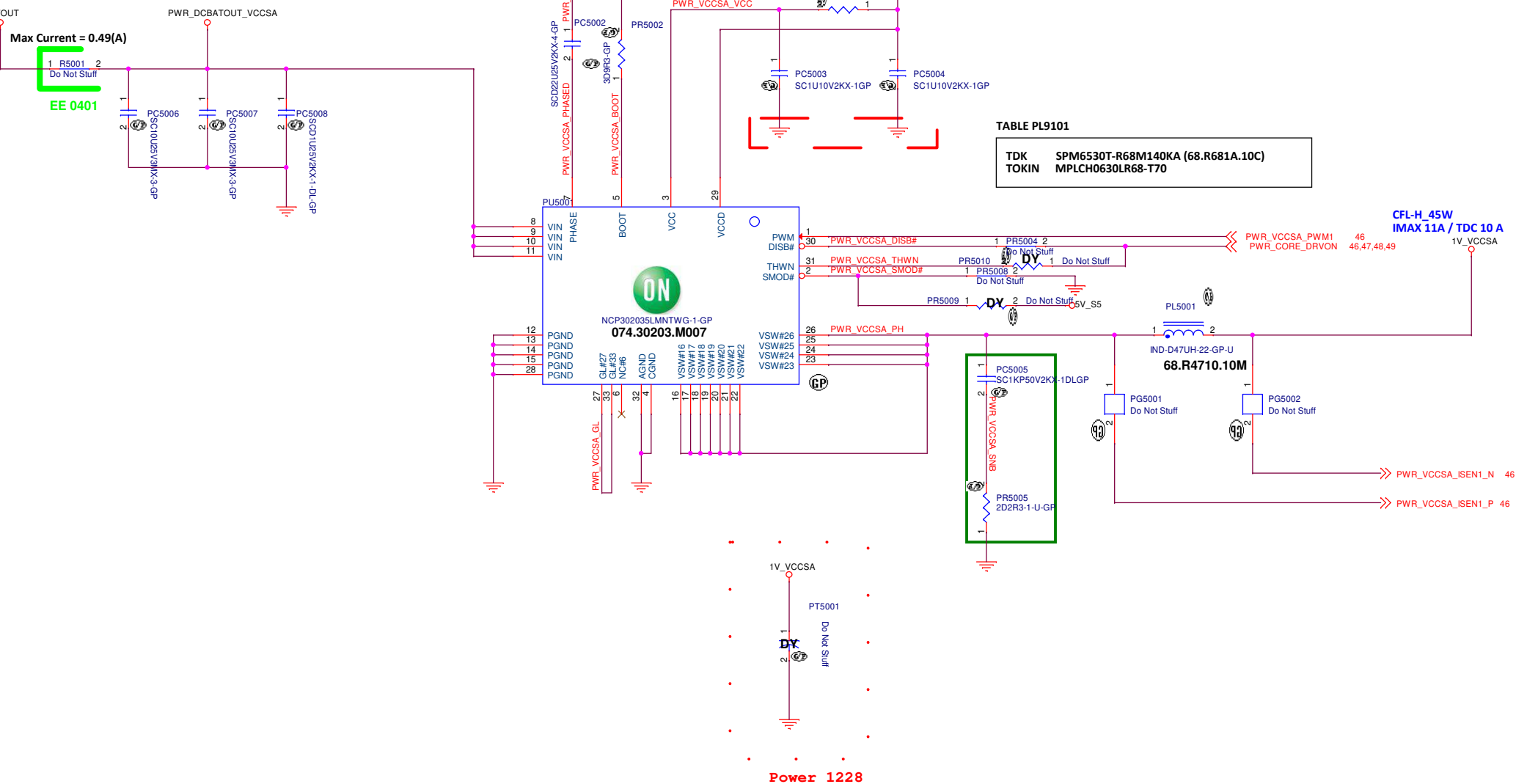


TABLE PL9101

TDK SPM6530T-R68M140KA (68.R681A.10C)
TOKIN MPLCH0630LR68-T70

CFL-H_45W
IMAX 11A / TDC 10 A

Selek CFLH N17P

DELL		Wistron Corporation	
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.			
Title DC/DC VCCSA(NCP302035)			
Size A3	Document Number SELEK N17P	Rev SD	
Date: Wednesday, April 03, 2019		Sheet	50 of 105

OFFPAGE-Signal

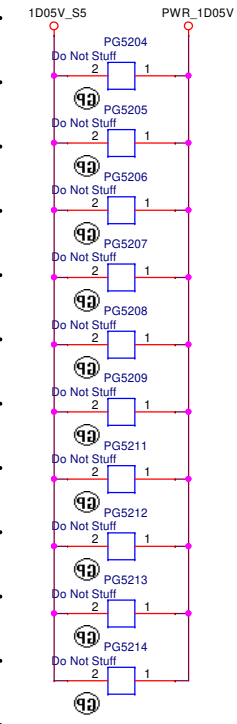
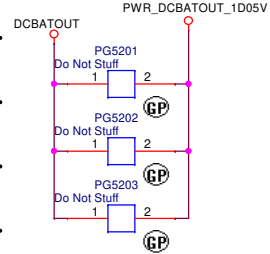
PH on EE Side

PWR_1D05V_PG

3V_5V_DSW_OK

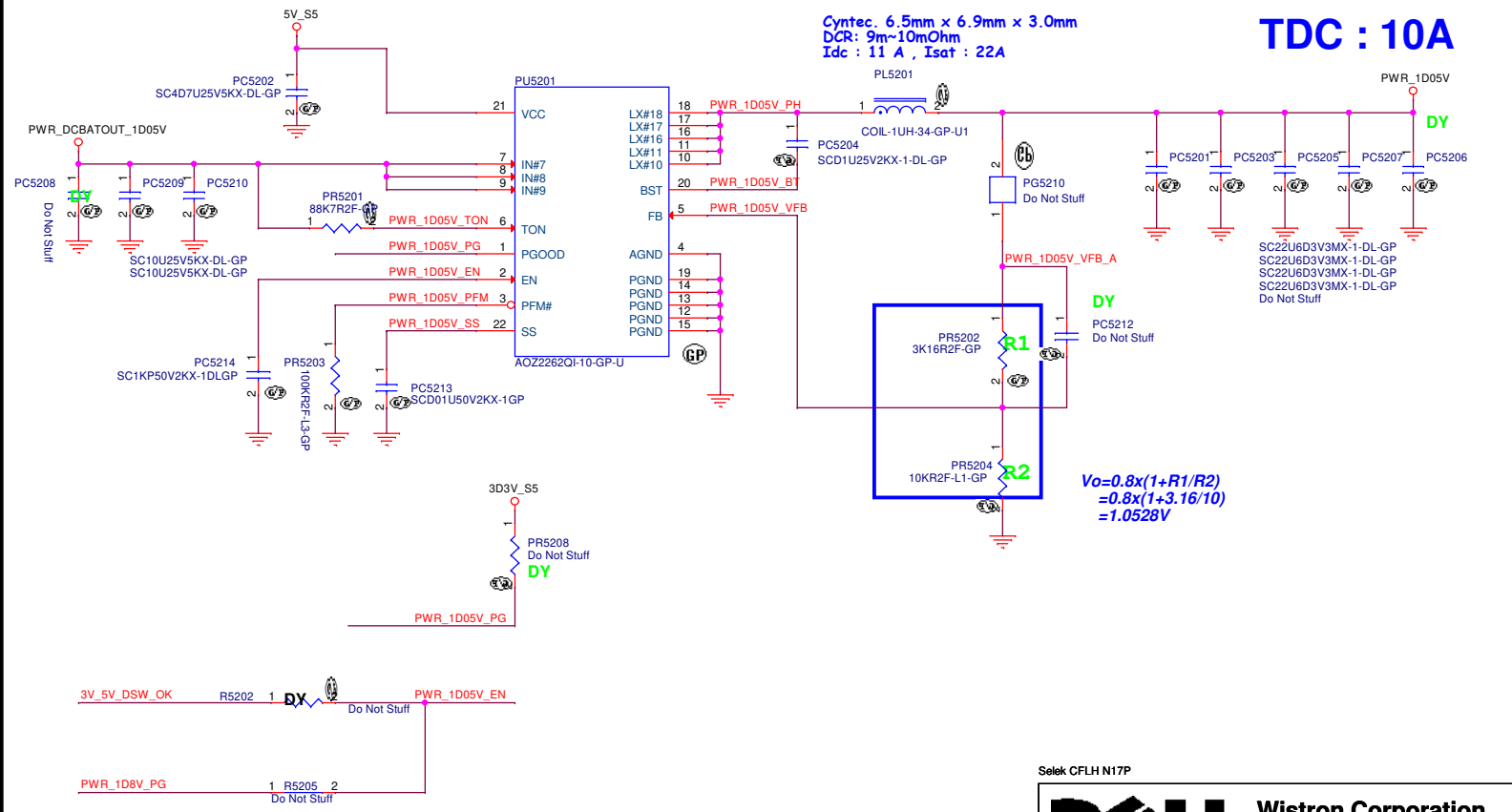
PWR_1D8V_PG

OFFPAGE-GAP



AOZ2262 For 1D05V

COM	IC	AOZ2262 (10A)	AOZ2261 (8A)	AOZ2260 (6A)
		074.02262.0043	074.02261.0A73	074.02260.0043
Chock		68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A	68.1R01A.20B IDC : 10A
Output CAP		22uF/6.3V * 5pcs DY*1	22uF/6.3V * 4pcs DY*1	22uF/6.3V * 4pcs DY*1



Main Func = 1D8V

OFFPAGE

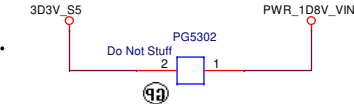
25,52 3V_5V_DSW_OK >>

PH on EE Side

24,40 PRIM_PWRGD << 1 R5304 PWR_1D8V_PG
Do Not Stuff

52 PWR_1D8V_PG <<

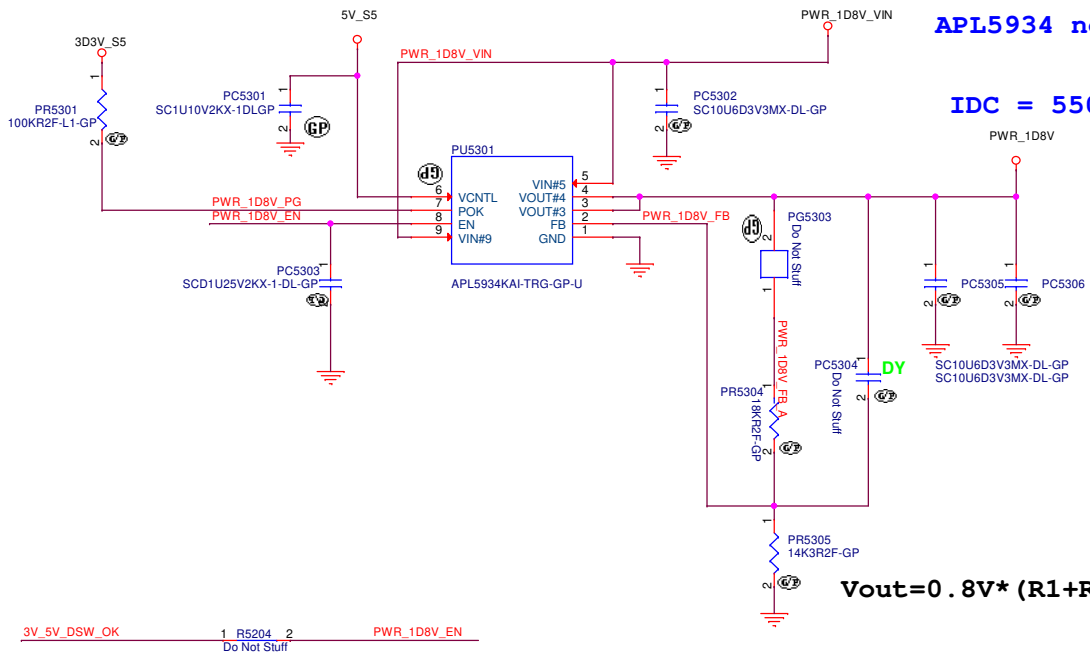
OFFPAGE_GAP



APL5934 for 1D8V


APL5934 need <1.8W

IDC = 550mA

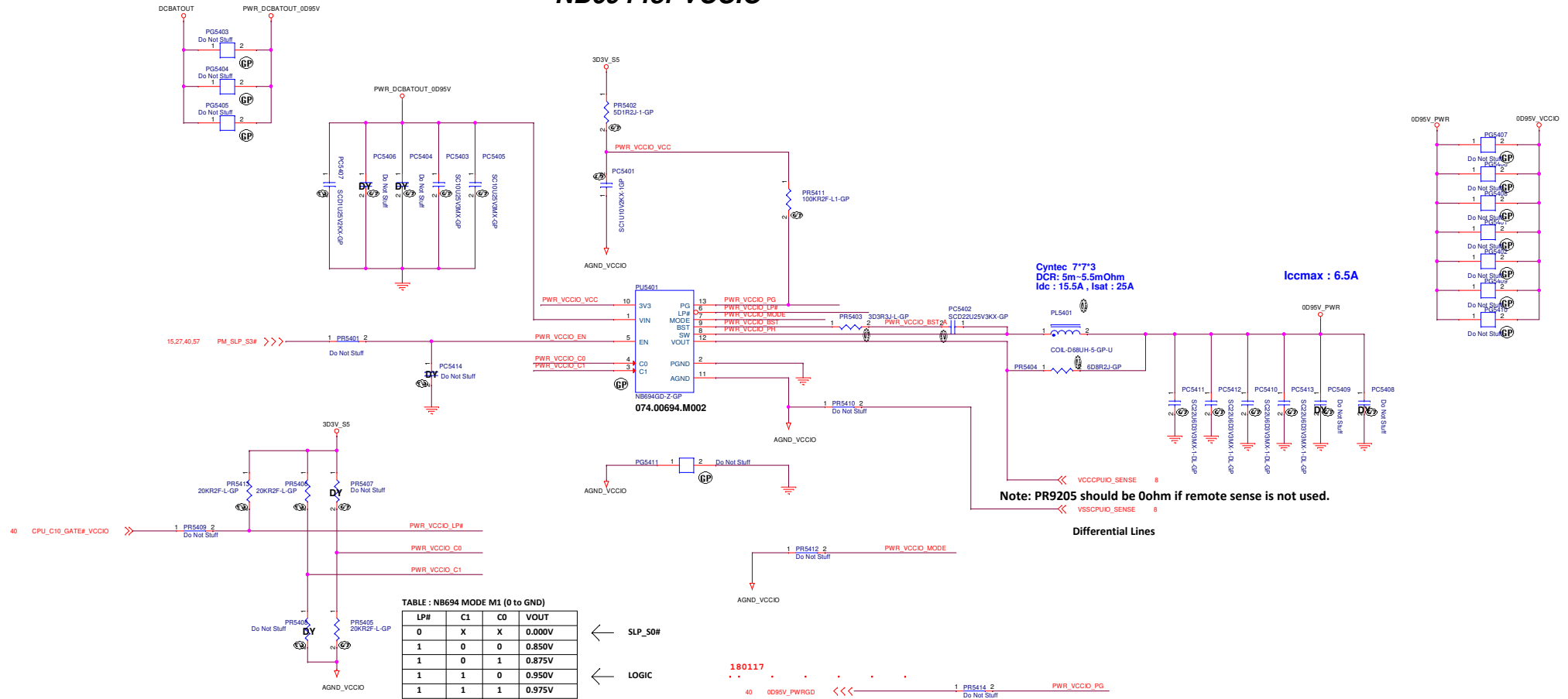


$$V_{out} = 0.8V * (R1 + R2) / R2$$

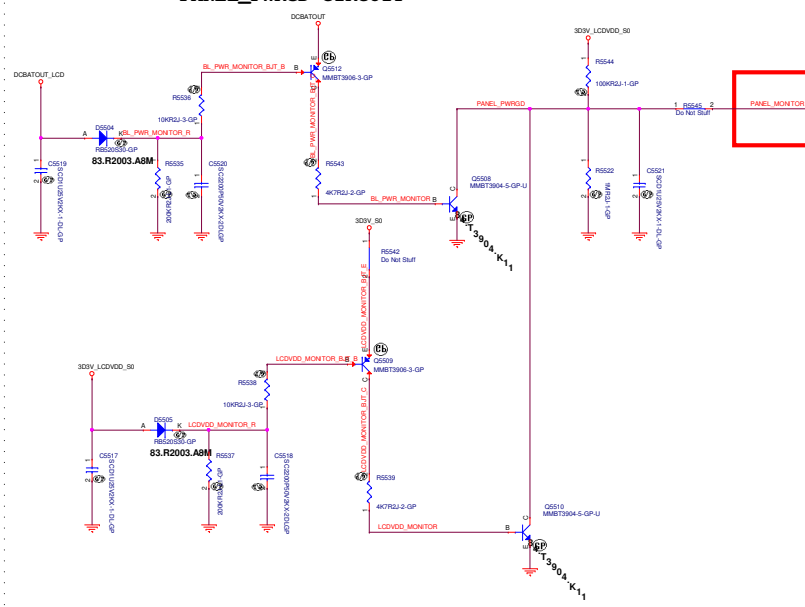
Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title POWER (APL5934 1D8V)			
Size A3	Document Number SELEK_N17P		Rev SD
Date: Wednesday, April 03, 2019 Sheet 1 of 1			

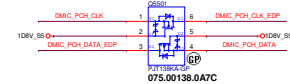
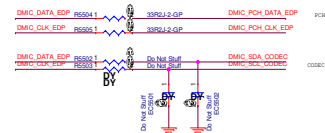
NB694 for VCCIO



LP#	C1	C0	VOUT
0	X	X	0.000V
1	0	0	0.850V
1	0	1	0.875V
1	1	0	0.950V
1	1	1	0.975V



Reserved for one time fuse: 69.43001.201
303V_S0



8

1

C

1

B

1

A

[illegible]

5

4

3

2

1

Selek CFLH N17P

Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **LCD/Inverter Connector**

Size

Custom

Document Number

SELEK N17P

Date: Wednesday, April 03, 2019

She

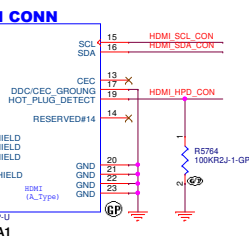
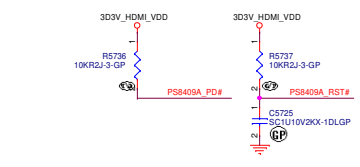
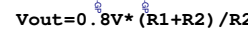
56

105

Rev	
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SD

the *Journal of the American Medical Association* (JAMA) and the *New England Journal of Medicine* (NEJM). The *Journal of the American Medical Association* (JAMA) is a peer-reviewed medical journal that publishes research, clinical practice, and medical education. The *New England Journal of Medicine* (NEJM) is a peer-reviewed medical journal that publishes research, clinical practice, and medical education. Both journals are highly respected and influential in the medical community.



5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title (Reserved)			
Size A	Document Number SELEK N17P		Rev SD
Date:	Wednesday, April 03, 2019	Sheet 58 of	105

D

C

B

A

Selek CFLH N17P



Wistron Corporation

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Taipei Hsien 221, Taiwan, R.O.C.

Title

(Reserved)

Size

A

Document Number

SELEK_N17P

Rev

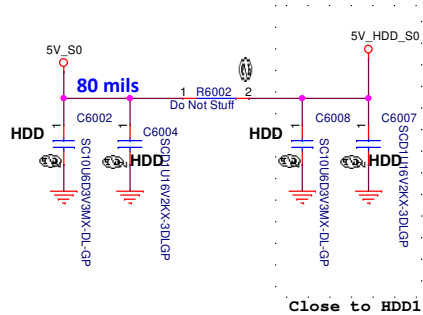
SD

Date: Wednesday, April 03, 2019

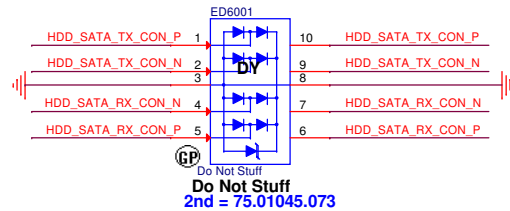
Sheet 59 of 105

Main Func = HDD

17 HDD_SATA_TX_P >>>
17 HDD_SATA_TX_N <<<
17 HDD_SATA_RX_N <<<
17 HDD_SATA_RX_P >>>
19 HDD_DEVSLP >>>
70 FFS_INT2_Q >>>
24.63 SSD_SCP# >>>



Layout Note:
Place near HDD1



SATA HDD Connector

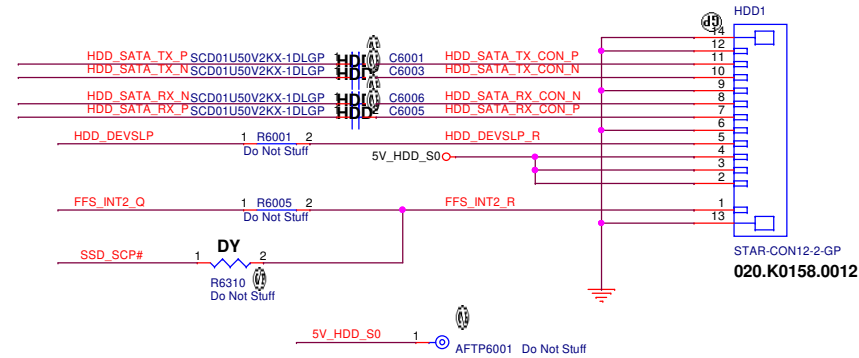


Table 16-5. SATA / PCI Express* Gen 2 and Gen 3 Capacitor Values

Condition	PCI Express* Gen 2 Only	PCI Express* Gen 3 Only	SATA Only	PCI Express* Gen 2/ SATA	PCI Express* Gen 3/ SATA
Processor Tx	100 nF	220 nF	10 nF	100 nF	220 nF
Processor Rx	None	None	10 nF ¹	None ²	None ³

Notes:

- This option supports all SATA devices. However, the Rx 10 nF capacitor can be removed if DC coupled ODDs / devices are NOT used.
- For PCIe* Gen 2/ SATA multiplexed configuration, motherboard Tx requires a 100 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- For PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Design Constraint: For PCIe* lane that needs to support either PCIe* Gen2 devices or PCIe* Gen3 devices, follow the PCIe* Gen 3/ SATA multiplexed configuration, motherboard Tx requires a 220 nF AC capacitor and NO AC capacitor is required for motherboard Rx channel. **This option DOES NOT support DC coupled ODDs / Devices.**
- Use a non-interleaved breakout to isolate Tx and Rx.

Selek CFLH N17P



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21F, 88, Sec.1, Hsin Tai Wuj Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

Title **SATA HDD**

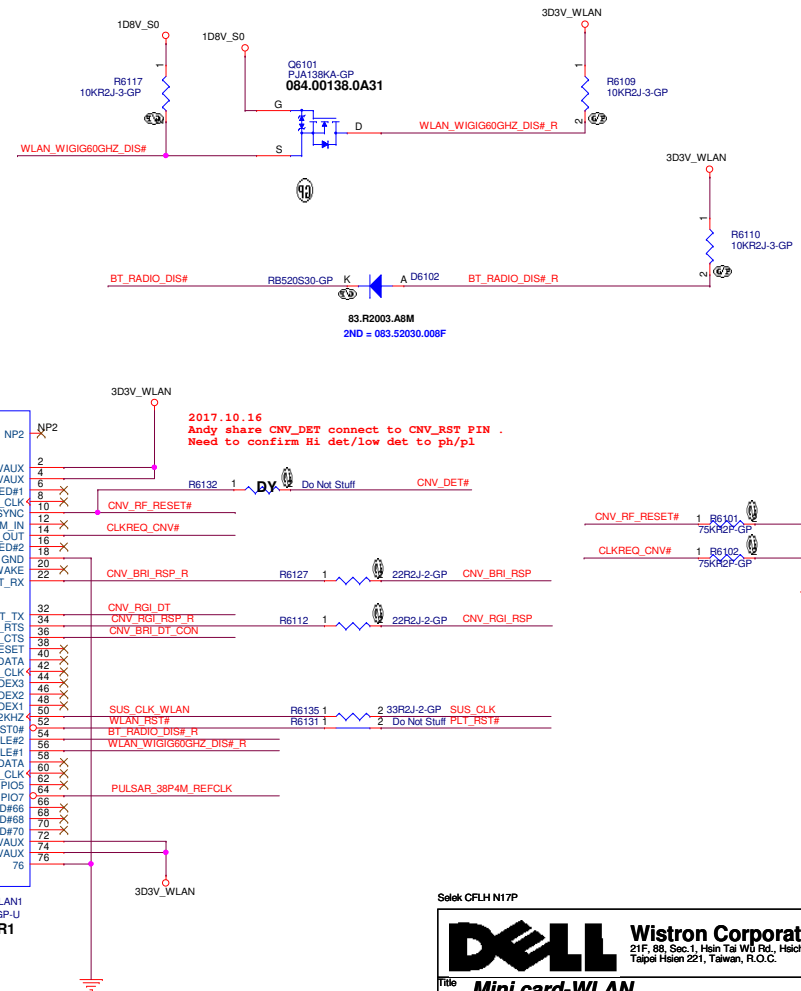
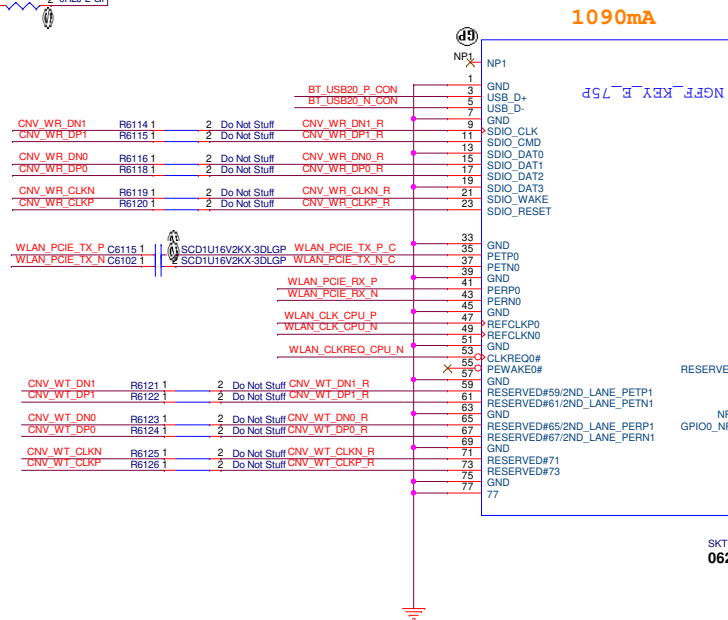
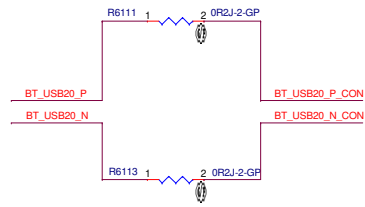
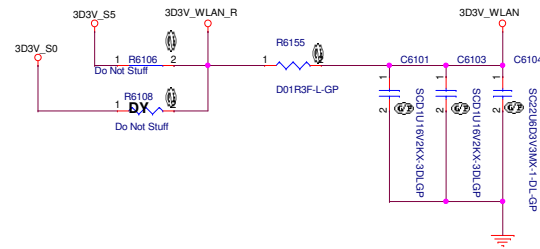
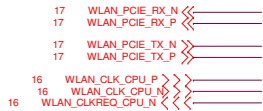
Size Custom Document Number **SELEK N17P**

Date: Wednesday, April 03, 2019

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Rev SD

Main Func = WLAN



Selekt CFLH N17P	
	Wistron Corporation 21F, 88, Sec. 1, Hsin Tsu Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
	Mini card-WLAN
Title _____	
Size _____ Custom _____	Document Number SELEK N17P
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Rev _____ SD	

SSID = Wireless

Selek CFLH N17P



Wistron Corporation

21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

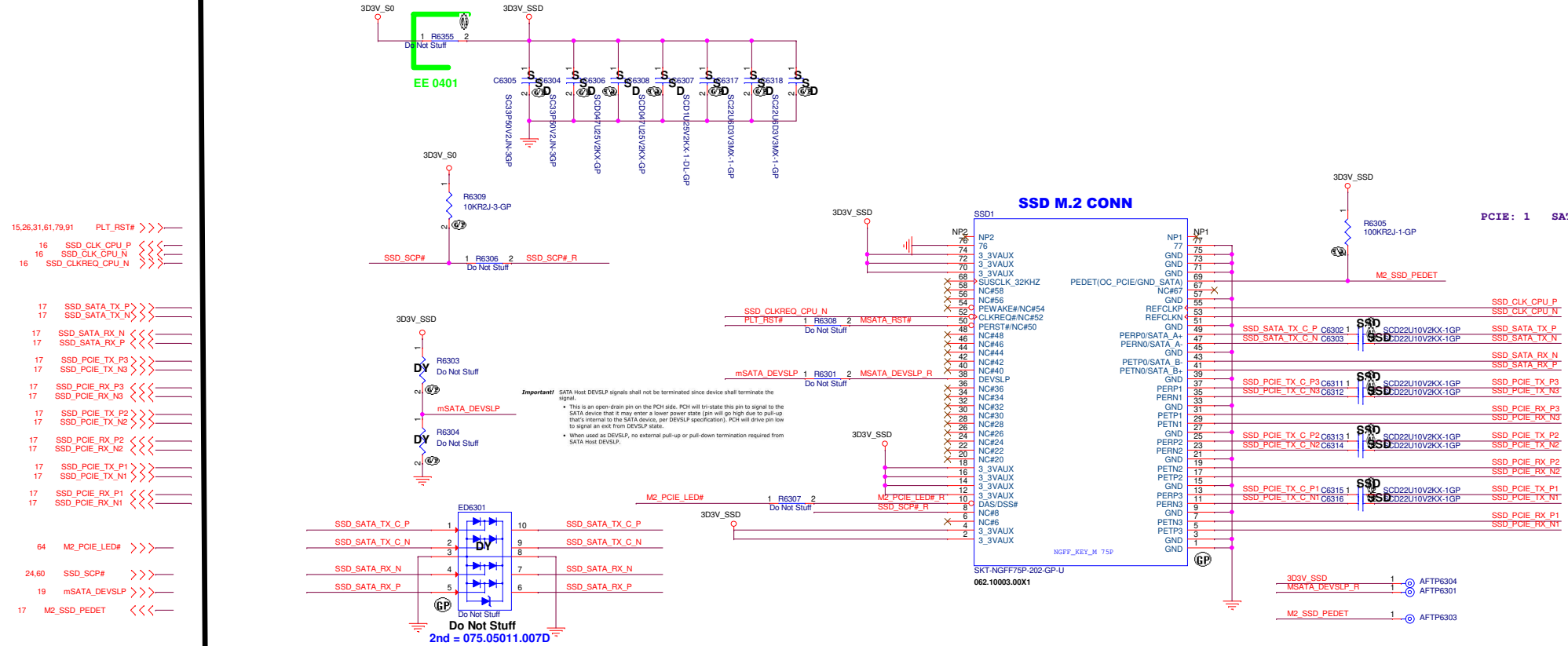
Title **(Reserved)WWAN**

Size A	Document Number SELEK N17P	Rev SD
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Date: Wednesday, April 03, 2019 Sheet 62 of 105

SSID = m-SATA

Mini Card Connector (NGFF m-SATA)



Selek CFLH N17P

DELL		Wistron Corporation	
21F, 88, Sec. 1, Hsin Tai Wb Rd., Hsichih, Taipei Hsein 221, Taiwan, R.O.C.			
Title SSD-NGFF			
Size	Document Number	Rev	
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Power button

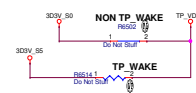
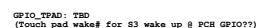
Battery LED2 (WHITE_LED)
Low activated from KBC GPIO

[illegible]

A2	SELEK N17P	SD
----	-------------------	-----------

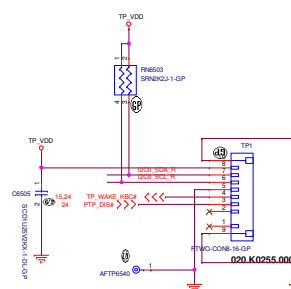
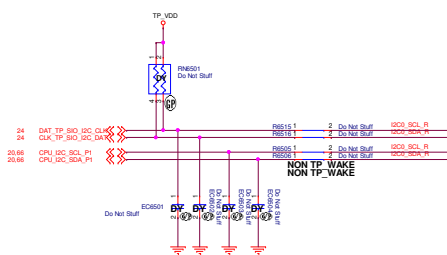
Rev
SD

Main Func = TPAD



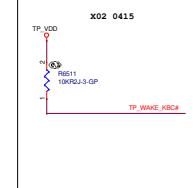
EC I2C

I2C



Change pindefine DWT1 0210 1334

Need to check if it is Active High or Active Low
~~and check if there is BH on TPAD side.~~



Pin number	Pin name
1	VDD
2	DAT (I2C)
3	CLK (I2C)
4	GND
5	ATTN
6	GPIO
7	DAT (PS2)
8	CLK (PS2)

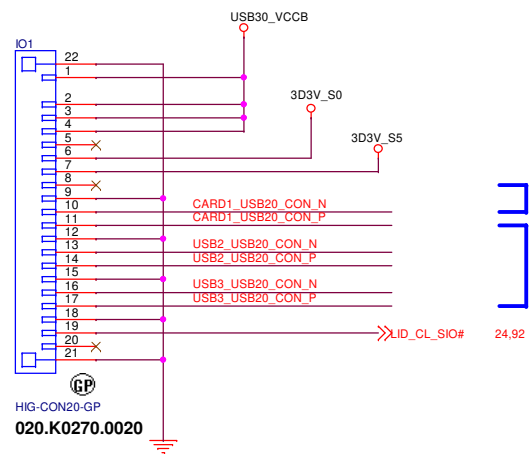


18 USB3_USB20_P
18 USB3_USB20_N
18 USB2_USB20_P
18 USB2_USB20_N

18 CARD1_USB20_N
18 CARD1_USB20_P

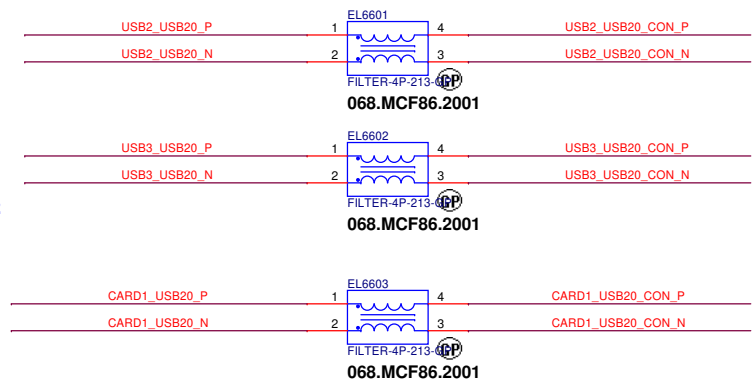
20.65 CPU_I2C_SCL_P1
20.65 CPU_I2C_SDA_P1

44 BT_PWR_IN-
44 BT_PWR_IN+

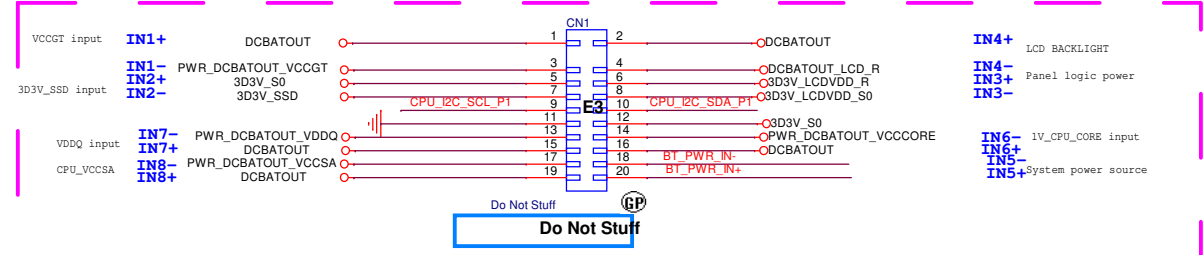


Cardreader


USB 2.0 Gen1 *2



E3 reserve



Selek CFLH N17P



Wistron Corporation
21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih,
Taipei Hsien 221, Taiwan, R.O.C.

IO Board Connector

Size
A3


Document Number
SELEK N17P

Rev
SD

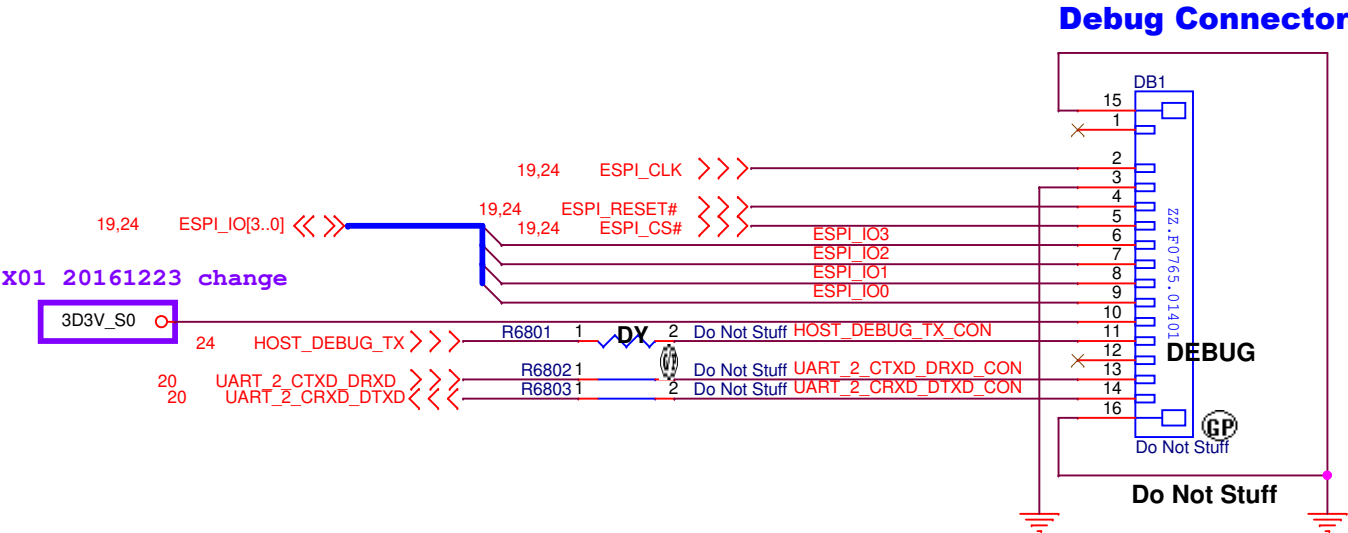
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Main Func = Hall Sensor


Selek CFLH N17P

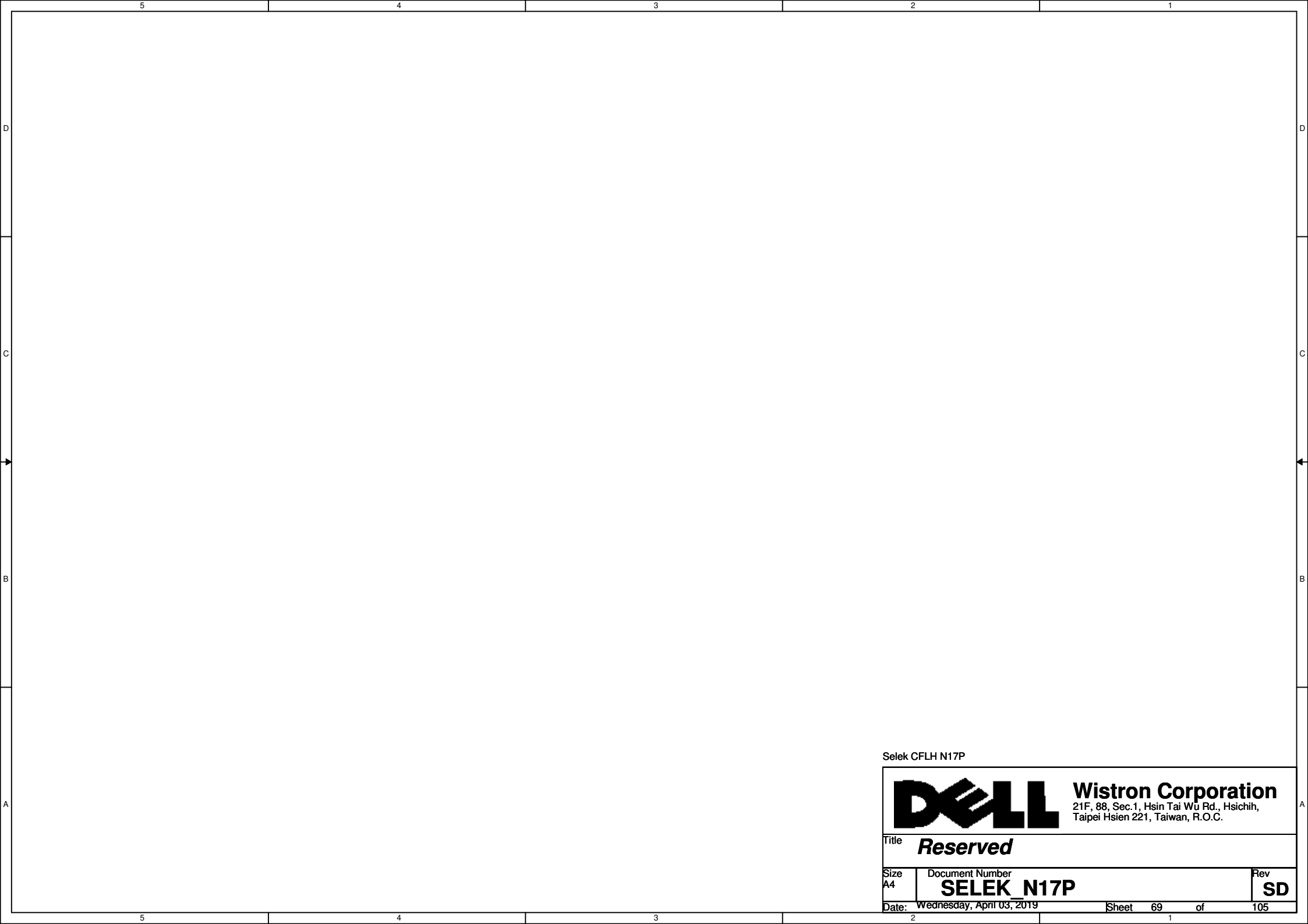
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Title Hall Sensor			
Size A	Document Number SELEK N17P		Rev SD
Date: Wednesday, April 03, 2019		Sheet 67 of	105

Main Func = Debug




Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.
Title Dubug connector		
Size A4	Document Number SELEK N17P	Rev SD
Date: Wednesday, April 03, 2019	Sheet 68	of 105



Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <i>Reserved</i>			
Size A4	Document Number SELEK N17P		Rev SD
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```

20      GSEN2_INT1_C  <<<<=====
20      GSEN2_INT2_C  <<<<=====

20  CPU_I2C_SDA_ISH  <<<<=====
20  CPU_I2C_SCL_ISH  <<<<=====

60      FFS_INT2_Q  <<<<=====

```

[illegible]

The schematic diagram illustrates the GSE2 input circuit. It features three input lines: GSE2_INT1_C (blue), GSE2_INT2_C (red), and INT2_SELECT (green). Each input line is connected to a pull-up resistor (R7005, R7006, and R7008 respectively) which is tied to a 1V supply. The inputs are connected to the FFS2 Not Stuff block. The output of the block is connected to the GSE2_INT1 and GSE2_INT2 outputs.

3D3V_S0

R7018
100KR2J-1-GP

Q7001

Do Not Stuff

Do Not Stuff

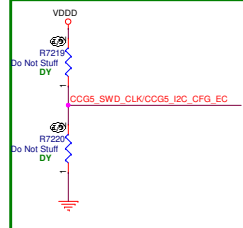
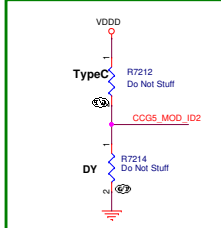
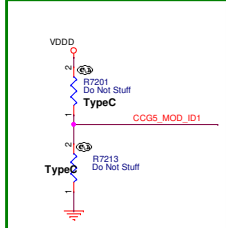
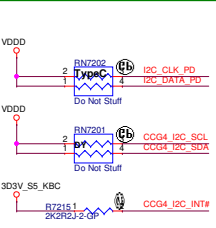
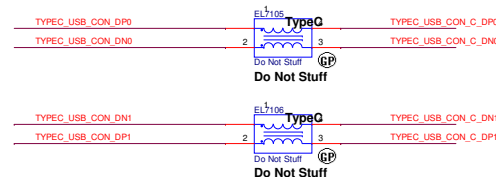
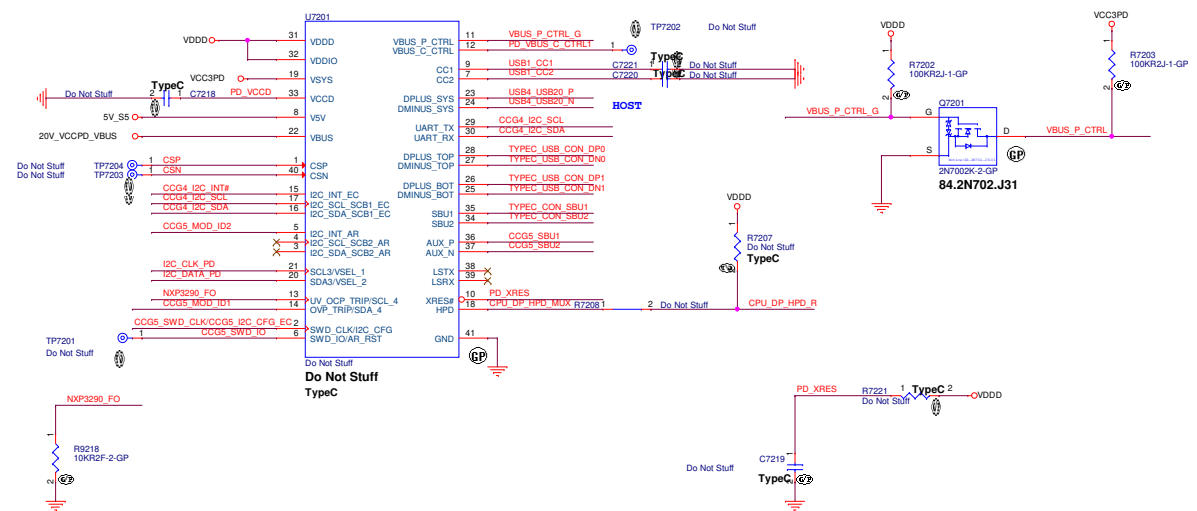
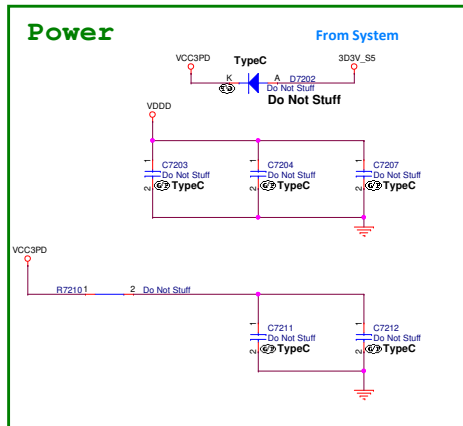
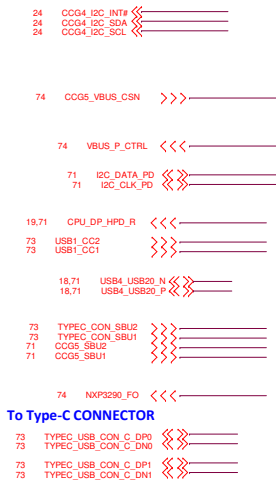
2nd = 075.67002.007

INT2_SELECT

FFS

FFS INT2 Q

Main Func = TYPEC CONTROLLER

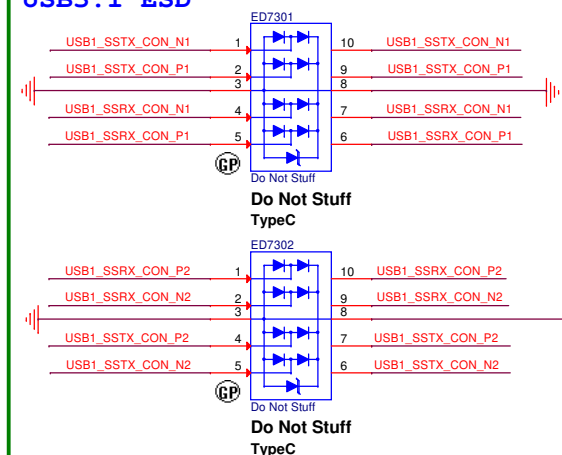


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Title: **USB3.0 PORT**

Size	Document Number	Rev
Custom	SELEK N17P	SD

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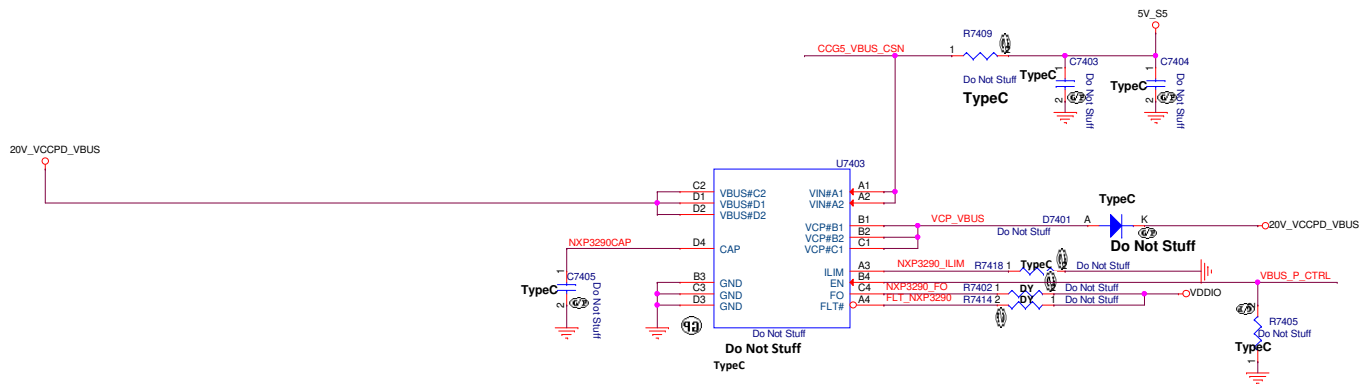


Main Func = LPS

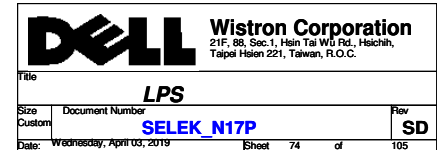
72 VBUS_P_CTRL >>>—

72 NXP3290_FO <<<—

72 CCG5_VBUS_CSN <<<—




Selek CFLH N17P

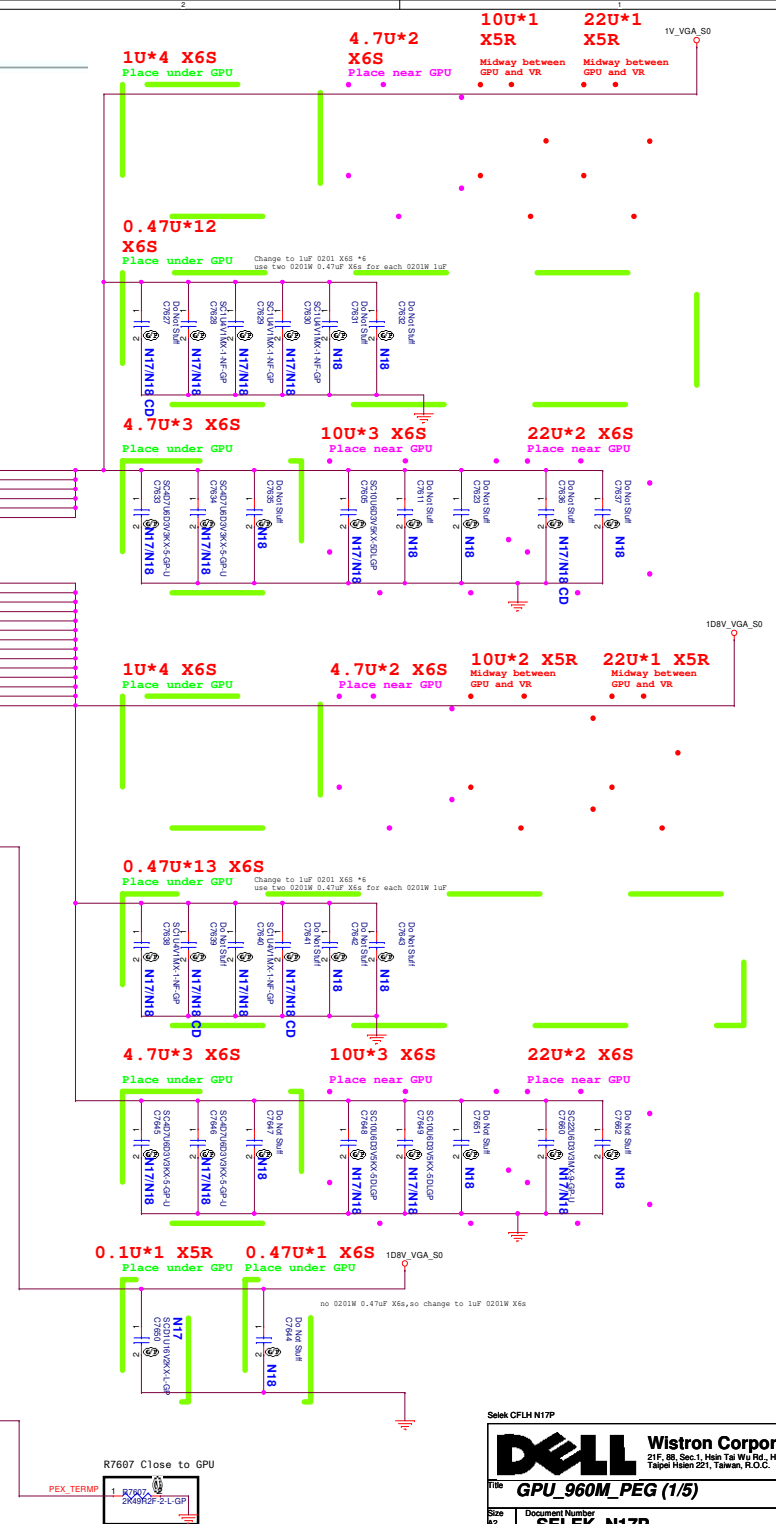
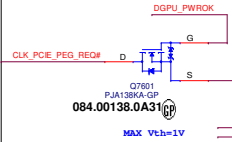


5	4	3	2	1
D				D
C				C
B				B
A				A
5	4	3	2	1

Selek CFLH N17P

		Wistron Corporation 21F, 88, Sec.1, Hsin Tai Wu Rd., Hsichih, Taipei Hsien 221, Taiwan, R.O.C.	
Title <i>(Reserved)Thunderbolt (5/5)</i>			
Size A	Document Number SELEK N17P		Rev SD
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GPU			Population		PEX_HVDD Supply Rail					
	Capacitor Type	Footprint	N18	N17	Location					
PEX_DVDD Supply Rail GB4C-128, GB4D-128	1.0 μF X6S		Q402 or Q301W	0	4	Under GPU				
	0.47 μF X6S	Q201W	12	0	Under GPU					
	4.7 μF X6S	Q603	0	2	Near GPU					
	4.7 μF X6S	Q603	0	2	Near GPU					
	4.7 μF X6S	Q603	0	2	Midway between GPU and power supply					
	10 μF XSR	R805	0	1	Midway between GPU and power supply					
	10 μF X6S	R805	3	0	Near GPU					
	22 μF XSR	R805	0	1	Midway between GPU and power supply					
	22 μF X6S	R805	2	0	Near GPU					
						Note: 1. Design may alternatively use two Q201W 0.47 μF X6S for each Q201W 1 μF.				





GPU	Type	Footprint	Population		Location
			N18	N17	
iFP_JOVDO Supply Rails	0.1 μ F	X70	0	6	Under GPU; 1 per ball
	0.47 μ F	X65	0	0	Under GPU; 1 per ball
	1.0 μ F	X65	0	3	Near GPU
	0.47 μ F	X65	0	0	Near GPU
	4.7 μ F	X65	0	3	Near GPU
	150 Ω \pm 10%	0603	0	0	Near GPU

Note



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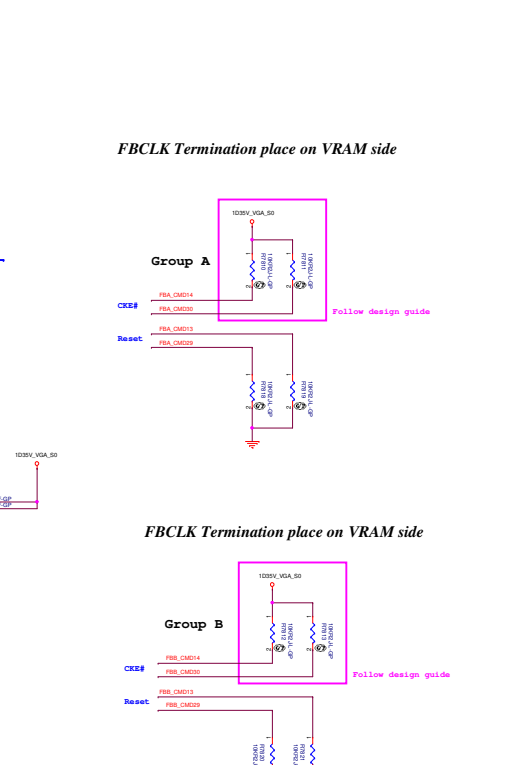
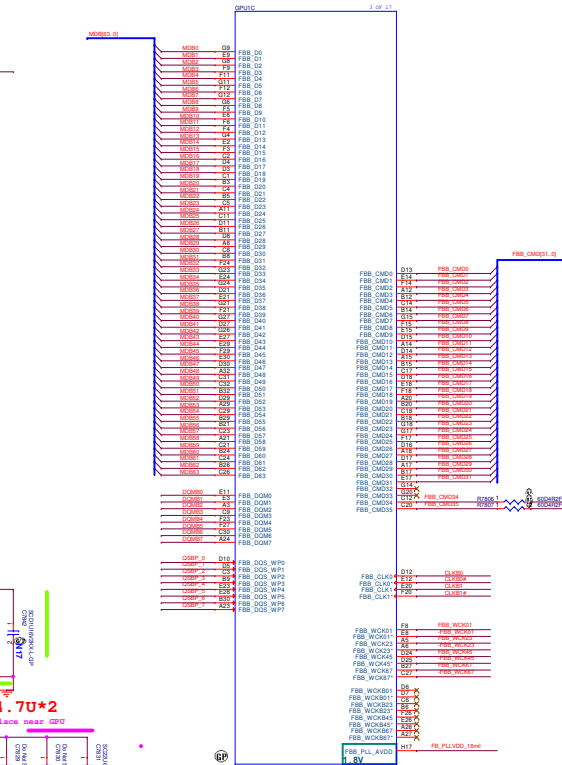
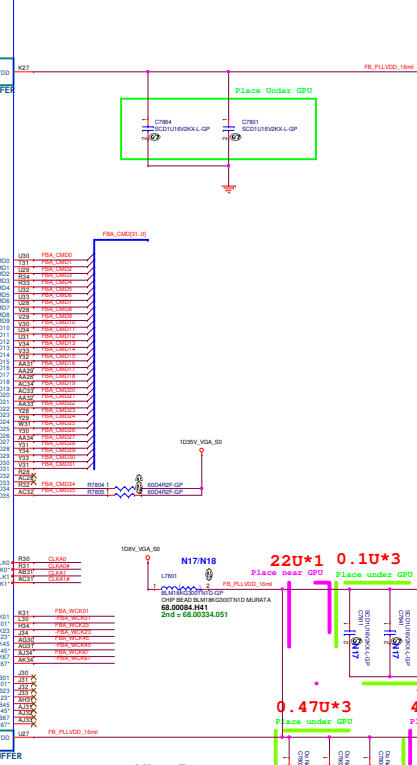
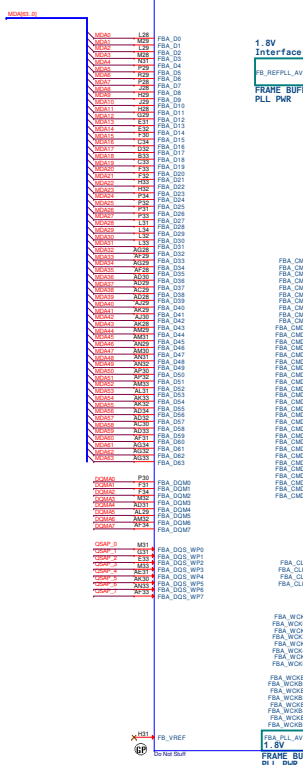


Table 4. Frame Buffer PLL Decoupling and Filtering

GPU	Capacitor Type	Footprint	N18	N17	Location
FBCLK_0	0.1 μF	0402	0	1	Under GPU
FBCLK_1	0.1 μF	0402	1	0	Under GPU
FBCLK_2	0.1 μF	0402	2	0	Under GPU
FBCLK_3	0.1 μF	0402	3	0	Under GPU
FBCLK_4	0.1 μF	0402	4	0	Under GPU
FBCLK_5	0.1 μF	0402	5	0	Under GPU
FBCLK_6	0.1 μF	0402	6	0	Under GPU
FBCLK_7	0.1 μF	0402	7	0	Under GPU
FBCLK_8	0.1 μF	0402	8	0	Under GPU
FBCLK_9	0.1 μF	0402	9	0	Under GPU
FBCLK_10	0.1 μF	0402	10	0	Under GPU
FBCLK_11	0.1 μF	0402	11	0	Under GPU
FBCLK_12	0.1 μF	0402	12	0	Under GPU
FBCLK_13	0.1 μF	0402	13	0	Under GPU
FBCLK_14	0.1 μF	0402	14	0	Under GPU
FBCLK_15	0.1 μF	0402	15	0	Under GPU

Notes:

- Design may alternatively use two 0201W 0.47 μF X65 for each 0201W 1 μF.

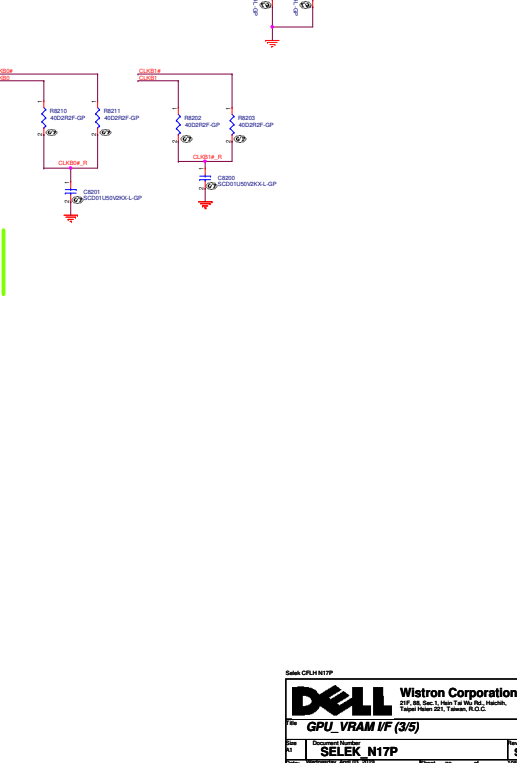
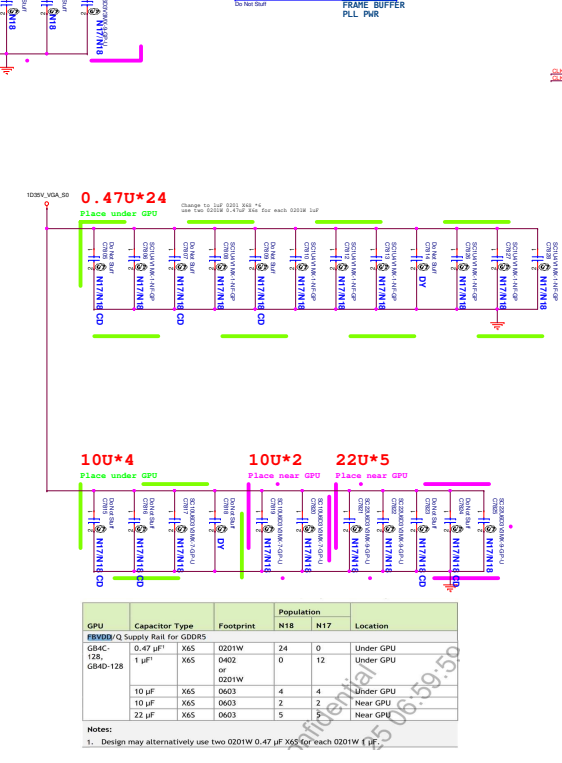
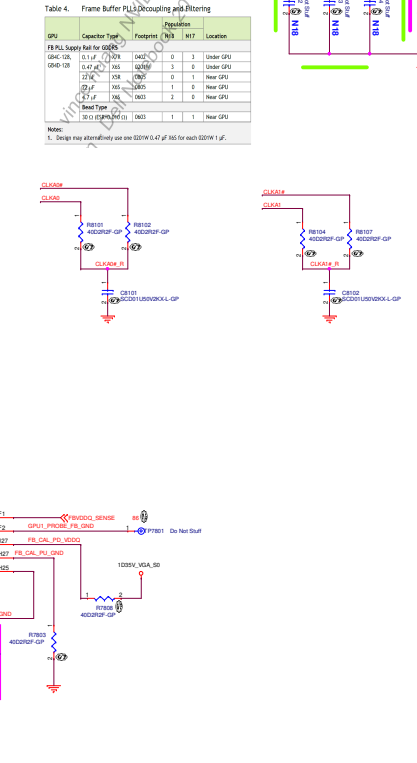
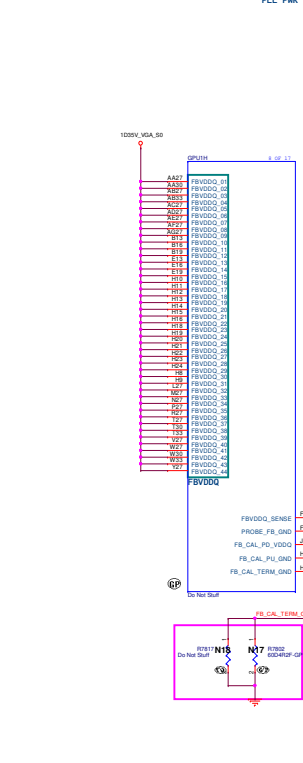


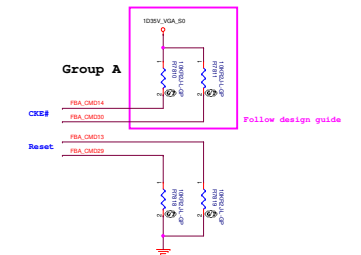
Table 5. Frame Buffer PLL Decoupling and Filtering

GPU	Capacitor Type	Footprint	N18	N17	Location
FBCLK_0	0.1 μF	0402	0	1	Under GPU
FBCLK_1	0.1 μF	0402	1	0	Under GPU
FBCLK_2	0.1 μF	0402	2	0	Under GPU
FBCLK_3	0.1 μF	0402	3	0	Under GPU
FBCLK_4	0.1 μF	0402	4	0	Under GPU
FBCLK_5	0.1 μF	0402	5	0	Under GPU
FBCLK_6	0.1 μF	0402	6	0	Under GPU
FBCLK_7	0.1 μF	0402	7	0	Under GPU
FBCLK_8	0.1 μF	0402	8	0	Under GPU
FBCLK_9	0.1 μF	0402	9	0	Under GPU
FBCLK_10	0.1 μF	0402	10	0	Under GPU
FBCLK_11	0.1 μF	0402	11	0	Under GPU
FBCLK_12	0.1 μF	0402	12	0	Under GPU
FBCLK_13	0.1 μF	0402	13	0	Under GPU
FBCLK_14	0.1 μF	0402	14	0	Under GPU
FBCLK_15	0.1 μF	0402	15	0	Under GPU

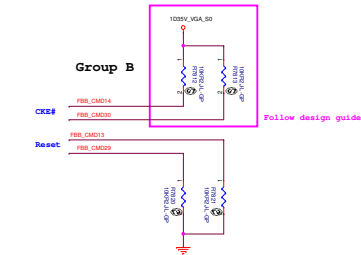
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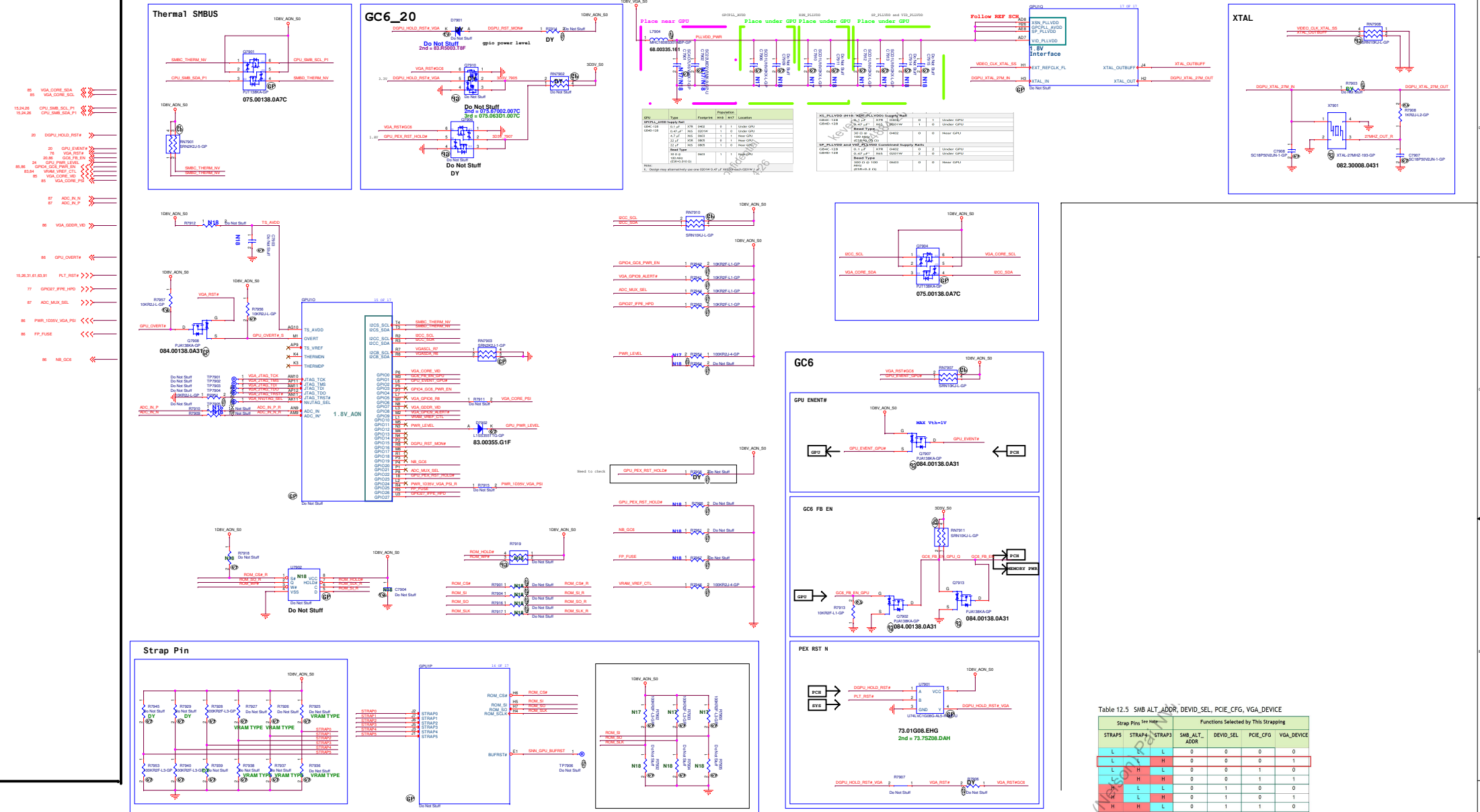
- Design may alternatively use two 0201W 0.47 μF X65 for each 0201W 1 μF.

FBCLK Termination place on VRAM side



FBCLK Termination place on VRAM side





Strap2	Strap1	Strap0	Vendor	Vendor number	wistron P/N	Strap	GPU
L	L	L	Samsung	K4G80325FB-HC28	N1MMHSA	0x0	N17P
L	L	H	Micron	MT51J256M32HF-80-B	MHVDXSA	0x1	N18P
L	H	L	Hynix	H5GCS824AJR-R2C	GVK6KSA	0x2	N18P
L	L	L	Samsung	K4G80325FC-HC25	J62CNSA	0x0	N18P

Table 3. N17P-G1/G0/G0-K1 GDDR5 Recommended Memories

Memory Density	Memory Configuration	Manufacturer	Part Number	Die Revision	Memory Speed Grade	Date Code	Strap	Strap Plan	Status
8 Gb	256Mx32	Samsung	K4G80325FB-HC28	B-die	7 Gbps	N/A	0x0	Full	Production candidate
		Micron	MT51J256M32HF-80-B	A-die	7 Gbps	N/A	0x1	Full	Production candidate
		Micron	MT51J256M32HF-80-B	A-die	8 Gbps	N/A	0x1	Full	Production candidate
		Hynix	H5GCS824AJR-R2C	B-die	7 Gbps	N/A	0x2	Full	Production candidate
		Hynix	H5GCS824AJR-R2C	B-die	8 Gbps	N/A	0x2	Full	Production candidate
		Micron	MT51J256M32HF-80-B	B-die	7 Gbps	N/A	0x1	Full	Production candidate
		Micron	MT51J256M32HF-80-B	B-die	8 Gbps	N/A	0x1	Full	Production candidate
		Hynix	H5GCS824AJR-R2C	A-die	7 Gbps	N/A	0x2	Full	Production candidate
		Hynix	H5GCS824AJR-R2C	A-die	8 Gbps	N/A	0x2	Full	Production candidate

Table 4. N18P-G0 GDDR5 Recommended Memories

Memory Density	Memory Configuration	FBVDD/Q	Vendor	Manufacturer Part Number	Die Revision	Memory Speed Grade	Date Code	Strap	Strap Plan	Status
8 Gb	256Mx32	1.35V and 1.5V ¹	Micron	MT51J256M32HF-80-B	B-die	8 Gbps	N/A	0x1	Full	Production candidate
		1.35V	Hynix	H5GCS824AJR-R2C	A-die	8 Gbps	N/A	0x2	Full	Production candidate
		1.35V and 1.5V ¹	Samsung	K4G80325FC-HC25	C-die	8 Gbps	N/A	0x0	Full	Production candidate

Strap Pins see note				RANCIF Testing Number				Strap Pins see note				RANCIF Setting Number			
STRAP2		STRAP1		STRAP0		STRAP0		STRAP2		STRAP1		STRAP0		STRAP0	
(see Memory SVL for memory config corresponding to these numbers)								(see Memory SVL for memory config corresponding to these numbers)							
L	L	L	L	L	L	L	L	0	000001	M	M	M	M	14	000007
L	L	L	L	L	L	L	H	1	000011	M	M	L	L	15	00000F
L	L	L	L	L	H	L	L	2	000021	M	L	L	M	16	000015
L	L	L	L	L	H	H	L	3	000031	M	L	L	M	17	00001D
L	L	L	L	L	H	H	H	4	000041	M	L	L	M	18	000023
L	L	L	L	H	L	L	L	5	000051	M	L	M	M	19	00002B
L	L	L	L	H	L	H	L	6	000061	M	L	M	M	20	000032
L	L	L	L	H	L	H	H	7	000071	M	L	M	M	21	00003A
L	L	L	H	L	L	L	L	8	000081	M	L	M	L	22	000042
L	L	L	H	L	L	H	L	9	000091	M	L	M	L	23	00004A
L	L	L	H	L	L	H	H	10	000101	M	L	M	L	24	000052
L	L	L	H	L	H	L	L	11	000111	M	L	M	L	25	00005A
L	L	L	H	L	H	H	L	12	000121	M	L	M	L	26	000062
L	L	L	H	L	H	H	H	13	000131	M	L	M	L	27	00006A
L	L	H	L	L	L	L	L	14	000141	M	M	M	M	28	00007F

100U*21
Place under GPU

100U*13
Place under GPU

10U*13
Place under GPU

0.47U*26
Place under GPU

100U*11
Place near GPU

22U*5
Place near GPU

22U*10
Place near GPU

3300U*1 4.7U*2
Place near GPU

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

Table 2. NVDD Decoupling and Filtering

GPU	Capacitor Type	Footprint	Population	N18	N17	Location
NVDD Supply Net						
GB4C-128, GB4D-128	10 μ F	X65	0603	34	21	Under GPU
	1 μ F ¹	X65	0402 or 0201W	0	13	Under GPU
	0.47 μ F ¹	X65	0402 or 0201W	26	0	Under GPU
	10 μ F	X65	0603	0	11	Near GPU
	22 μ F	X65	0805	15	10	Near GPU
	4.7 μ F	X65	0603	0	2	Near GPU
	330 μ F	POS	7343	0	1	Near GPU

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

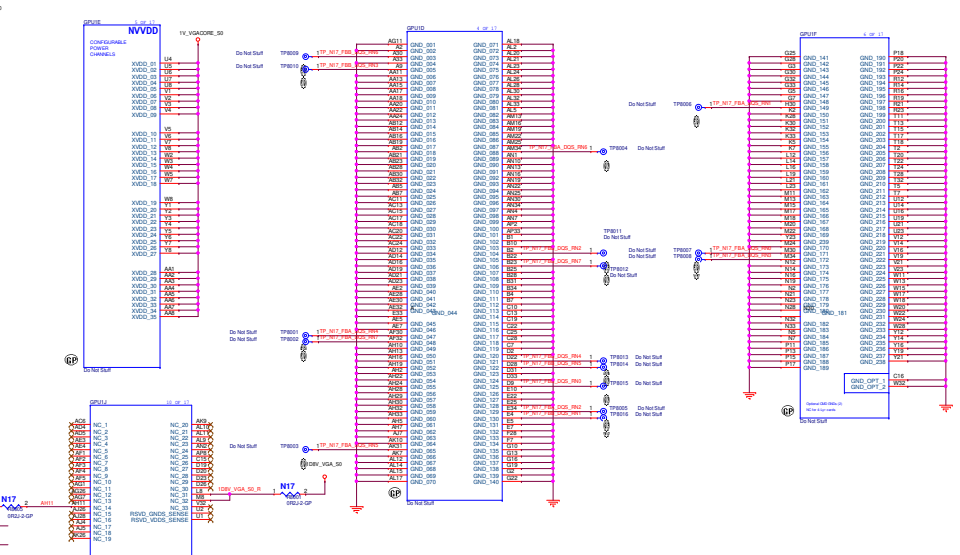
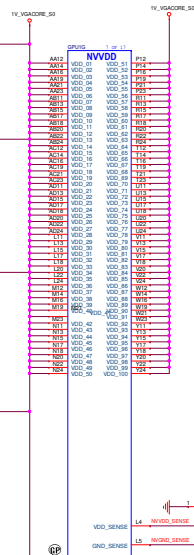


Table 9. VDD_AON and VDD_MAIN Decoupling

GPU	Capacitor Type	Footprint	Population	N18	N17	Location
N17 VDD18 (N18 NC) Supply Rail						
GB4C-128, GB4D-128	0.1 μ F	X7R	0402	N/A	2	Under GPU
	1.0 μ F	X65	0603	N/A	1	Near GPU
	4.7 μ F	X65	0603	N/A	1	Near GPU
1V8_AON Supply Rail						
GB4C-128, GB4D-128	0.1 μ F	X7R	0402	0	2	Under GPU
	0.47 μ F	X65	0201W	4	0	Under GPU
	1.0 μ F	X65	0402 or 0201W	0	1	Near GPU
	0.47 μ F ¹	X65	0201W	6	0	Near GPU
	4.7 μ F	X65	0603	3	1	Near GPU

Note:

1. Design may alternatively use two 0201W 0.47 μ F X65 for each 0201W 1 μ F.

78 MDA[63..0] <<>>
78 FBA_CMD[31..0] <<>>

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78 DQMA1 <>>
78 DQMA2 <>>
78 DQMA3 <>>
78 DQMA4 <>>
78 DQMA5 <>>
78 DQMA6 <>>
78 DQMA7 <>>

78 QSAP_0 <>>
78 QSAP_1 <>>
78 QSAP_2 <>>
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78 QSAP_4 <>>
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78 FBA_WCK01 <>>
78 -FBA_WCK01 <>>
78 FBA_WCK23 <>>
78 -FBA_WCK23 <>>
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78 -FBA_WCK45 <>>
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78 CLKA1 <>>
78 CLKA1# <>>

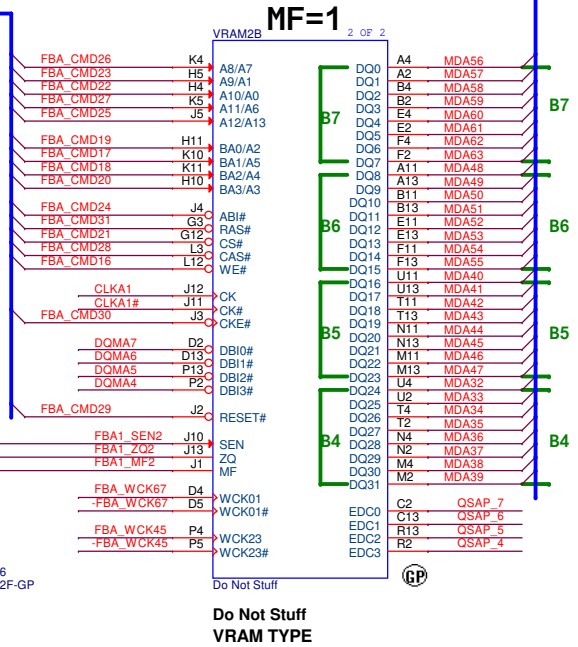
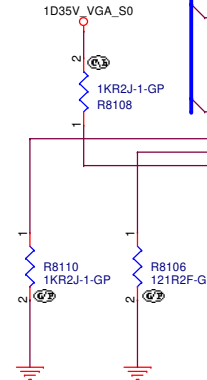
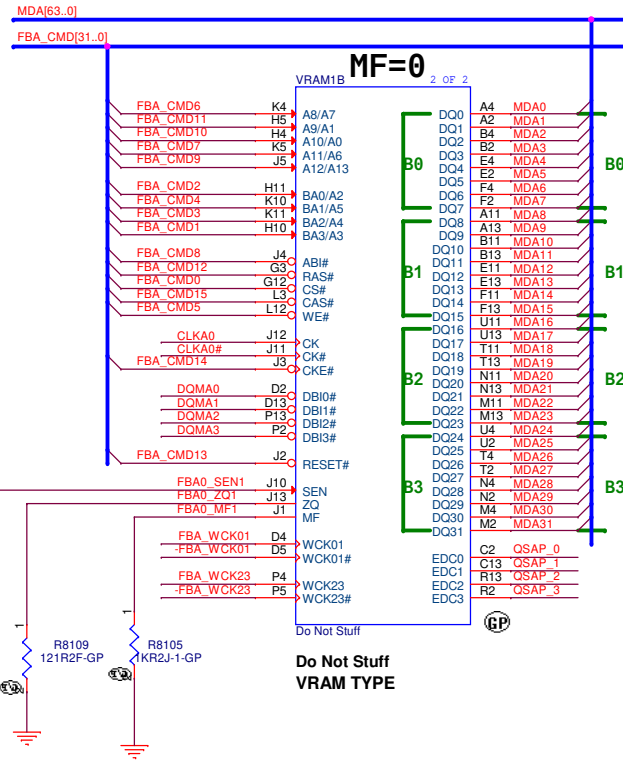


Table 9.4 GDDR5 Command Mapping (GB4C-128 packages)

Command Ball on GPU		DRAM Signal Definition
For DRAM(s) tied to DQ[31:0]	For DRAM(s) tied to DQ[63:32]	
FBA_CMD0	FBA_CMD16	CS*
FBA_CMD1	FBA_CMD17	A3_BA3
FBA_CMD2	FBA_CMD18	A2_BA0
FBA_CMD3	FBA_CMD19	A4_BA2
FBA_CMD4	FBA_CMD20	A5_BA1
FBA_CMD5	FBA_CMD21	WE*
FBA_CMD6	FBA_CMD22	A7_A8
FBA_CMD7	FBA_CMD23	A6_A11
FBA_CMD8	FBA_CMD24	ABI*
FBA_CMD9	FBA_CMD25	A12_RFU
FBA_CMD10	FBA_CMD26	A0_A10
FBA_CMD11	FBA_CMD27	A1_A9
FBA_CMD12	FBA_CMD28	RAS*
FBA_CMD13	FBA_CMD29	RST*
FBA_CMD14	FBA_CMD30	CKE*
FBA_CMD15	FBA_CMD31	CAS*

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78 MDB[3..0] <<<>>>

78 FBB_CMD[31..0] <<<>>>

78 DQMB0 <>>>

78 DQMB1 <>>>

78 DQMB2 <>>>

78 DQMB3 <>>>

78 DQMB4 <>>>

78 DQMB5 <>>>

78 DQMB6 <>>>

78 DQMB7 <>>>

78 QSBP_0 <>>>

78 QSBP_1 <>>>

78 QSBP_2 <>>>

78 QSBP_3 <>>>

78 QSBP_4 <>>>

78 QSBP_5 <>>>

78 QSBP_6 <>>>

78 QSBP_7 <>>>

78 FBB_WCK01 <>>>

78 FBB_WCK01# <>>>

78 FBB_WCK23 <>>>

78 FBB_WCK23# <>>>

78 FBB_WCK45 <>>>

78 FBB_WCK45# <>>>

78 FBB_WCK67 <>>>

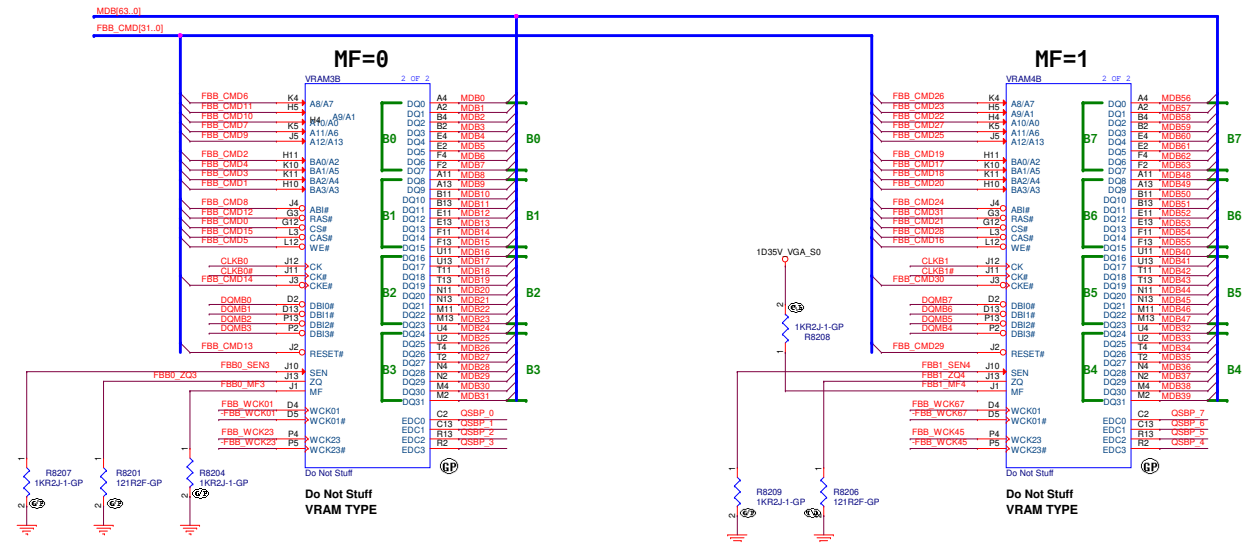
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78 CLKB0 <>>>

78 CLKB0# <>>>

78 CLKB1 <>>>

78 CLKB1# <>>>

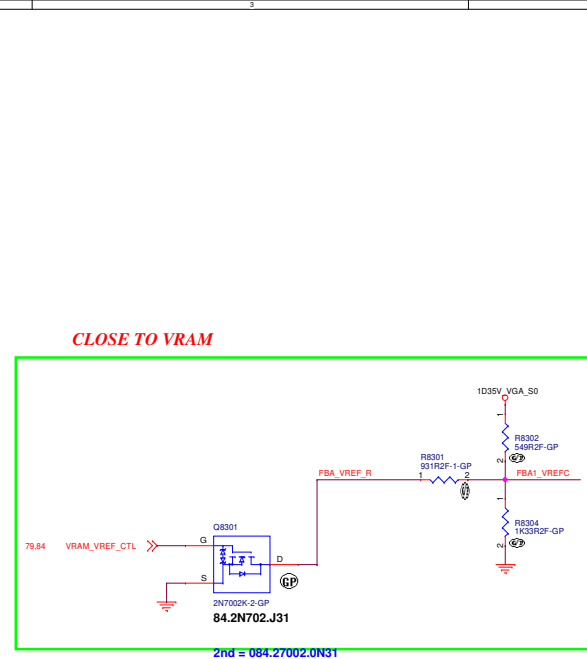


GDDR5 Data Mapping									
BYTE0 (BYTE4)		BYTE1 (BYTE5)		BYTE2 (BYTE6)		BYTE3 (BYTE7)			
MF=0	MF=1	MF=0	MF=1	MF=0	MF=1	MF=0	MF=1		
DQ0	DQ24 (DQ02)	DQ8	DQ16 (DQ08)	DQ16	DQ8 (DQ04)	DQ24	DQ0 (DQ06)	DQ0	DQ05
DQ1	DQ25 (DQ03)	DQ9	DQ17 (DQ09)	DQ17	DQ9 (DQ05)	DQ25	DQ1 (DQ07)	DQ1	DQ05
DQ2	DQ26 (DQ04)	DQ10	DQ18 (DQ10)	DQ18	DQ10 (DQ06)	DQ26	DQ2 (DQ08)	DQ2	DQ05
DQ3	DQ27 (DQ05)	DQ11	DQ19 (DQ11)	DQ19	DQ11 (DQ07)	DQ27	DQ3 (DQ09)	DQ3	DQ05
DQ4	DQ28 (DQ06)	DQ12	DQ20 (DQ12)	DQ20	DQ12 (DQ08)	DQ28	DQ4 (DQ10)	DQ4	DQ06
DQ5	DQ29 (DQ07)	DQ13	DQ21 (DQ13)	DQ21	DQ13 (DQ09)	DQ29	DQ5 (DQ11)	DQ5	DQ06
DQ6	DQ30 (DQ08)	DQ14	DQ22 (DQ14)	DQ22	DQ14 (DQ10)	DQ30	DQ6 (DQ12)	DQ6	DQ06
DQ7	DQ31 (DQ09)	DQ15	DQ23 (DQ15)	DQ23	DQ15 (DQ11)	DQ31	DQ7 (DQ13)	DQ7	DQ06
DBI0	DBI3 (DB04)	DBI1	DBI2 (DB05)	DBI2	DBI1 (DB06)	DBI3	DBI0 (DB07)	DBI0	DB08
EDC0	EDC3 (EDC4)	EDC1	EDC2 (EDC5)	EDC2	EDC1 (EDC6)	EDC3	EDC0 (EDC7)	EDC0	ED09
GDDR5 CLK Mapping									
WCK01	WCK23 (WCK45)			WCK23	WCK01 (WCK67)				
WCK01#	WCK23# (WCK45#)			WCK23#	WCK01# (WCK67#)				
CK	CK								
CK#	CK#								
Others									
MF	MF	SEN	SEN						
ZQ	ZQ	RESET#	RESET#						

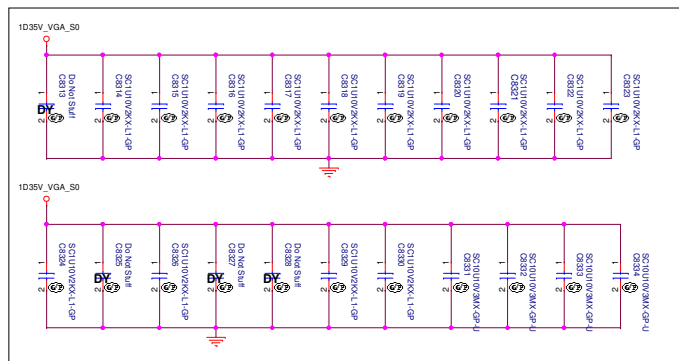
Table 9.4 GDDR5 Command Mapping (GB4C-128 packages)

Command Ball on GPU		DRAM Signal Definition
For DRAM(s) tied to DQ[31:0]	For DRAM(s) tied to DQ[63:32]	
FBA_CMD0	FBA_CMD16	CS*
FBA_CMD1	FBA_CMD17	A3_BA3
FBA_CMD2	FBA_CMD18	A2_BA0
FBA_CMD3	FBA_CMD19	A4_BA2
FBA_CMD4	FBA_CMD20	A5_BA1
FBA_CMD5	FBA_CMD21	WE*
FBA_CMD6	FBA_CMD22	A7_A8
FBA_CMD7	FBA_CMD23	A6_A11
FBA_CMD8	FBA_CMD24	AB1*
FBA_CMD9	FBA_CMD25	A12_RFU
FBA_CMD10	FBA_CMD26	A0_A10
FBA_CMD11	FBA_CMD27	A1_A9
FBA_CMD12	FBA_CMD28	RAS*
FBA_CMD13	FBA_CMD29	RST*
FBA_CMD14	FBA_CMD30	CKE*
FBA_CMD15	FBA_CMD31	CAS*

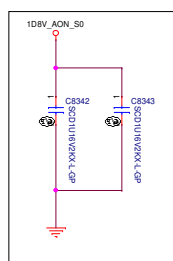
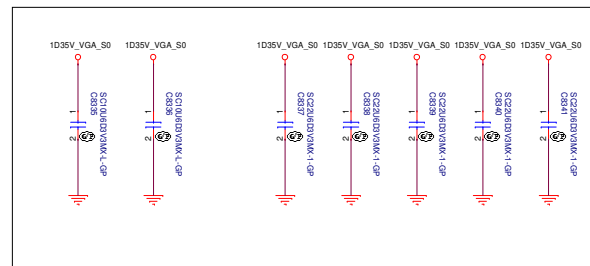
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FOR VRAM1/VRAM2



CLOSE TO THE MEMORY



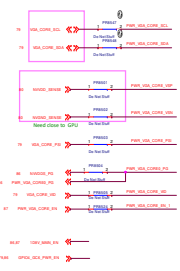


Table 7.8 PWM-VID Spec and Component Values

PWM-VID Specification		
Item	Unit	Config
Number of Voltage Levels N	level	160
PWM Frequency F _{PWM}	MHz	475
PWM Minimum Pulse Width T _{PWM}	ns	9.28
VID Transient Time T	us	1000
Component Value		
R1 (Ω)	Ω	4.75
R2 (Ω)	Ω	20.5
R3 (Ω)	Ω	4.32
R4 (Ω)	Ω	16.5
R5 (Ω)	Ω	8.0
C	μF	0.01

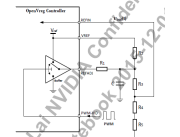
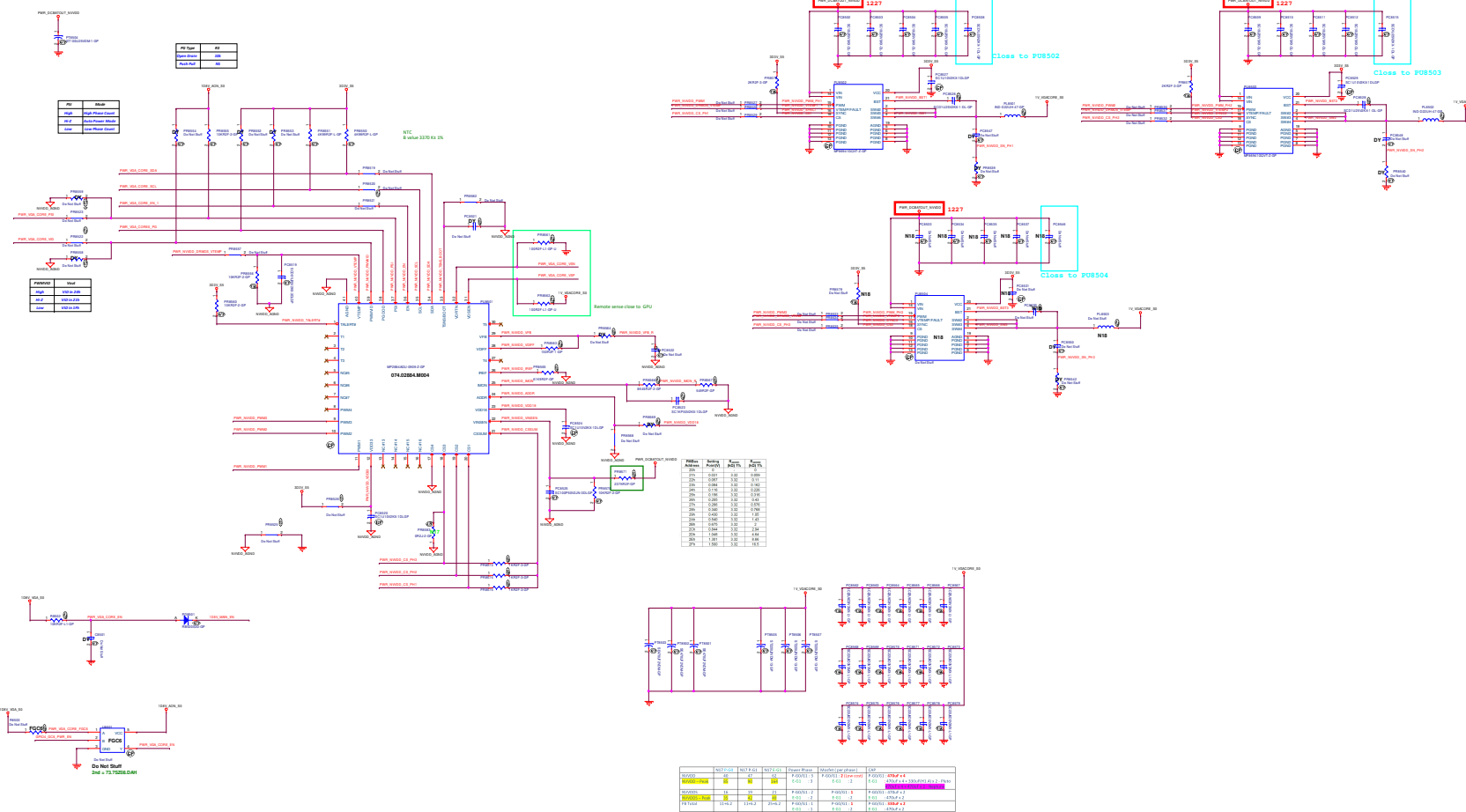
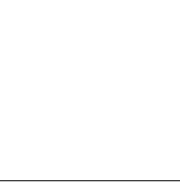


Table 7.9 PWM-VID Spec and Component Values

PWM-VID Specification		
Item	Unit	Config
V _{min}	V	0.3
V _{max}	V	1.3
V _{boot}	V	0.8
Voltage Step Width	mV	6.25
Number of Voltage Levels N	level	160
PWM Frequency F _{PWM}	MHz	475
PWM Minimum Pulse Width T _{PWM}	ns	9.28
VID Transient Time T	us	1000
Component Value		
R1 (Ω)	Ω	6.19
R2 (Ω)	Ω	20.5
R3 (Ω)	Ω	4.32
R4 (Ω)	Ω	16.5
R5 (Ω)	Ω	8.0
C	μF	0.01




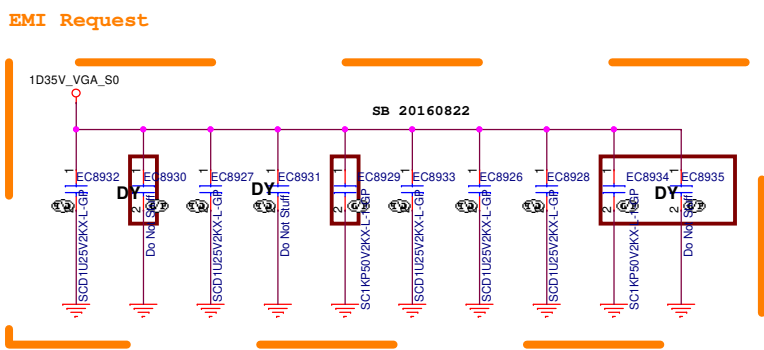
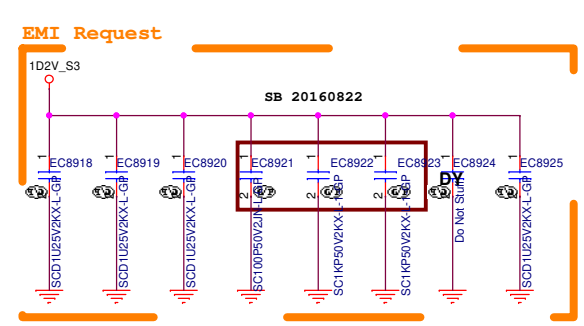
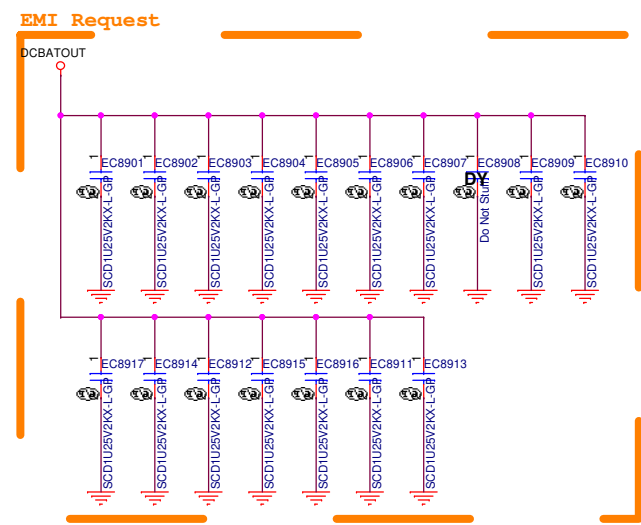
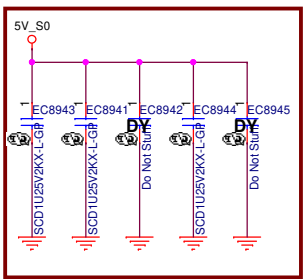
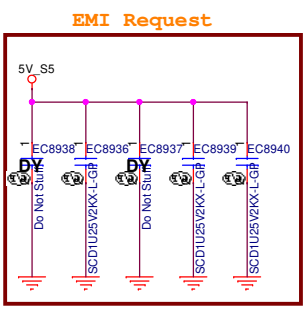
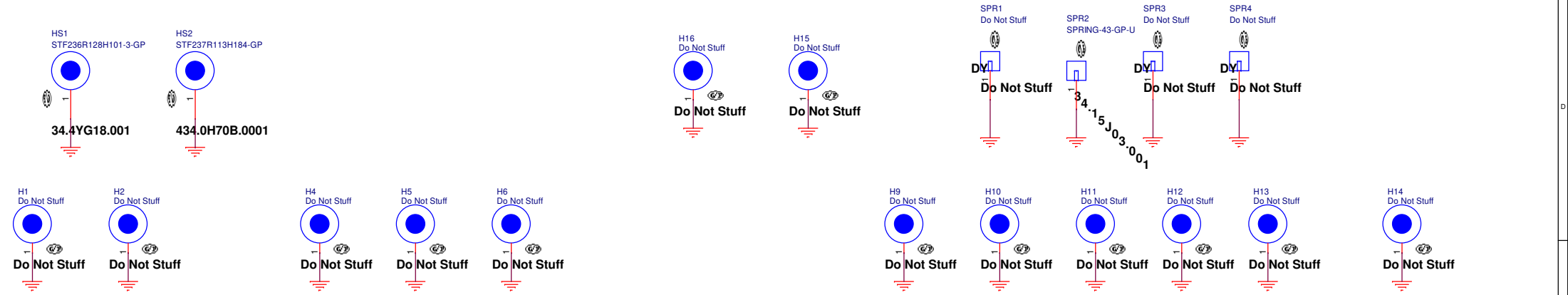
Item	Unit	Config
V _{min}	V	0.3
V _{max}	V	1.3
V _{boot}	V	0.8
Voltage Step Width	mV	6.25
Number of Voltage Levels N	level	160
PWM Frequency F _{PWM}	MHz	475
PWM Minimum Pulse Width T _{PWM}	ns	9.28
VID Transient Time T	us	1000
Component Value		
R1 (Ω)	Ω	6.19
R2 (Ω)	Ω	20.5
R3 (Ω)	Ω	4.32
R4 (Ω)	Ω	16.5
R5 (Ω)	Ω	8.0
C	μF	0.01

Item	Unit	Config
V _{min}	V	0.3
V _{max}	V	1.3
V _{boot}	V	0.8
Voltage Step Width	mV	6.25
Number of Voltage Levels N	level	160
PWM Frequency F _{PWM}	MHz	475
PWM Minimum Pulse Width T _{PWM}	ns	9.28
VID Transient Time T	us	1000
Component Value		
R1 (Ω)	Ω	6.19
R2 (Ω)	Ω	20.5
R3 (Ω)	Ω	4.32
R4 (Ω)	Ω	16.5
R5 (Ω)	Ω	8.0
C	μF	0.01

5	4	3	2	1
D				D
C				C
B				B
A				A


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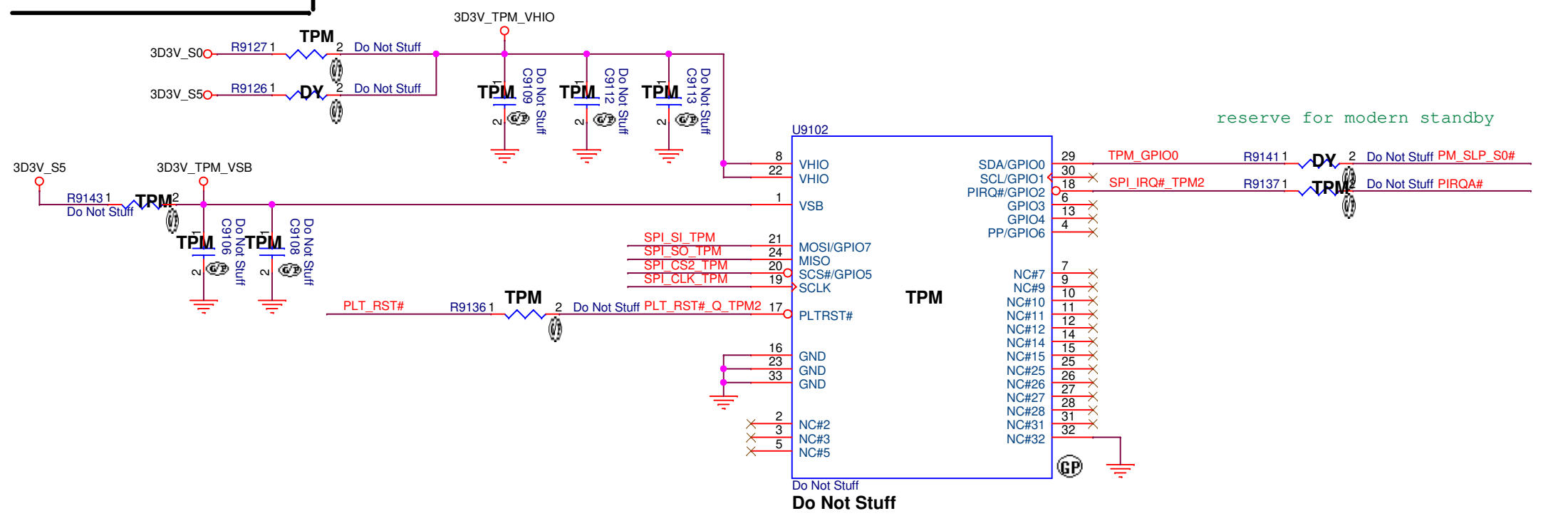
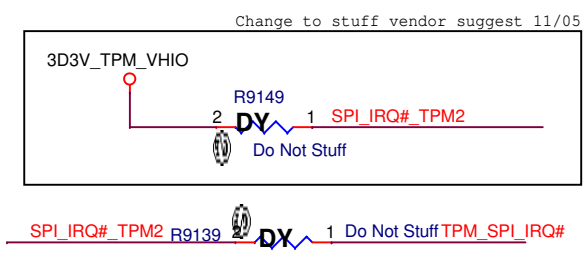
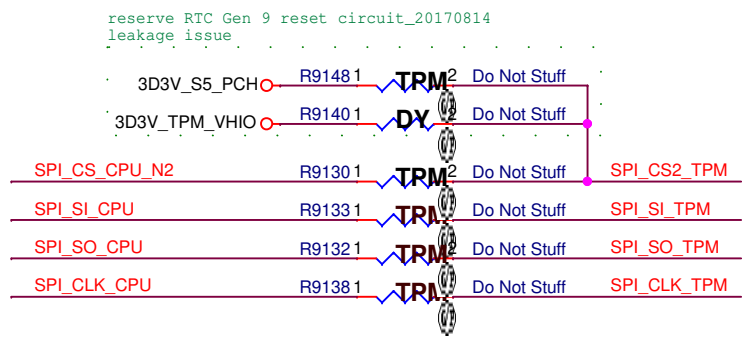
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C				C
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A				A
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SSID = TPM

19	PIRQA#	>>>	
15	TPM_SPI_IRQ#	>>>	
31,61,63,79	PLT_RST#	>>>	
15,40	PM_SLP_S0#	>>>	
15	SPI_CS_CPU_N2	>>>	
15,21,25	SPI_SO_CPU	<<<	
15,21,25	SPI_SI_CPU	>>>	
15,25	SPI_CLK_CPU	>>>	



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TPM2.0

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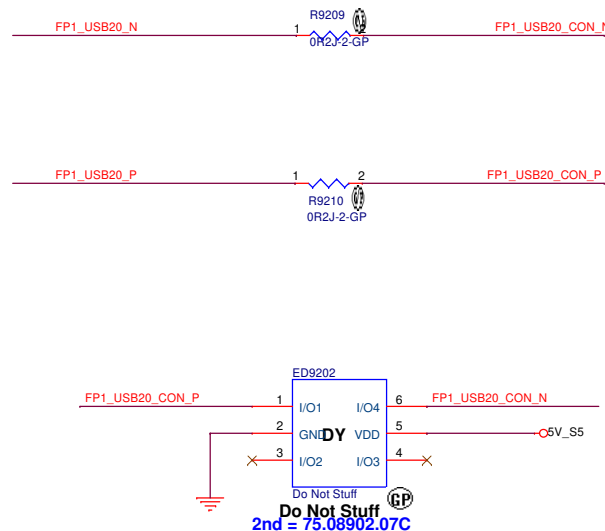
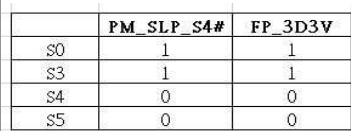
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24 FPR_SCAN# >>> _____
15,40,44,51 PM_SLP_S4# >>> _____

24,64 KBC_PWRBTN# <<< _____
24,66 LID_CL_SIO# >>> _____

18 FP1_USB20_N <<< _____
18 FP1_USB20_P <<< _____



PWFPR_SSO: GOODIX module
PWFPR_NON_SSO: ELAN module(R9211 R9214 R9217)

Pin Definition

CN PIN MAP	
PIN NO.	INFO
1	VCC-3.3V
2	Power button
3	USB_N
4	USB_P
5	GND
6	LID closed
7	GPIO key shielding
8	GND(ID pin)

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Document Number

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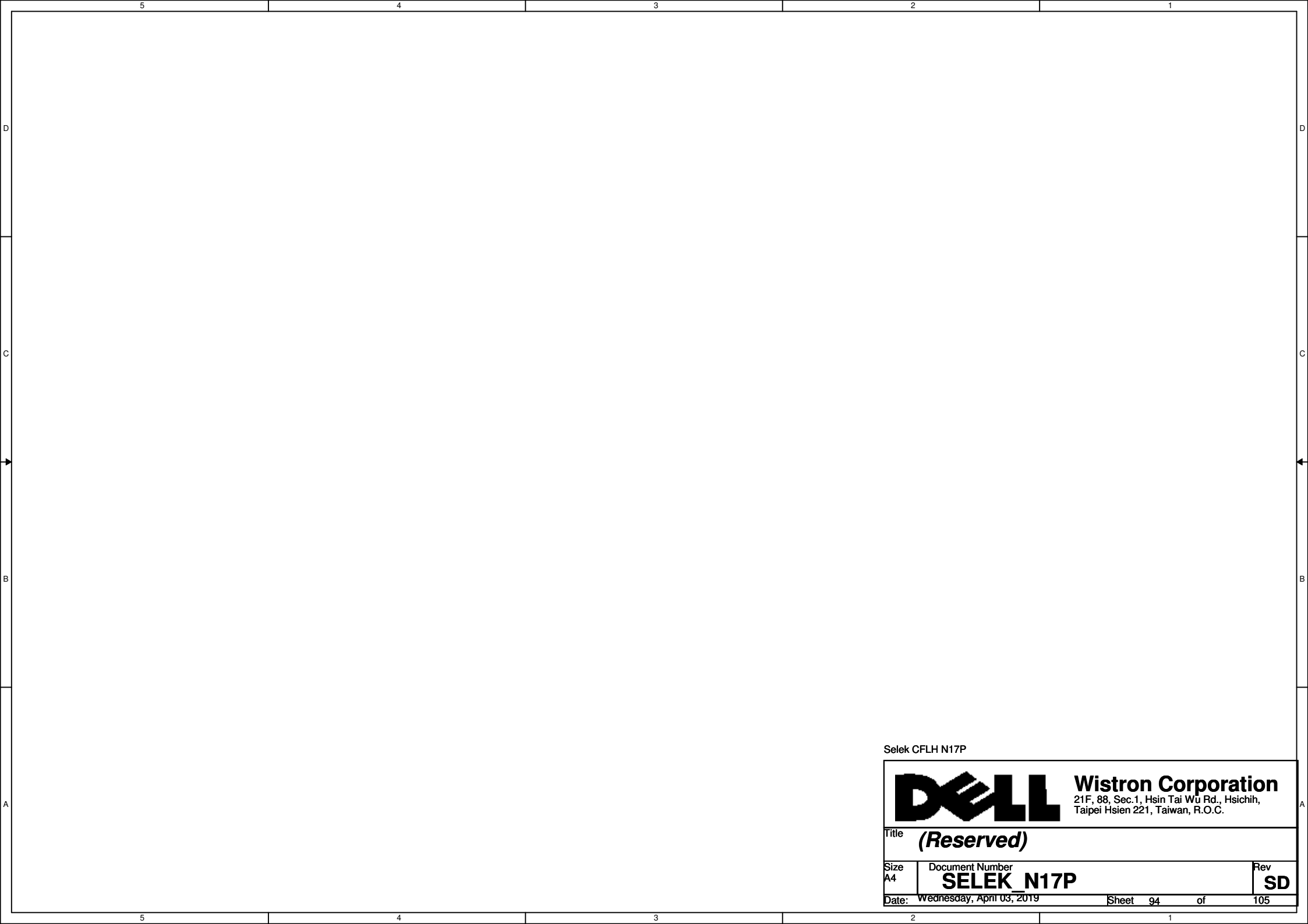
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C				C
B				B
A				A
5	4	3	2	1

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C				C
B				B
A				A
5	4	3	2	1

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D				D
C				C
B				B
A				A
5	4	3	2	1

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Title (Reserved)			
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D				D
C				C
B				B
A				A
5	4	3	2	1

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D

C |

B

A

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Size

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Main Func = XDP

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Title CPU_XDP;PCH_XDP		
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D				D
C				C
B				B
A				A

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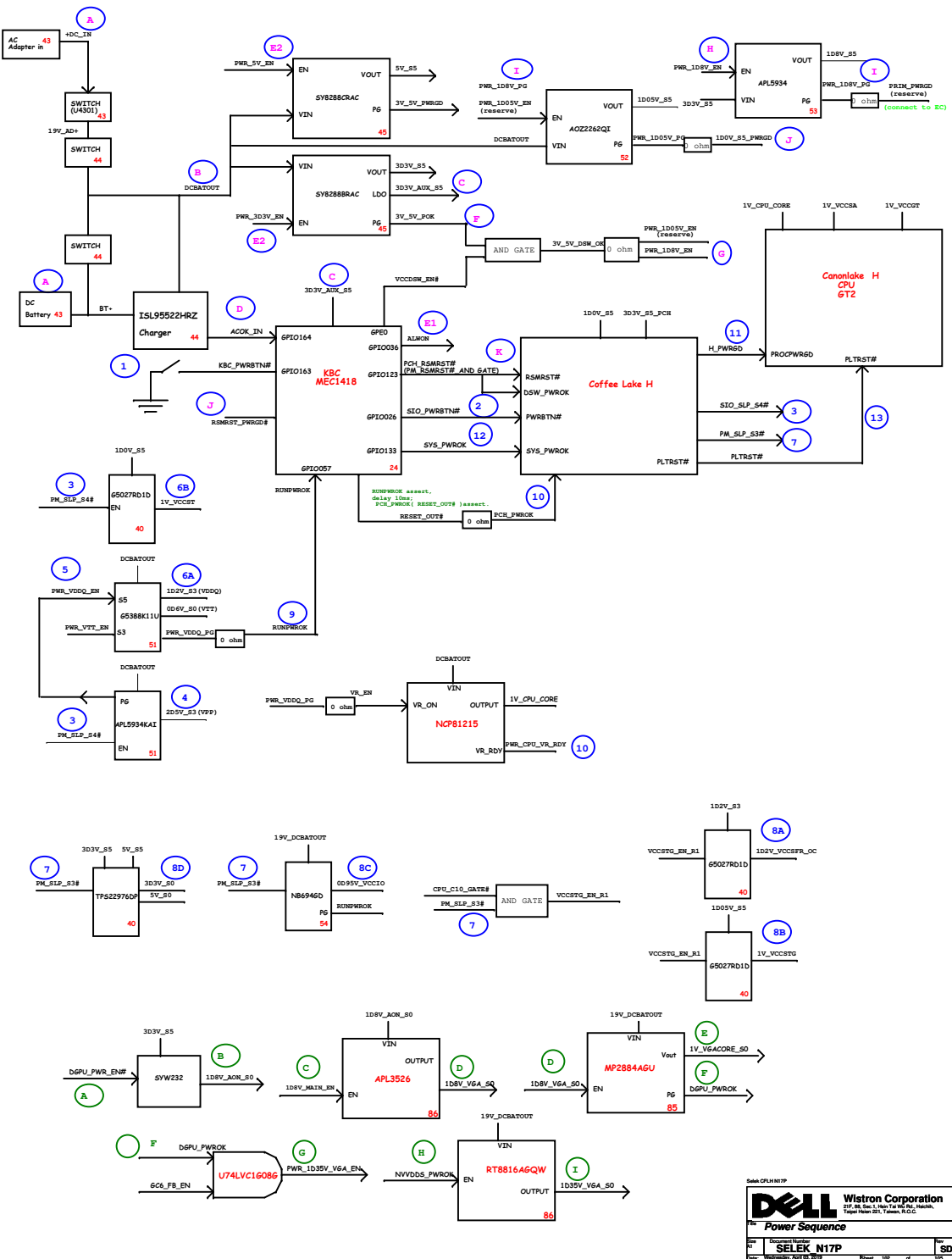
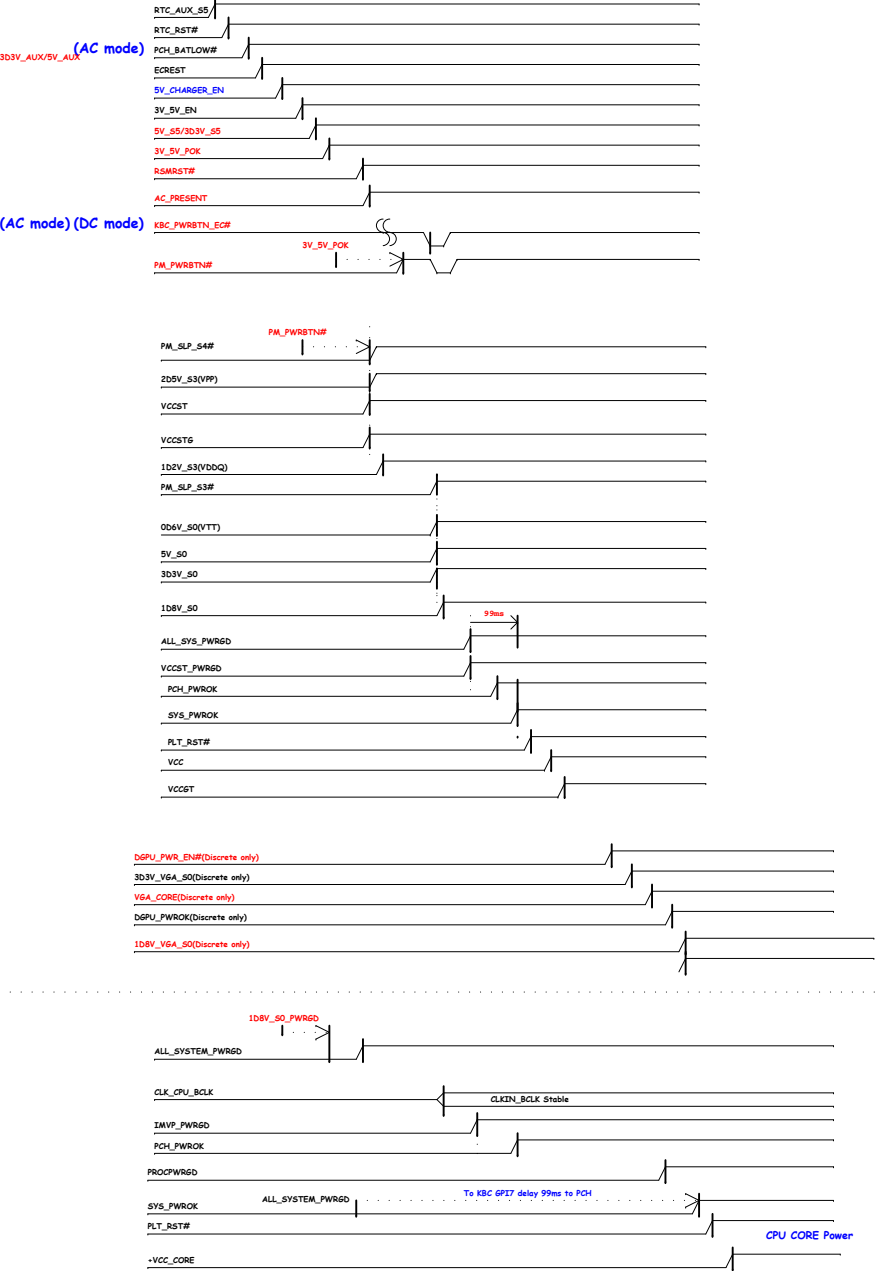
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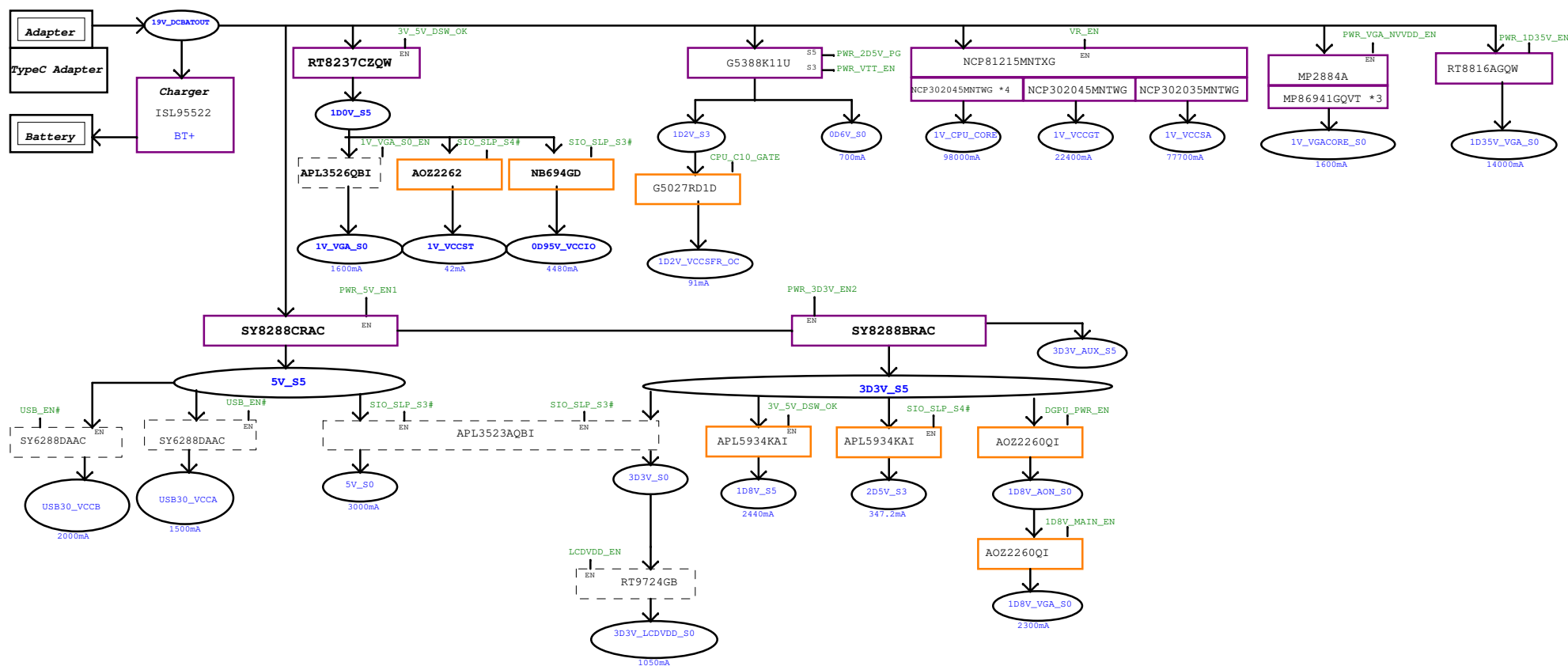
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B						B
A						A
	5	4	3	2	1	

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Title <i>Change History</i>			
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Intel-Power Up Sequence



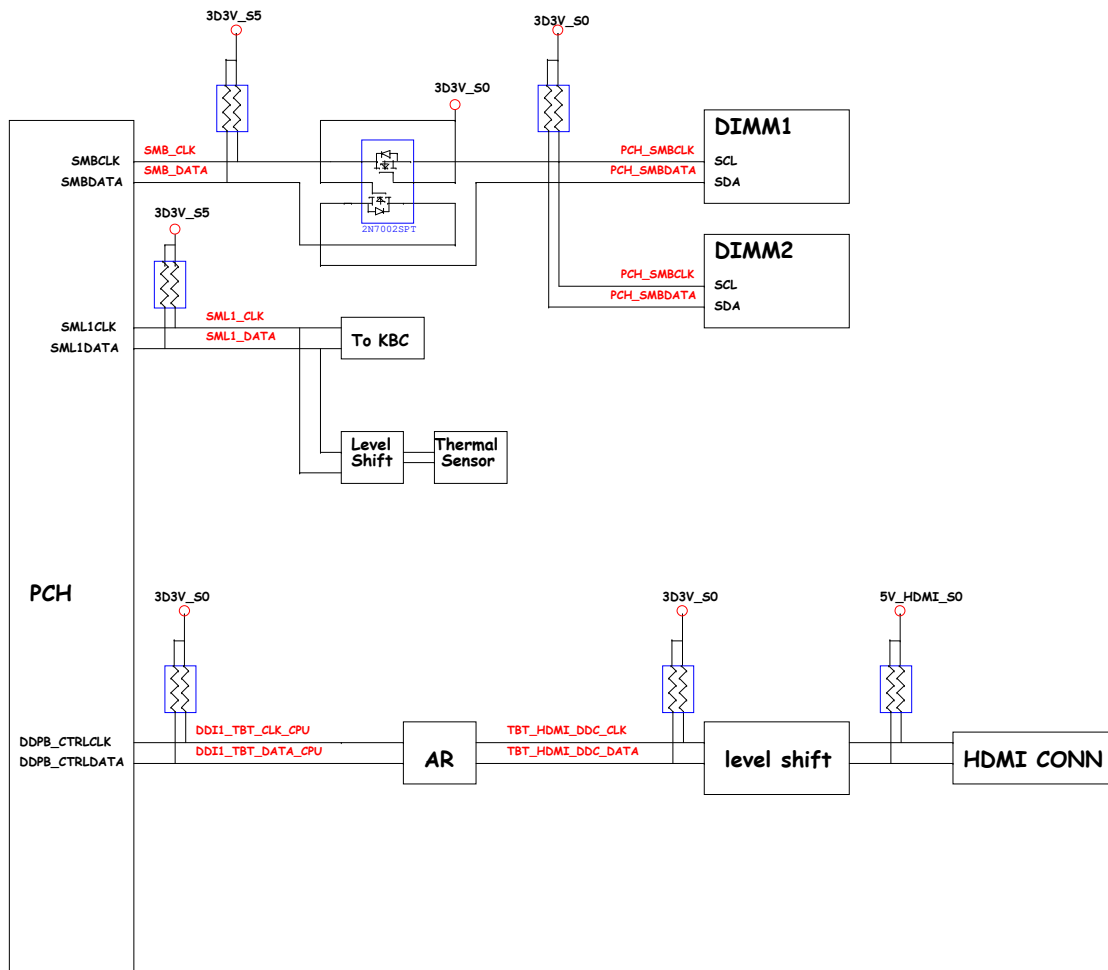


Power Shape

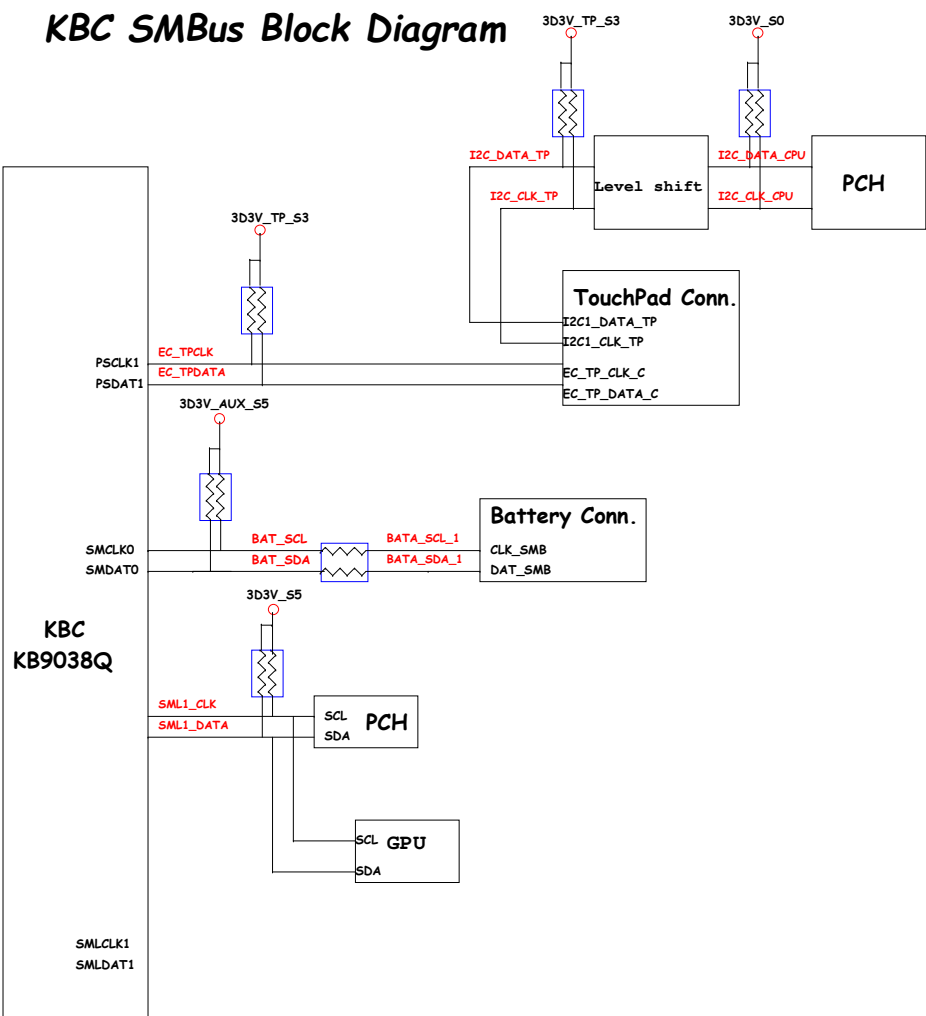
Regulator LDO Switch

Selek CFLM N17P

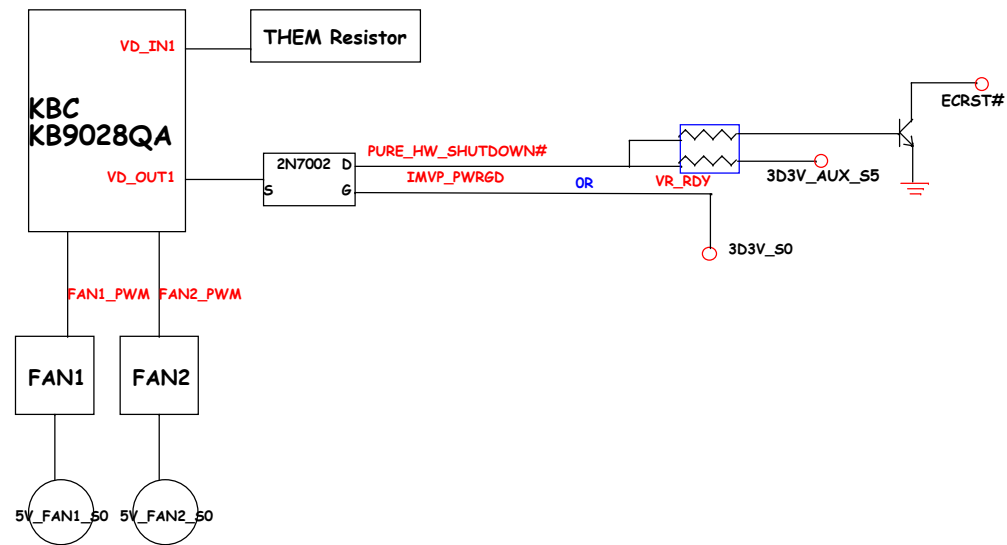
PCH SMBus Block Diagram



KBC SMBus Block Diagram



Thermal Block Diagram



Audio Block Diagram

